

# COMPAL CONFIDENTIAL

MODEL NAME : *BDW00*

COMPAL P/N : *DA8DW00L100*

PCB NO : *LA-1452*

Revision : *1.0*

DATE :

## Abacus/TangII Schematics Document

### uFCBGA/uFCPGA Northwood

2002-11-26

REV: 1.0

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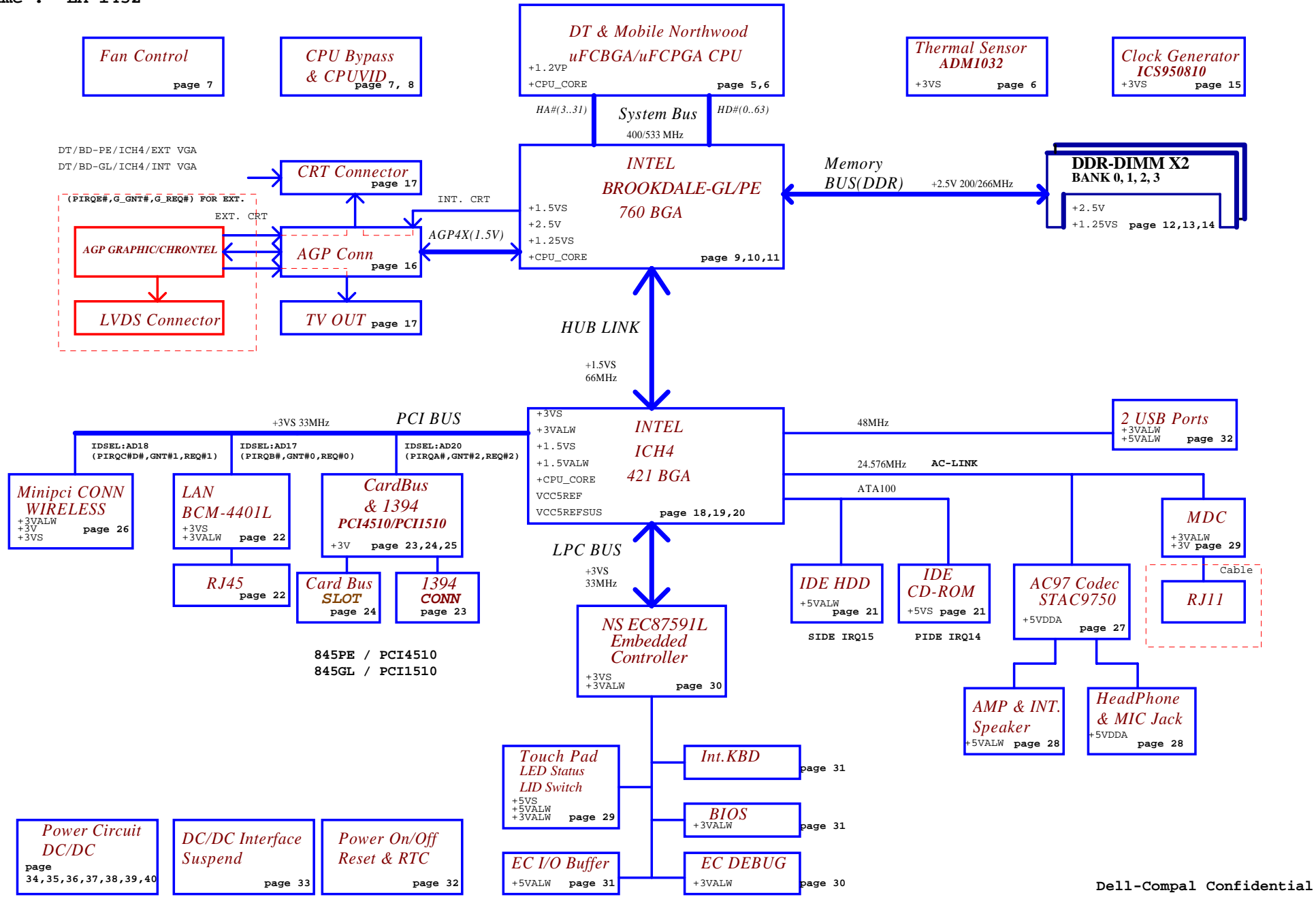
Compal Electronics, Inc.

Title		
Cover Sheet		
Size	Document Number	Rev
	Abacus/TangII LA-1452	1.0
Date:	Tuesday, November 26, 2002	Sheet 1 of 46

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Model Name : ABACUS/TangII

File Name : LA-1452



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Block Diagram		
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Revision List

	Schematics Rev	PCB Rev	CHIPS Rev
SST-Build	0.1	0.1	
PT-Build	0.2	0.2	845PE Rev B0 845GL Rev B1 ICH4 Rev B0
ST-Build			
QT-Build			

Power Management table

Signal / State	+3VALW +5VALW +12VALW	+3V +5V +2.5V	+3VS +5VS +1.5VS +1.2VP +CPU_CORE +1.25VS
S0	ON	ON	ON
S1	ON	ON	ON
S3	ON	ON	OFF
S5 S4/AC	ON	OFF	OFF
S5 S4/AC don't exist	OFF	OFF	OFF

Ceramic Capacitor Spec Guide:

Temperature Characteristics:

Symbol	0	1	2	3	4	5	6	7
CODE	Z5U	Z5V	Z5P	Y5U	Y5V	Y5P	X5R	X7R

8	9	A	B	C	D	E	F	G
NP0	COG		BJ	CH	CJ	CK	SH	SJ

H	I	J	
UJ	UK	SL	

Tolerance:

Symbol	A	B	C	D	F	G	H	J
CODE	+/-0.05PF	+/-0.1PF	+/-0.25PF	+/-0.5PF	+/-1PF	+/-2%	+/-3%	+/-5%

K	M	N	P	Q	v	X	Z	
+/-10%	+/-20%	+/-30%	+100,-0%	+30,-10%	+20,-10%	+40,-20%	+80,-20%	

SMBUS Control Table

	SOURCE	INVERTER	BATT	SERIAL EPROM	THERMAL SENSOR (CPU) (U57)	THERMAL SENSOR (U25/U23)	SODIMM	CLK CHIP	MINI PCI
SMB_EC_CK1 SMB_EC_DA1	NS 87591	✓	✓	✓ (1010)	✗	✗	✗	✗	✗
SMB_EC_CK2 SMB_EC_DA2	NS 87591	✗	✗	✗	✓	✓	✗	✗	✗
SMB_CLK SMB_DATA	ICH4	✗	✗	✗	✗	✗	✓	✓	✓

NOTE1:

@XX : Depop component

1@XX : Pop for INT, Depop for EXT

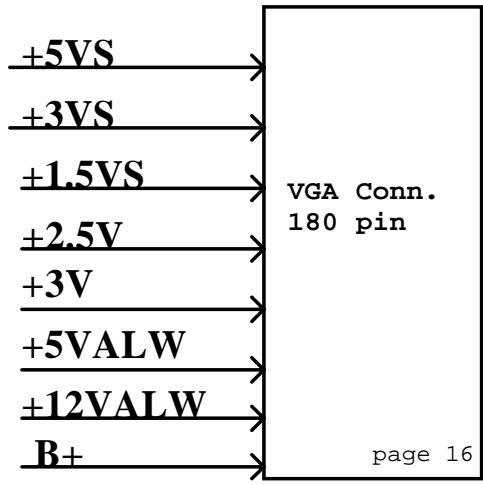
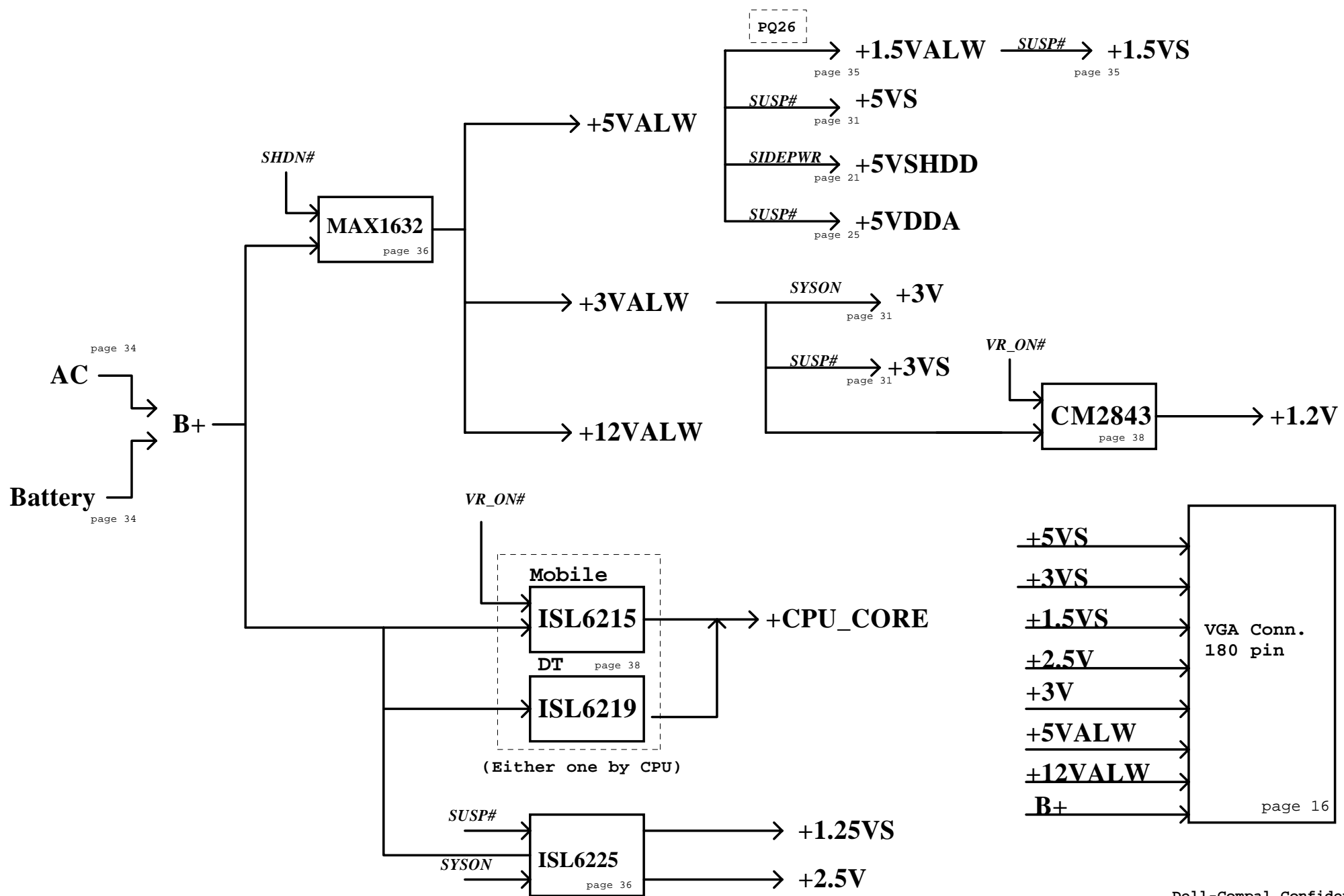
2@XX : Pop for EXT, Depop for INT

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Title		Note & Revision	
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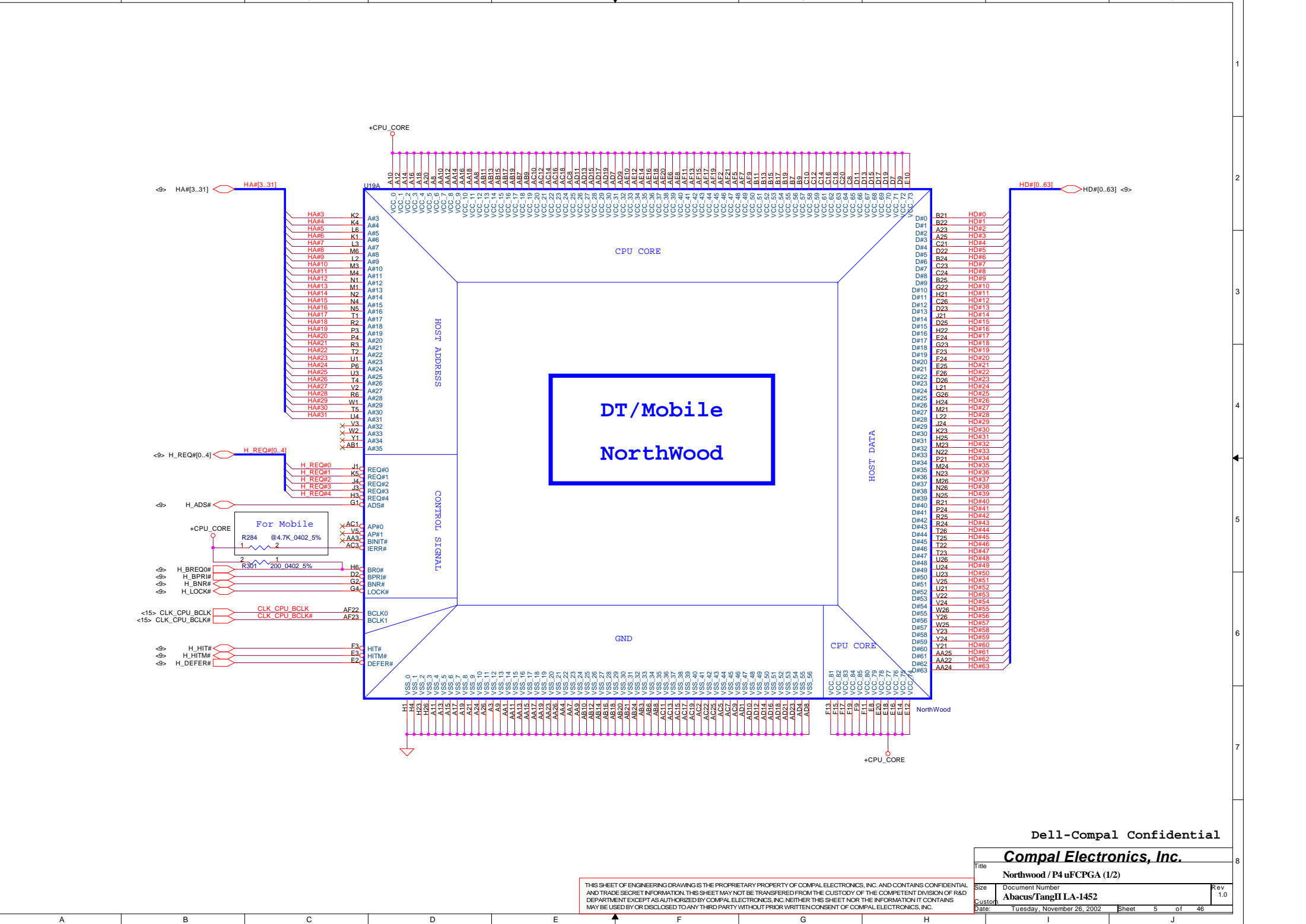


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Title <b>POWER DIAGRAM</b>		
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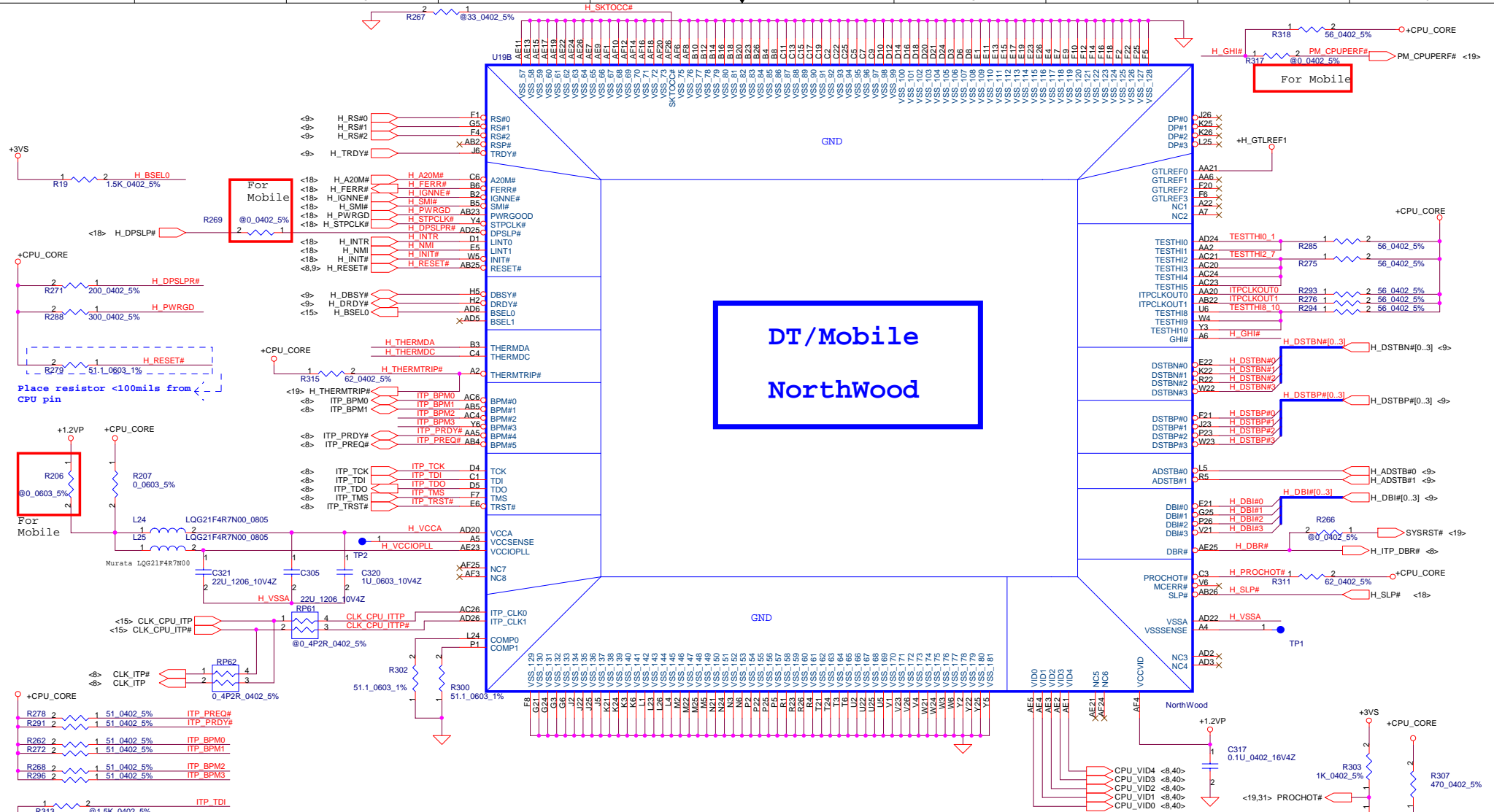
**DT/Mobile  
NorthWood**

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Title		Northwood / P4 uFCPGA (1/2)	
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DT/Mobile  
NorthWood

**For Mobile**  
@0.0402\_5%

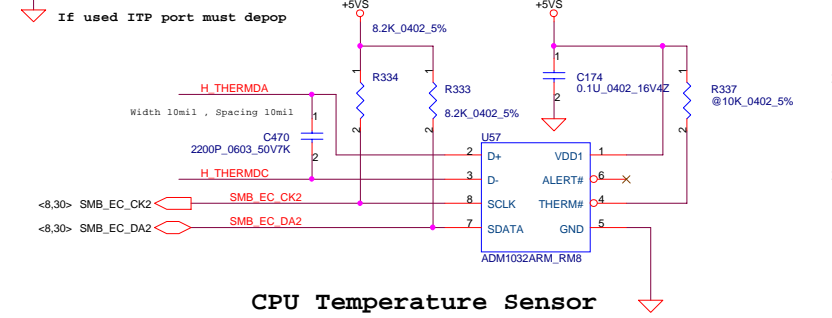
Place resistor <100mils from CPU pin

**For Mobile**  
@0.0603\_5%

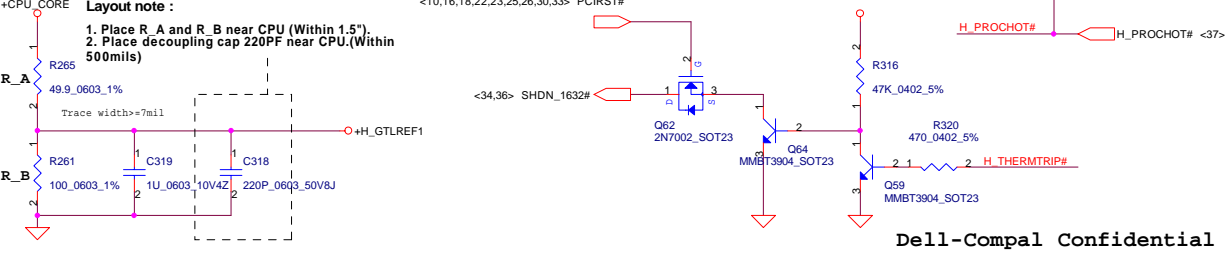
For Mobile

If used ITP port must depop

**GTL Reference Voltage**  
Layout note :  
1. Place R\_A and R\_B near CPU (Within 1.5")  
2. Place decoupling cap 220PF near CPU.(Within 500mils)



**CPU Temperature Sensor**



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**Compal Electronics, Inc.**  
Title: Mobile NorthWood / P4 uFCPGA & Thermal sensor (2/2)

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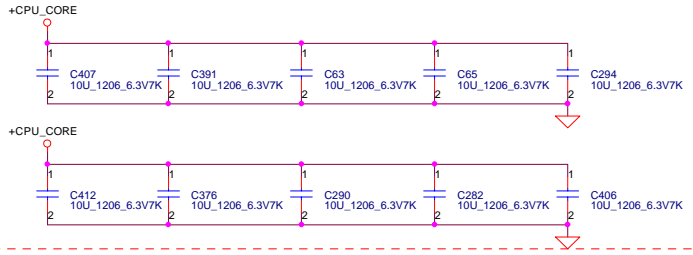
**Layout note :**  
 Place close to CPU, Use 2-3 vias per PAD.  
 Place .22uF caps underneath balls on solder side.  
 Place 10uF caps on the peripheral near balls.  
 Use 2-3 vias per PAD.

**Layout note :**  
 Place close to CPU power and ground pin as possible (<1inch)

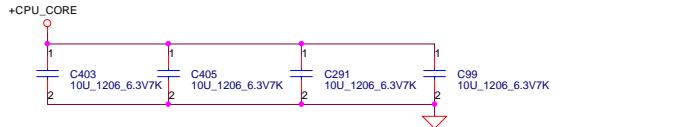
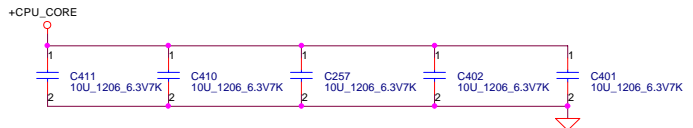
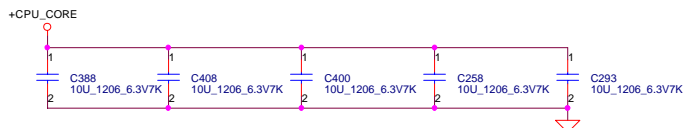
**For Desktop's CPU:**  
 ESR total=0.75m ohm  
 C total=6350uF

**For Mobile's CPU:**  
 ESR total=1.875m ohm  
 C total=2590uF

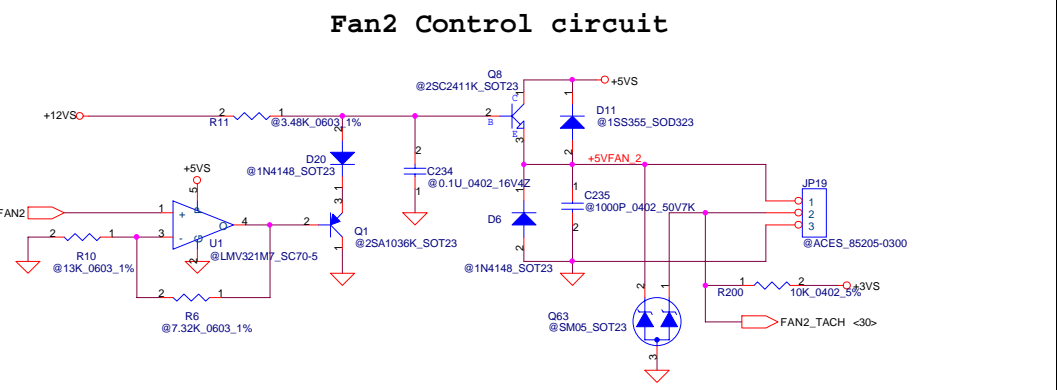
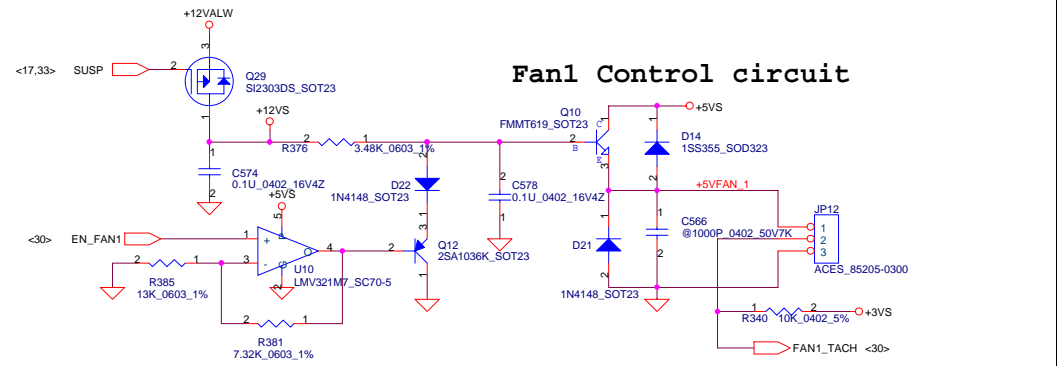
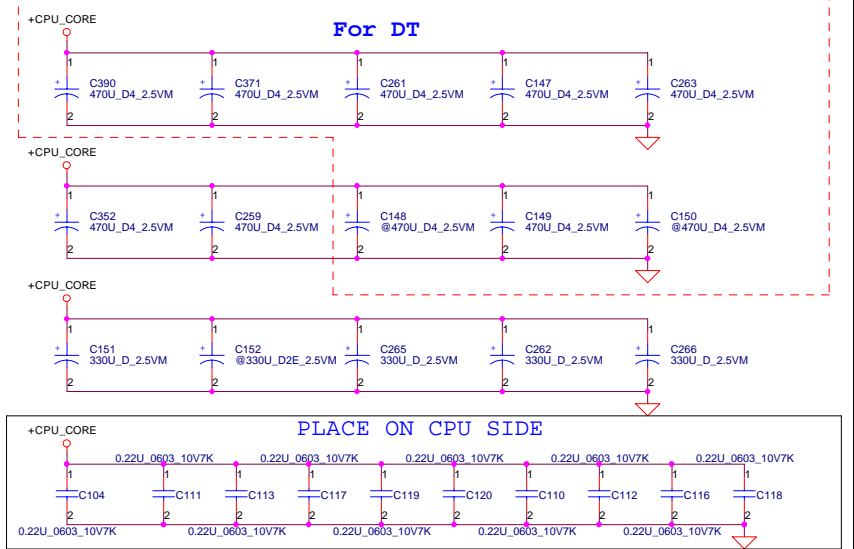
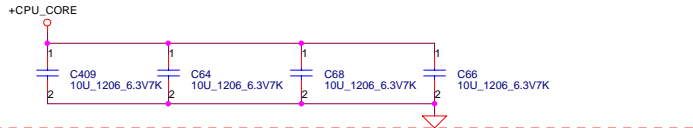
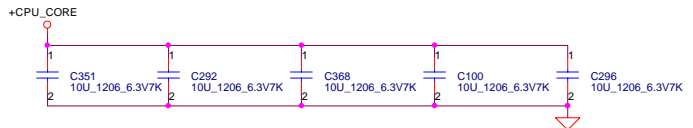
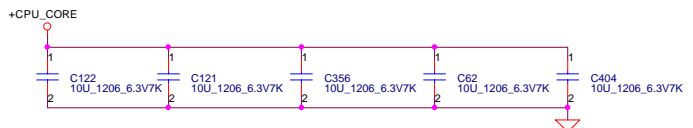
Please place these cap in the socket cavity area



Please place these cap on the socket north side



Please place these cap on the socket south side

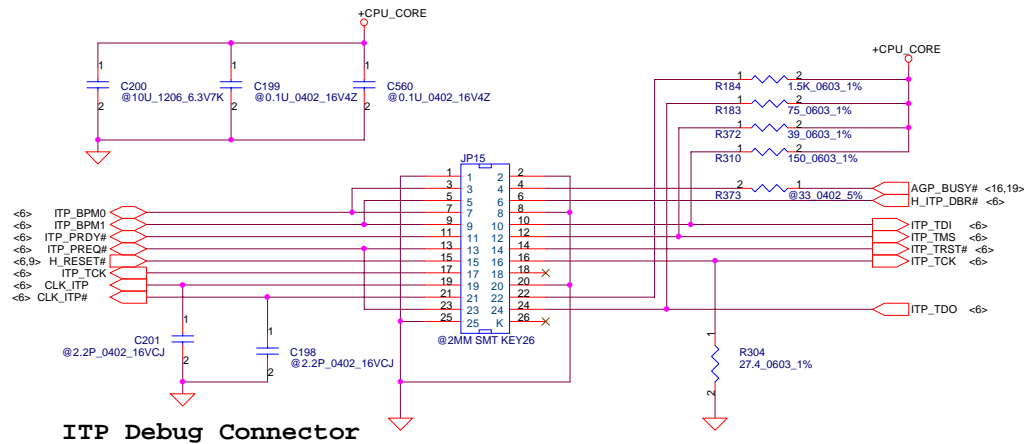
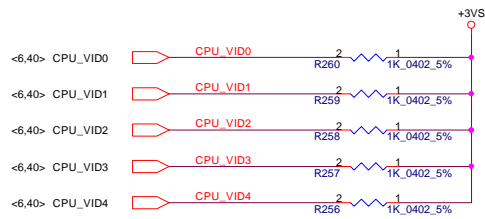


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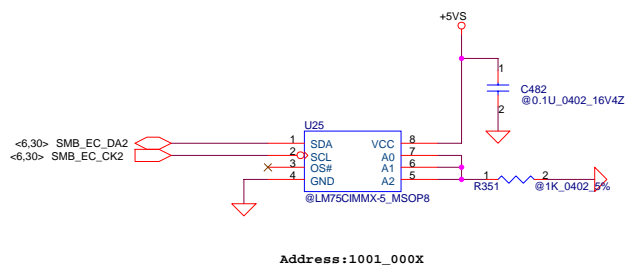
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Title		CPU Decoupling CAP. & Fan control	
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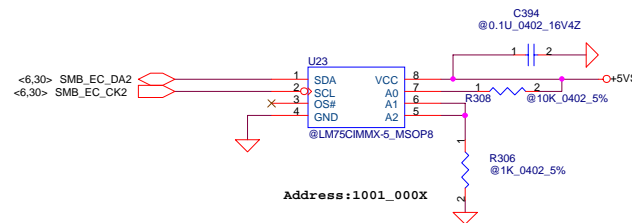
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**ITP Debug Connector**



Address:1001\_000X



Address:1001\_000X

MO/DT_CPU	Mobile CPU					Desktop CPU				
	1					0				
VID	4	3	2	1	0	4	3	2	1	0
VCC										
1.750V	0	0	0	0	0	0	0	1	0	0
1.700V	0	0	0	0	1	0	0	1	1	0
1.650V	0	0	0	1	0	0	1	0	0	0
1.600V	0	0	0	1	1	0	1	0	1	0
1.550V	0	0	1	0	0	0	1	1	1	0
1.500V	0	0	1	0	1	0	1	1	1	0
1.450V	0	0	1	1	0	1	0	0	0	0
1.400V	0	0	1	1	1	1	0	0	1	0
1.350V	0	1	0	0	0	1	0	1	0	0
1.300V	0	1	0	0	1	1	0	1	1	0
1.250V	0	1	0	1	0	1	1	0	0	0
1.200V	0	1	0	1	1	1	1	0	1	0
1.150V	0	1	1	0	0	1	1	1	0	0
1.100V	0	1	1	0	1	1	1	1	1	0
1.050V	0	1	1	1	0	X	X	X	X	X
1.000V	0	1	1	1	1	X	X	X	X	X
0.975V	1	0	0	0	0	X	X	X	X	X
0.950V	1	0	0	0	1	X	X	X	X	X
0.925V	1	0	0	1	0	X	X	X	X	X
0.900V	1	0	0	1	1	X	X	X	X	X
0.875V	1	0	1	0	0	X	X	X	X	X
0.850V	1	0	1	0	1	X	X	X	X	X
0.825V	1	0	1	1	0	X	X	X	X	X
0.800V	1	0	1	1	1	X	X	X	X	X
0.775V	1	1	0	0	0	X	X	X	X	X
0.750V	1	1	0	0	1	X	X	X	X	X
0.725V	1	1	0	1	0	X	X	X	X	X
0.700V	1	1	0	1	1	X	X	X	X	X
0.675V	1	1	1	0	0	X	X	X	X	X
0.650V	1	1	1	0	1	X	X	X	X	X
0.625V	1	1	1	1	0	X	X	X	X	X
0.600V	1	1	1	1	1	X	X	X	X	X
VRM output off						1	1	1	1	1

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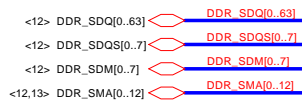
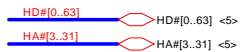
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Title CPU VID & ITP PORT

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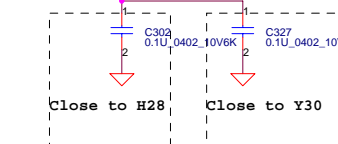
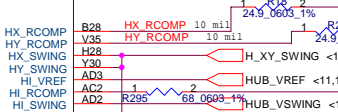
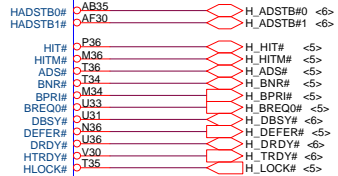
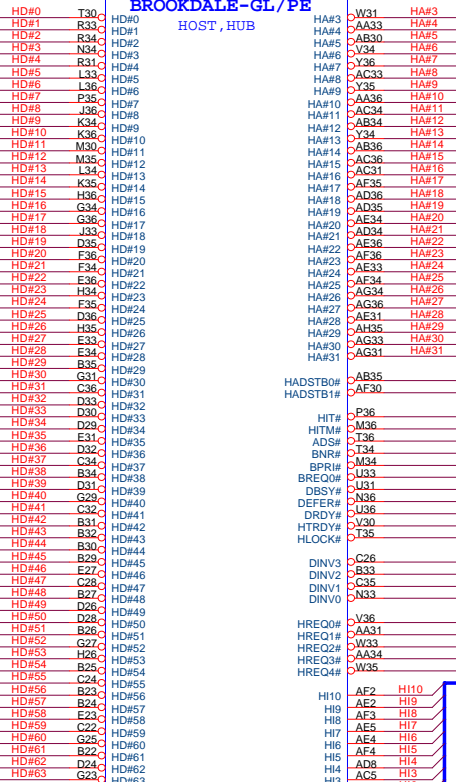
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U12A

**BROOKDALE-GL/PE**  
HOST\_HUB

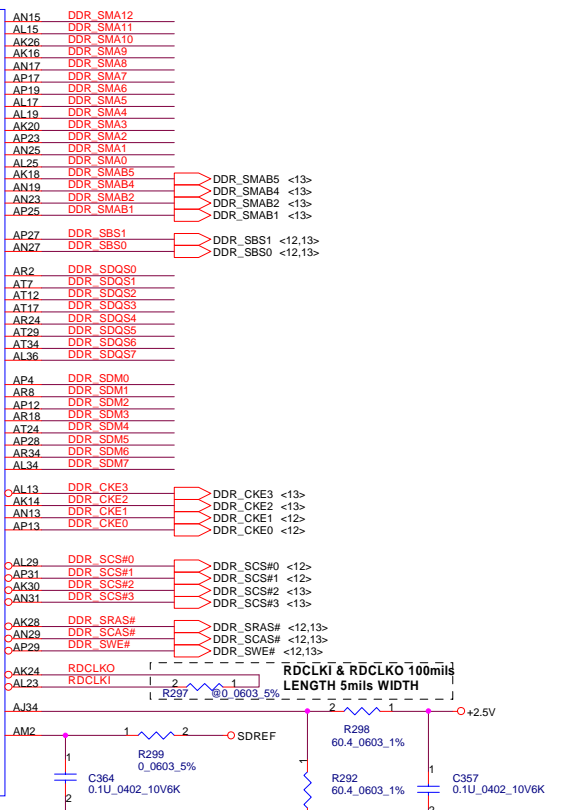
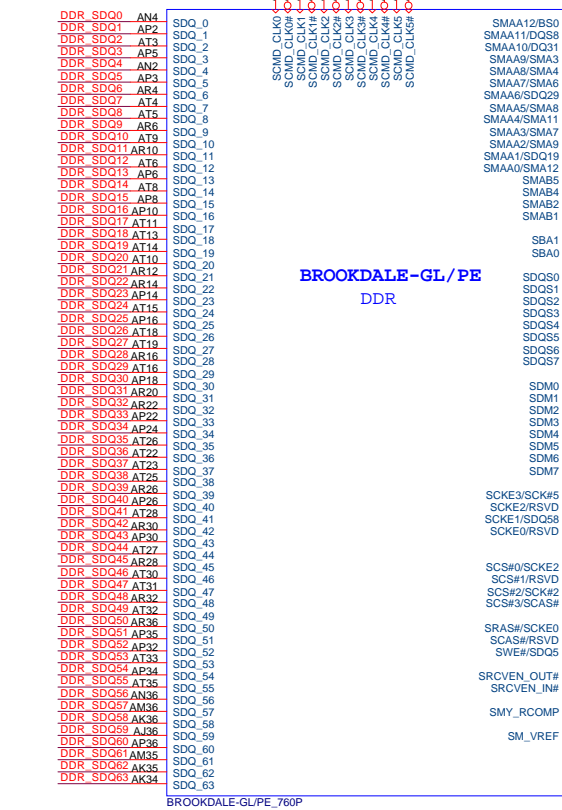


Layout note:  
1. HX\_RCOMP, HY\_RCOMP Trace width 10 mil.  
2. Terminator Max 500 mil.



U12B

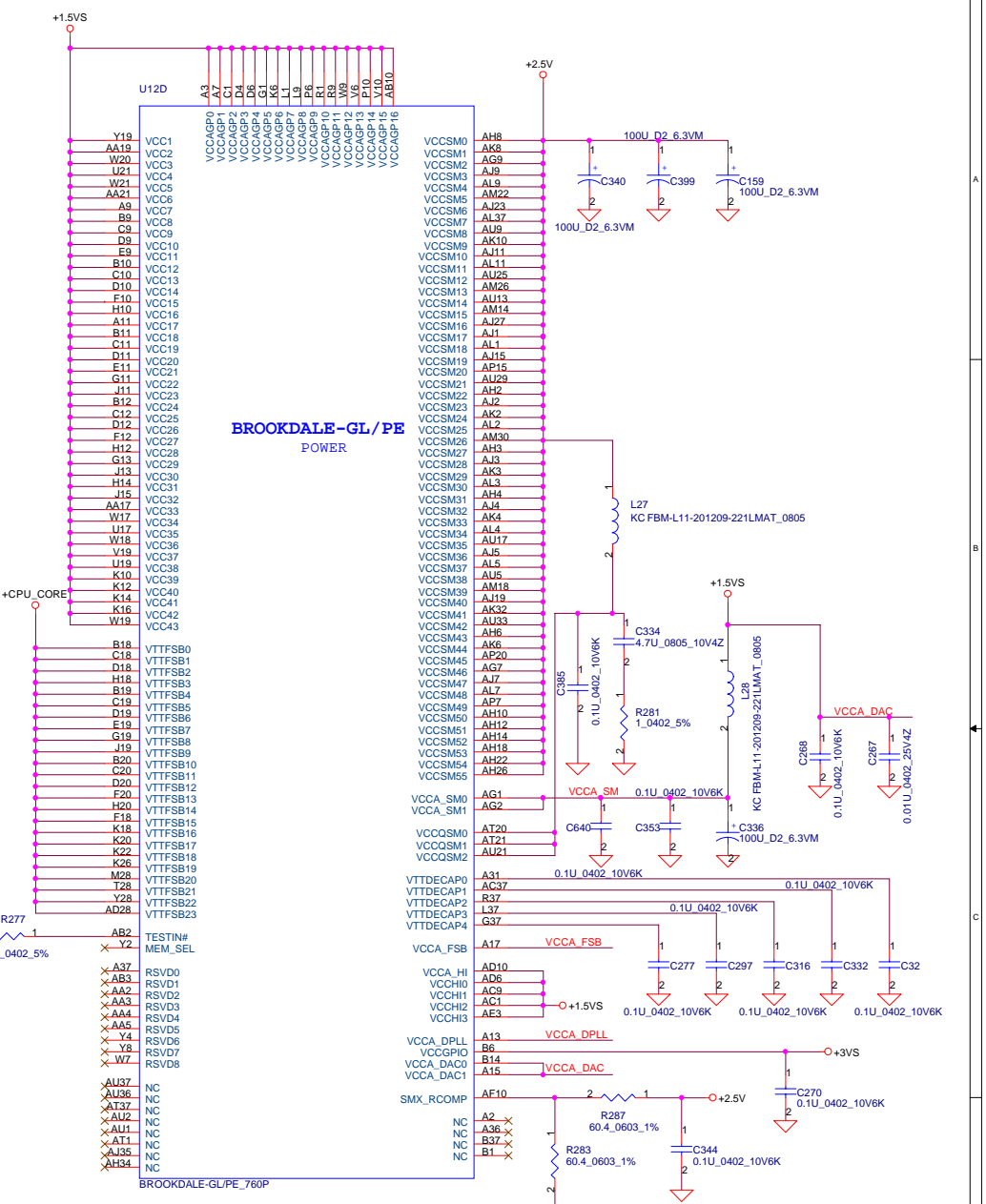
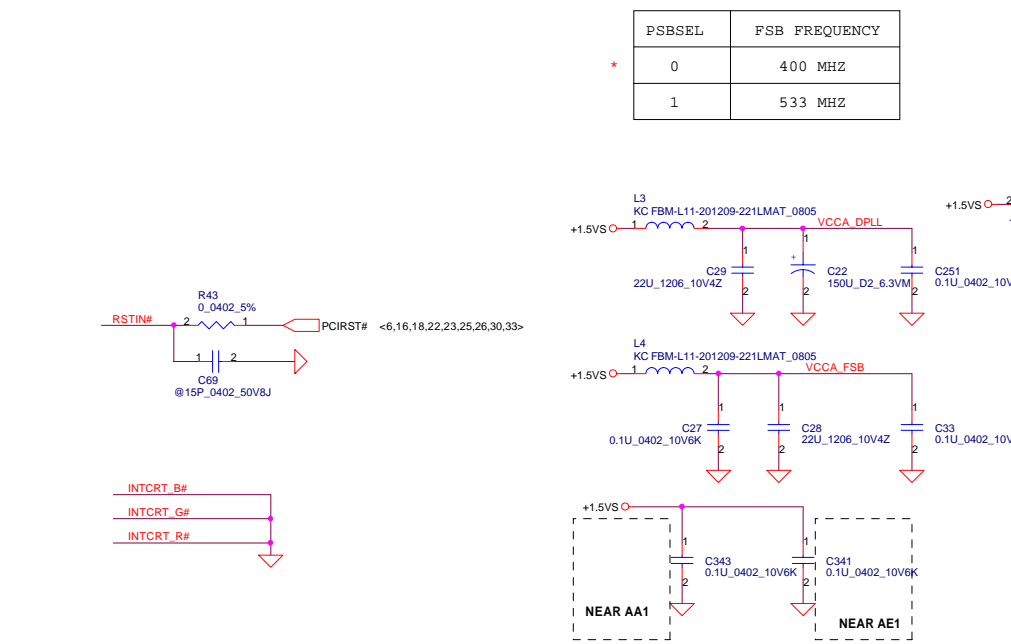
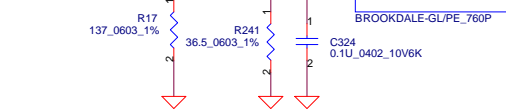
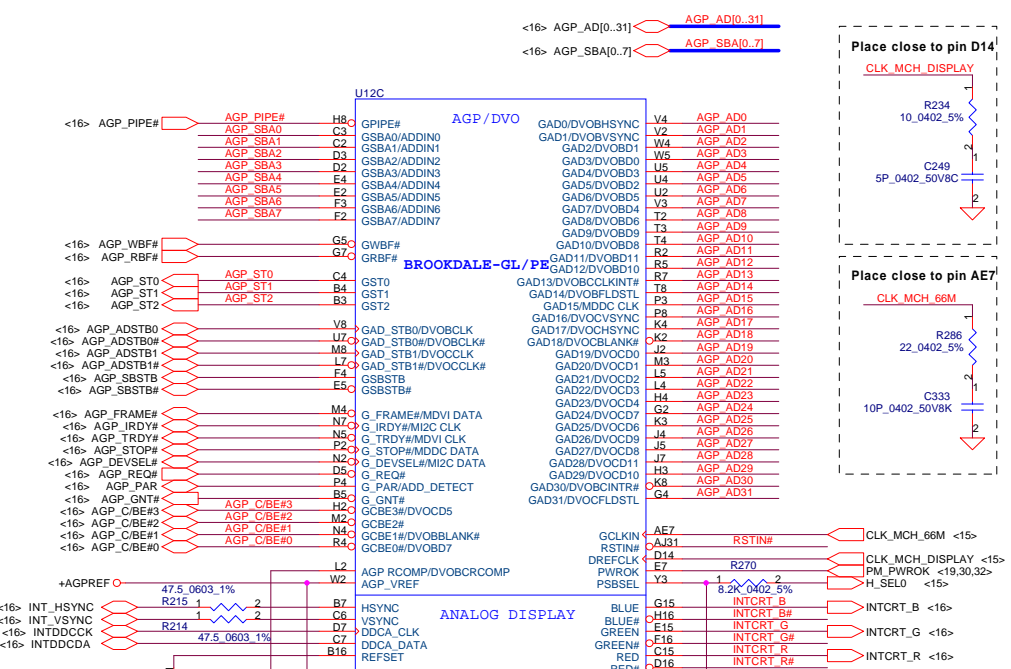
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DDR



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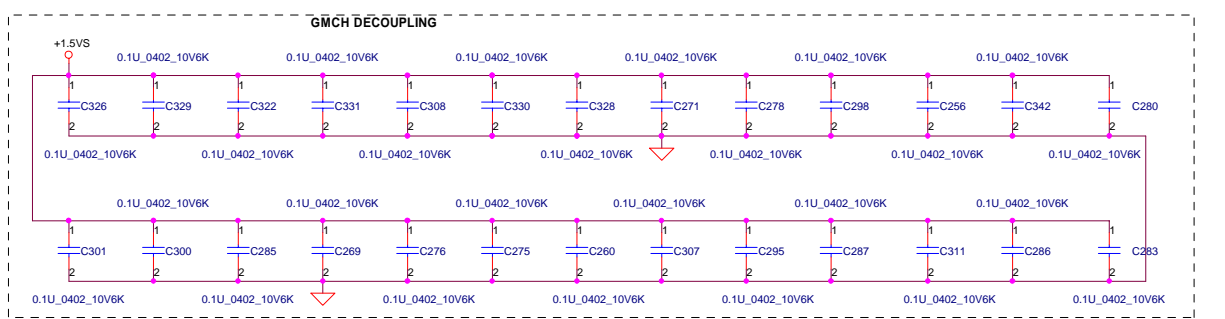
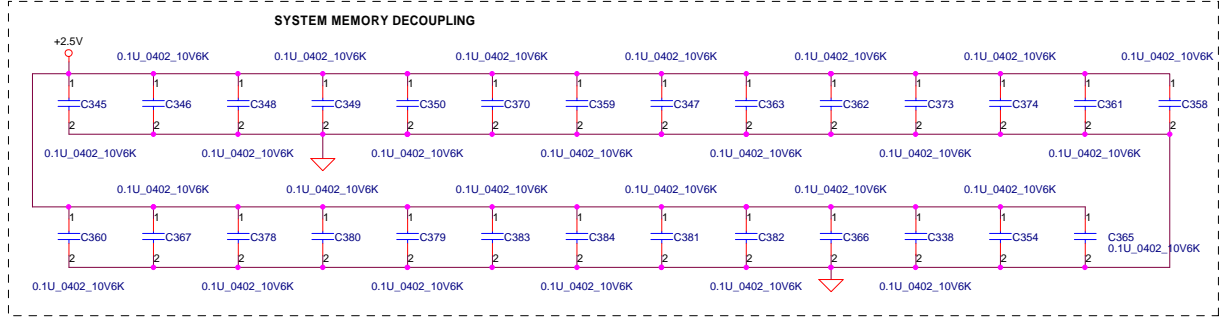
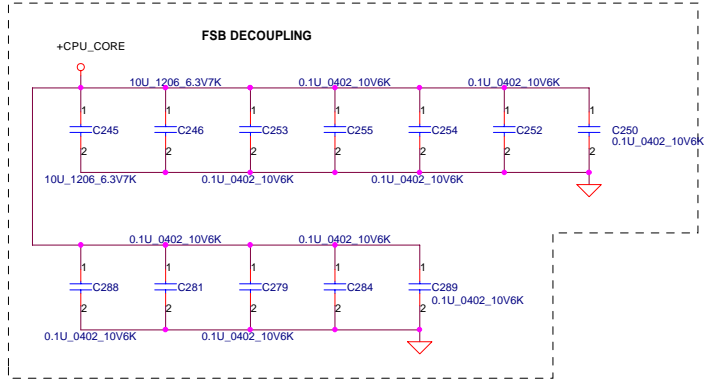
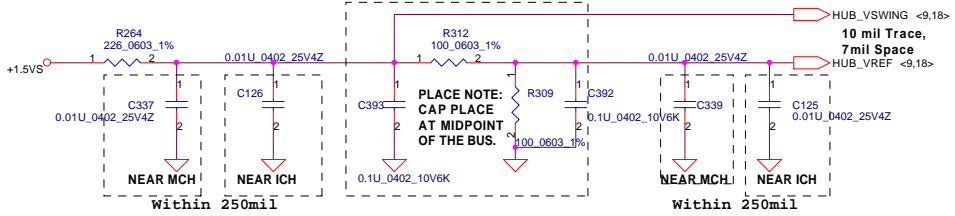
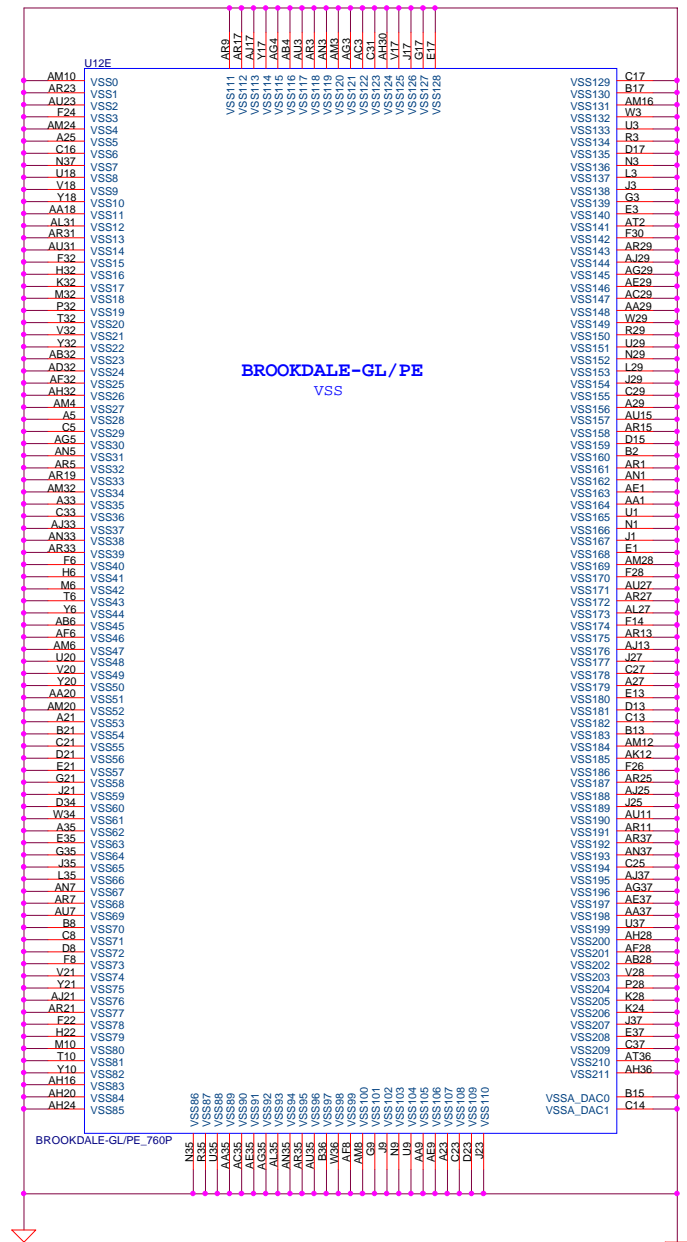
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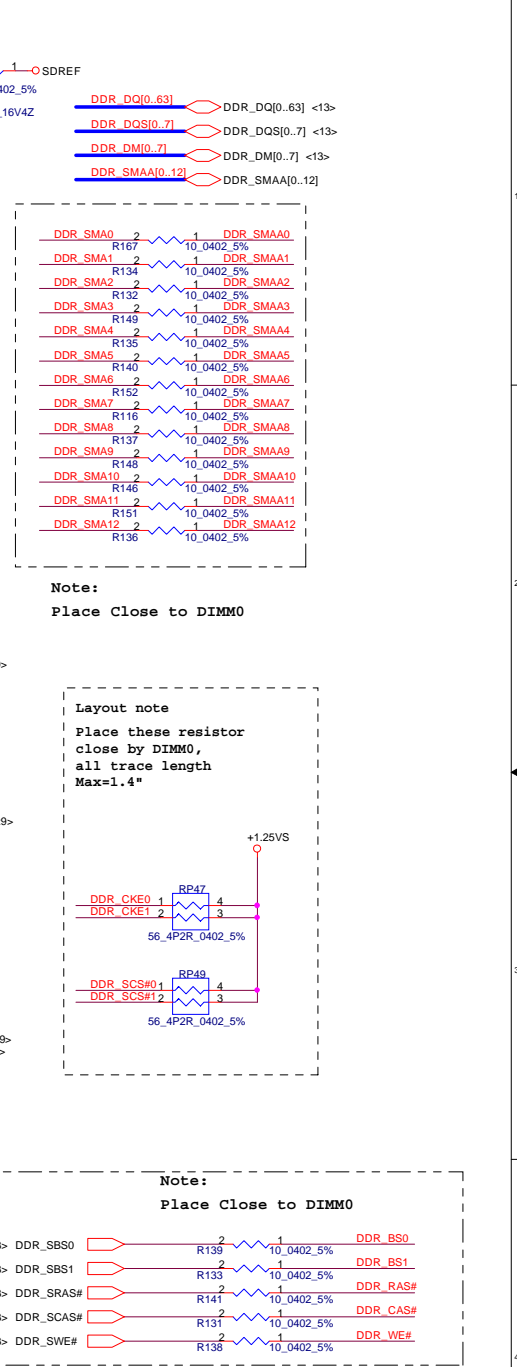
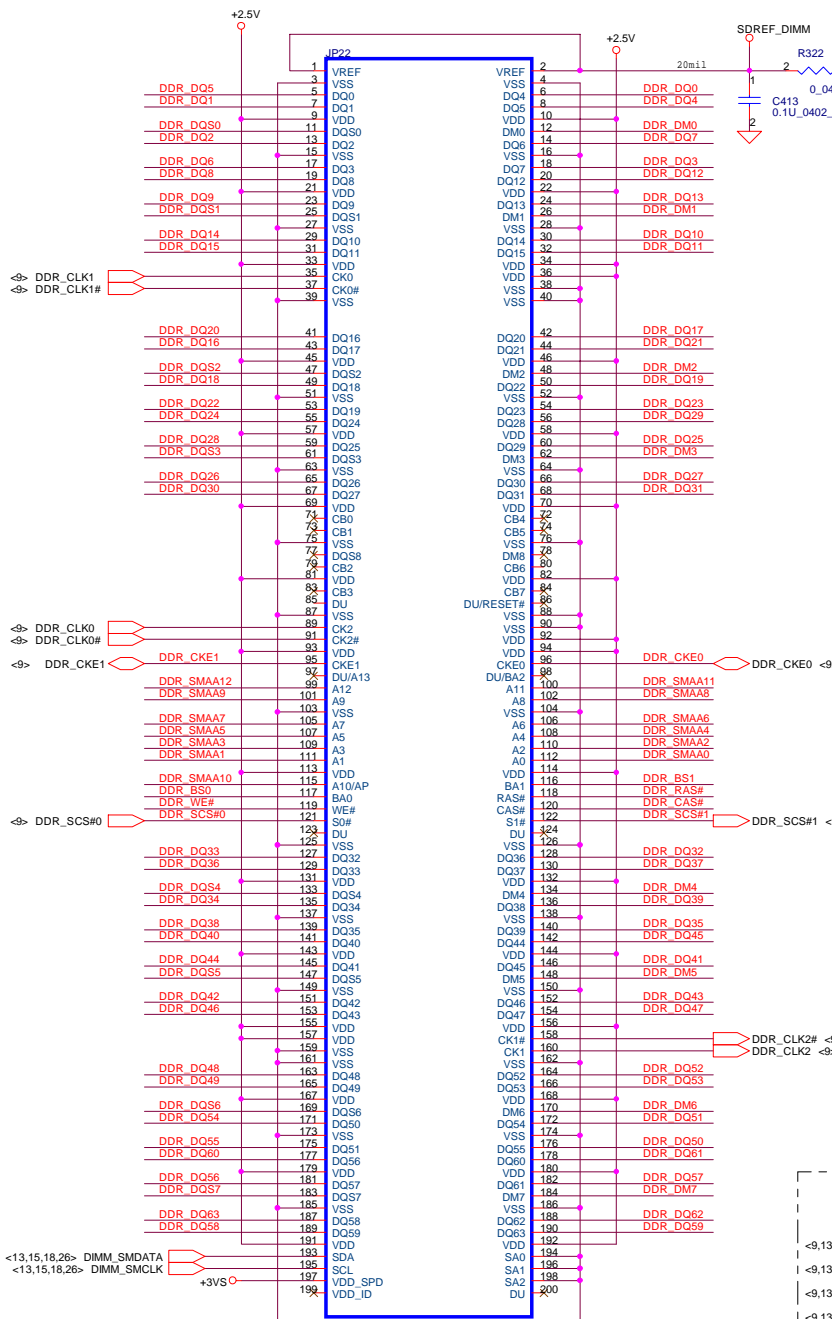
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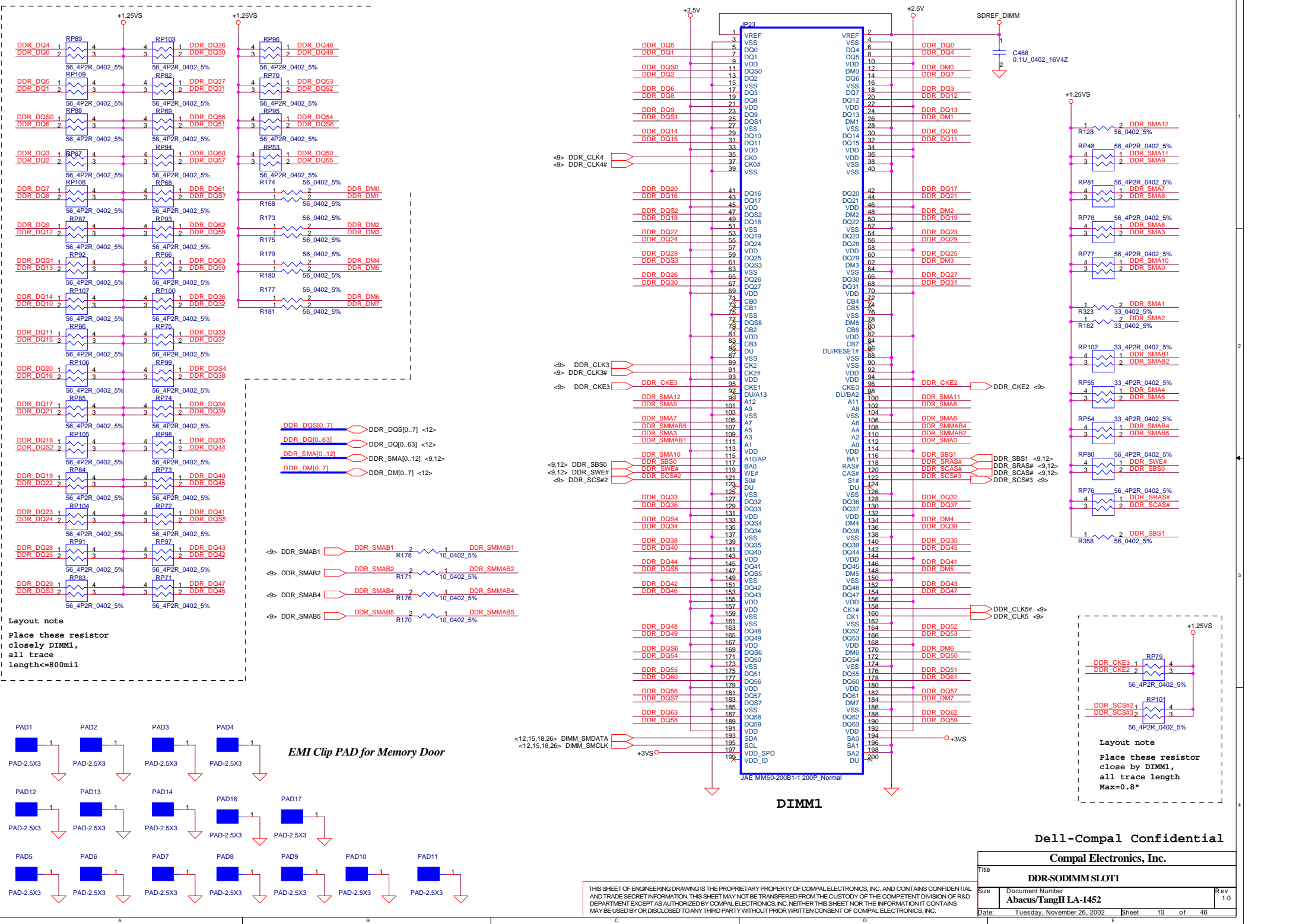


**Layout note**  
Place these resistors close to DIMM0, all trace length<500 mil

**Note:**  
Place Close to DIMM0

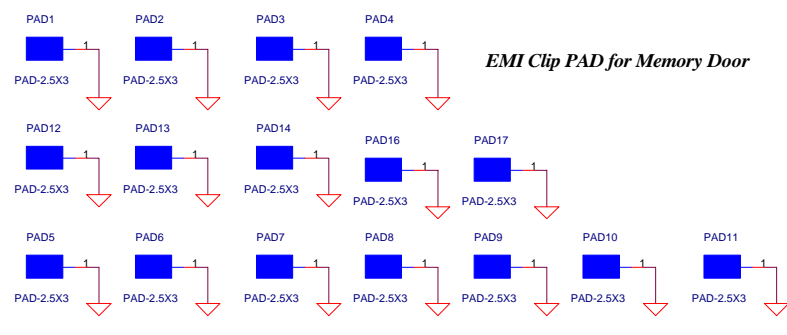
**Layout note**  
Place these resistor close by DIMM0, all trace length Max=1.4"

**Note:**  
Place Close to DIMM0



**Layout note**  
Place these resistor closely DIMM1, all trace length<=800mil

**Layout note**  
Place these resistor close by DIMM1, all trace length Max=0.8"



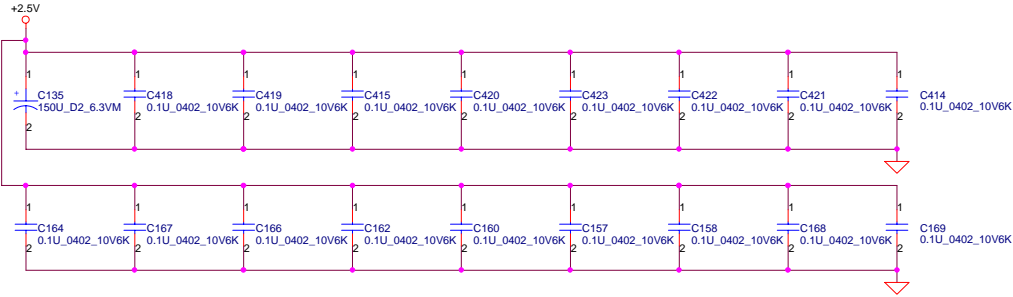
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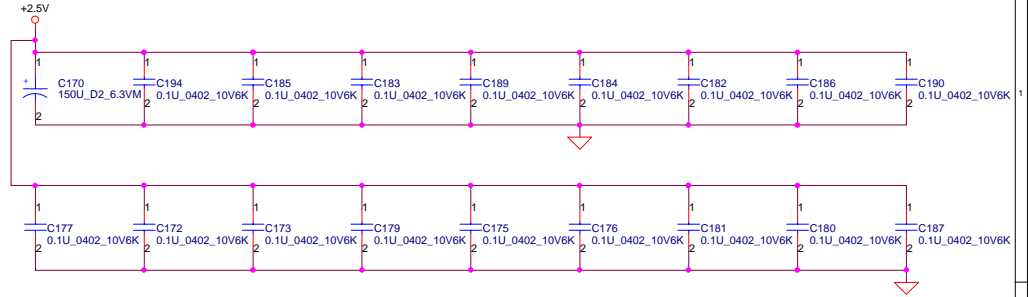
**Compal Electronics, Inc.**

Title <b>DDR-SODIMM SLOT1</b>		
Size	Document Number <b>Abacus/TangII LA-1452</b>	Rev 1.0
Date	Tuesday, November 26, 2002	Sheet 13 of 46

**Layout note :**  
Distribute as close as possible to DDR-SODIMM0.



**Layout note :**  
Distribute as close as possible to DDR-SODIMM1.



**Layout note :**  
Place one cap close to every 2 pull up resistors termination to +1.25VS

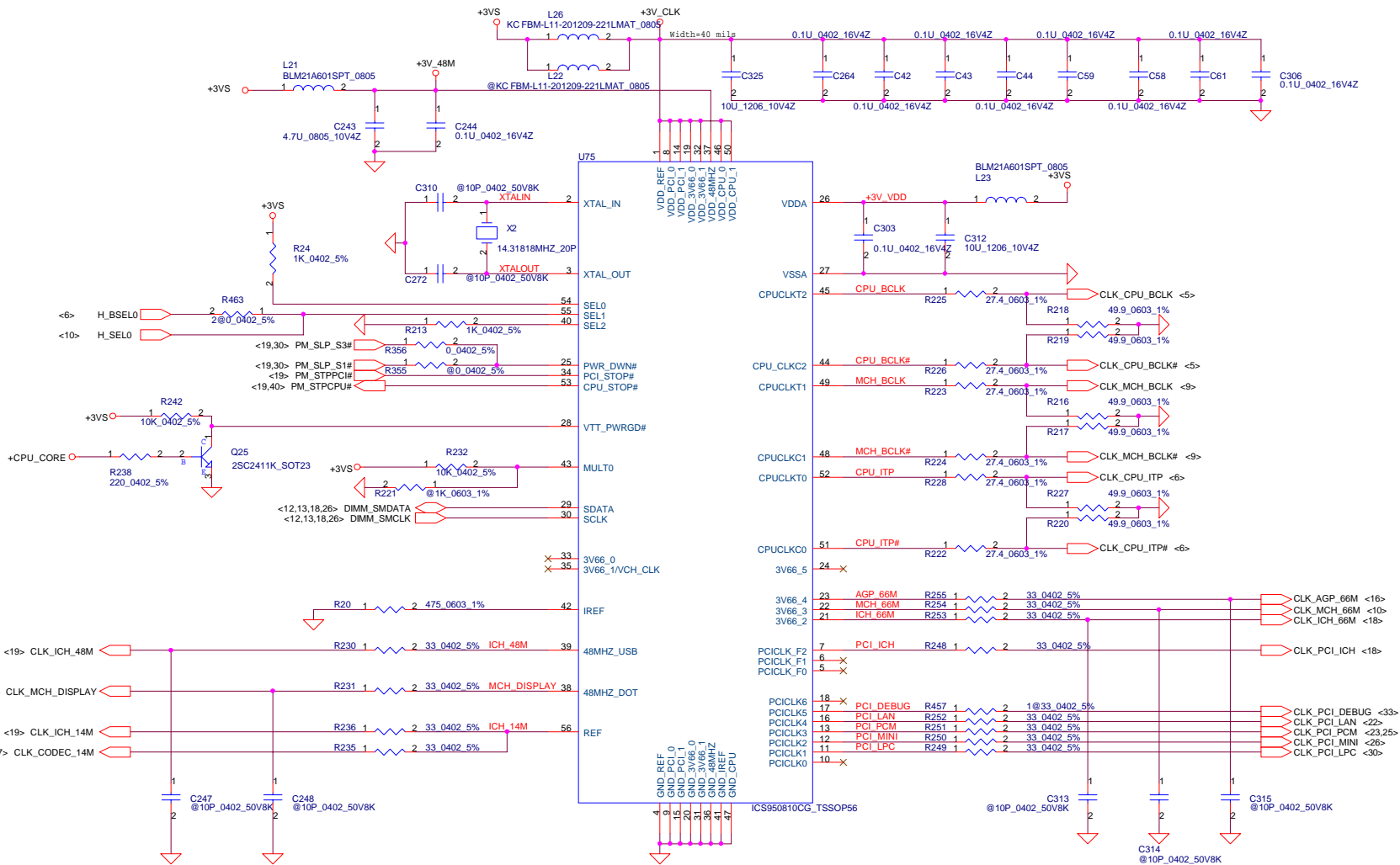


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**Compal Electronics, Inc.**

Title <b>DDR SODIMM Decoupling</b>		
Size	Document Number <b>Abacus/TangH LA-1452</b>	Rev 1.0
Date:	Tuesday, November 26, 2002	Sheet 14 of 46

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CPU Frequency Select Table

SEL[2:0]	CK-408 Speed
001	100 MHZ
011	133 MHZ

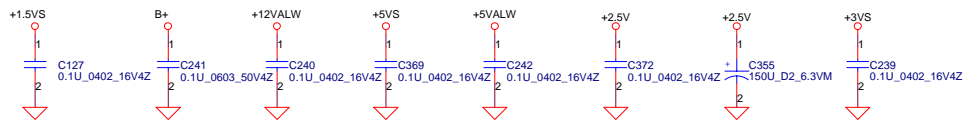
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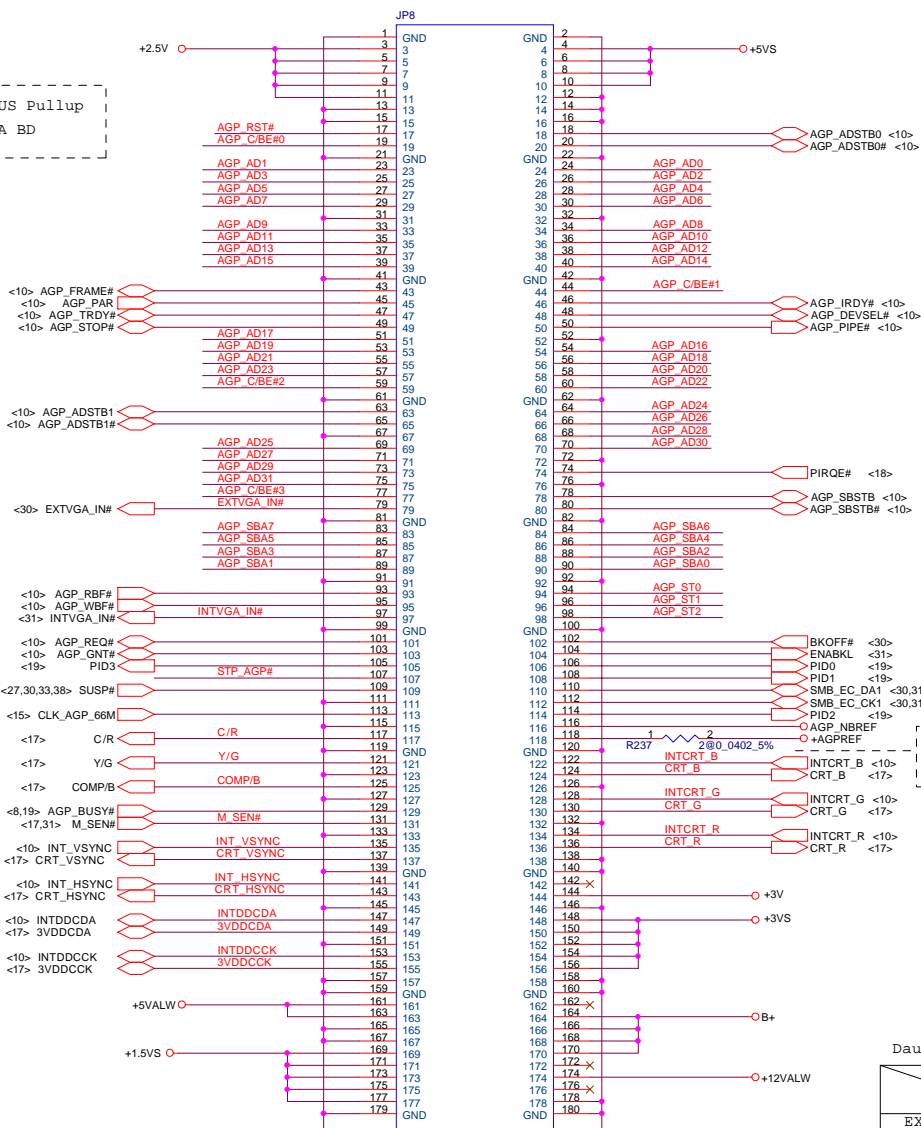
Compal Electronics, Inc.

Title <b>Clock Generator</b>		
Size	Document Number <b>Abacus/TangII LA-1452</b>	Rev 1.0
Date:	Tuesday, November 26, 2002	Sheet 15 of 46

<10> AGP\_ST[0..2] AGP\_ST[0..2]  
 <10> AGP\_SBA[0..7] AGP\_SBA[0..7]  
 <10> AGP\_AD[0..31] AGP\_AD[0..31]  
 <10> AGP\_C/BE[0..3] AGP\_C/BE[0..3]

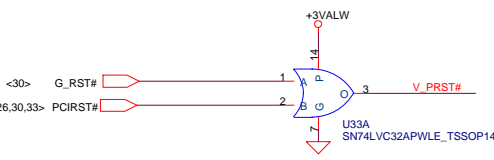
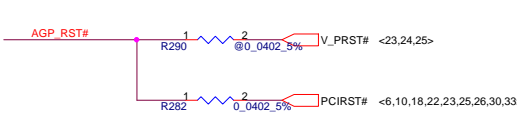
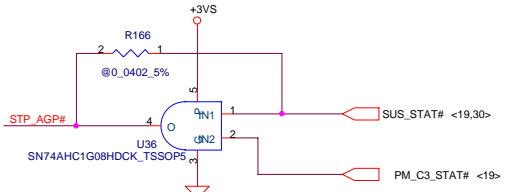
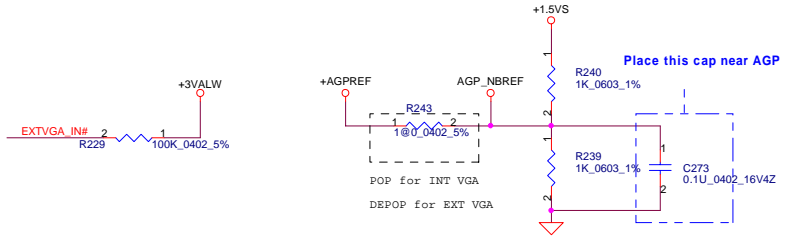


AGP BUS Pullup  
 on VGA BD



FOXCONN\_QT00180A-5120C

CLK\_AGP\_66M  
 Terminator on VGA BD



Daughter Card Present Table

	DOCKED	NON DOCKED
EXTVGA_IN# (Ext. Graphy)	LOW	HIGH
INTVGA_IN# (Int. Graphy)	LOW	HIGH

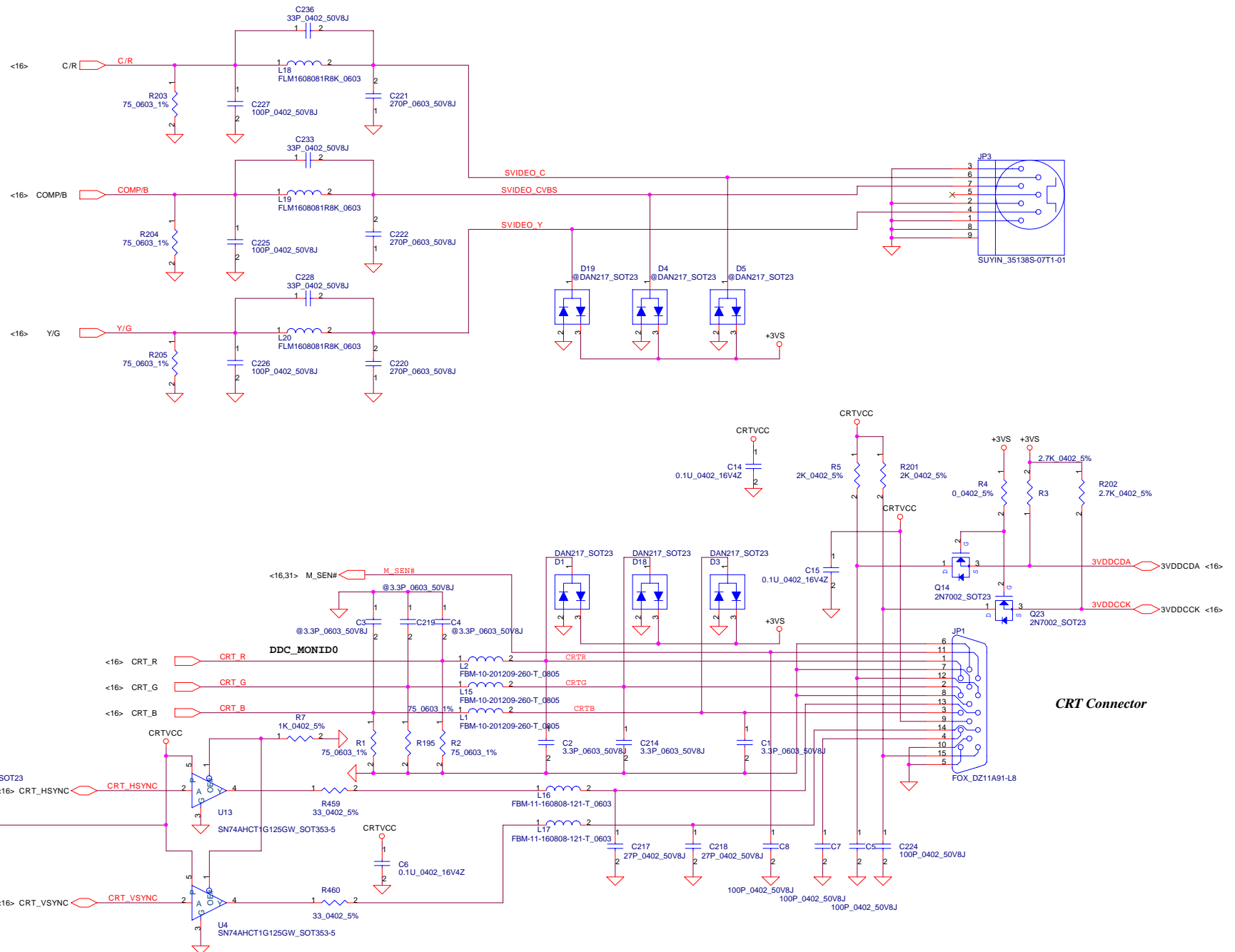
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Compal Electronics, Inc.

Title <b>AGP Conn.</b>		
Size	Document Number <b>Abacus/TangII LA-1452</b>	Rev 1.0
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**CRT Connector**

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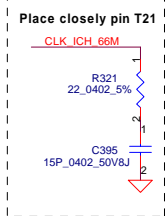
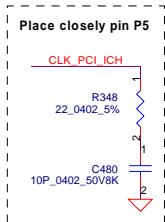
**Compal Electronics, Inc.**

Title: **TVOUT & CRT**

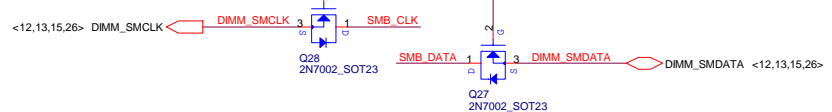
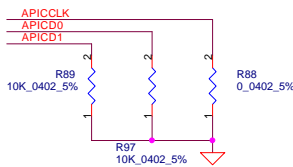
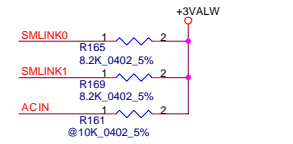
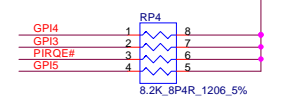
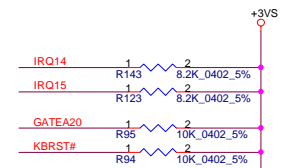
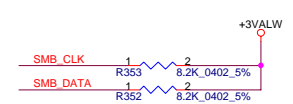
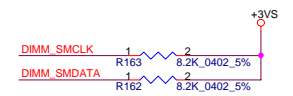
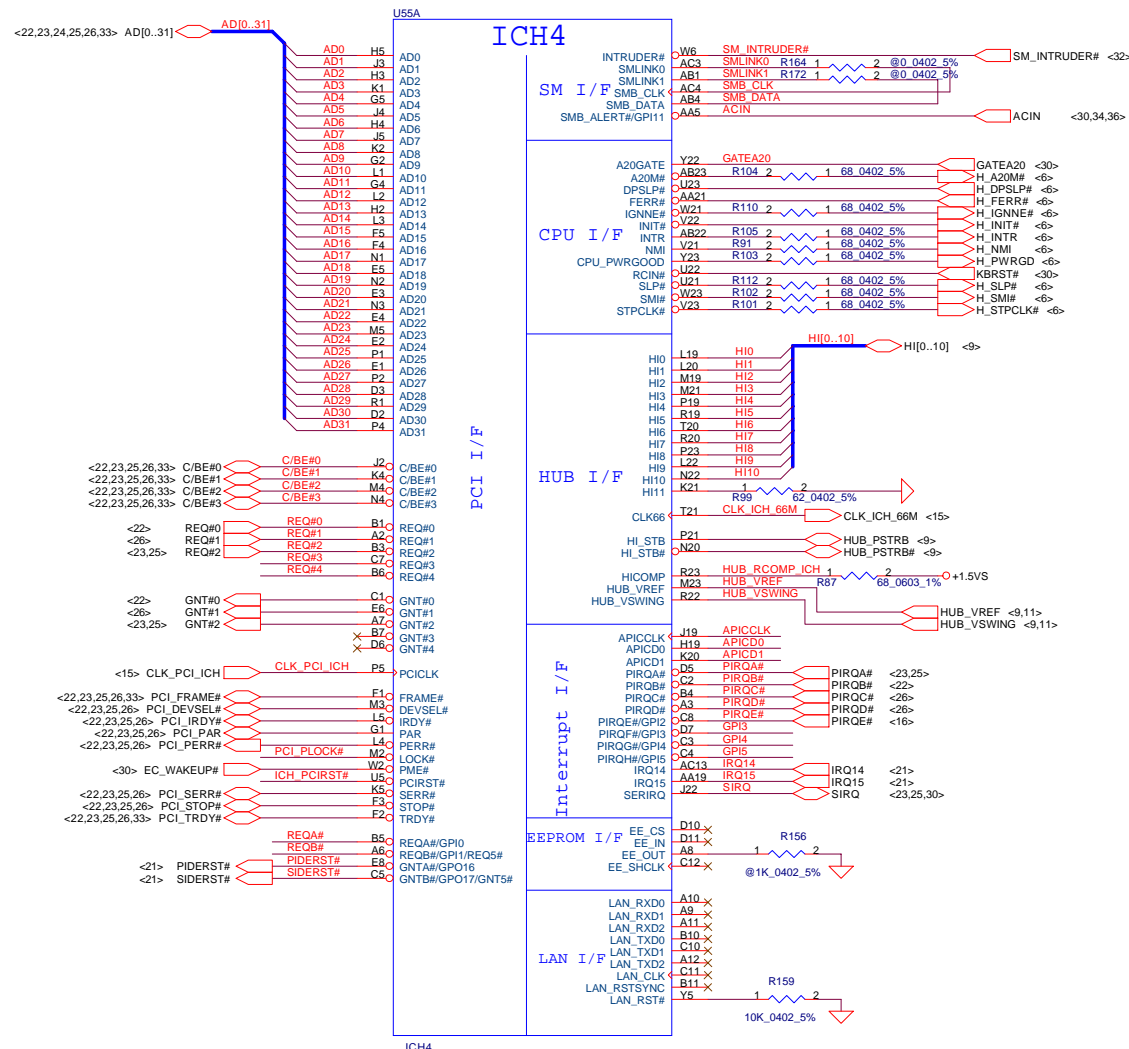
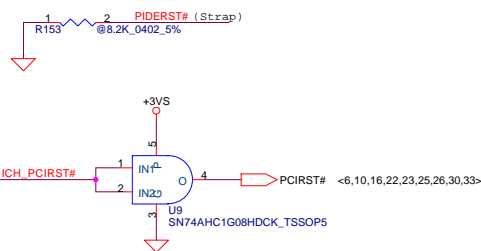
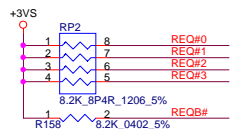
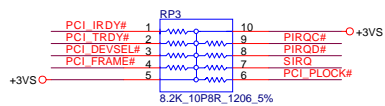
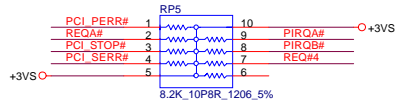
Size: Document Number **Abacus/TangII LA-1452** Rev 1.0

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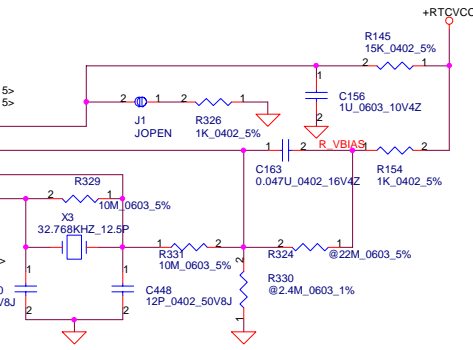
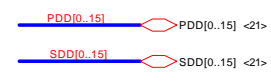
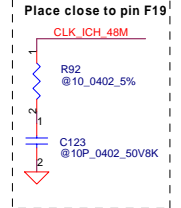
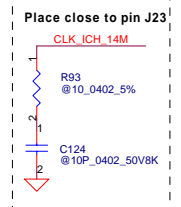
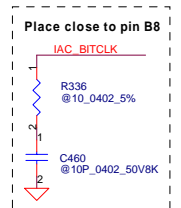
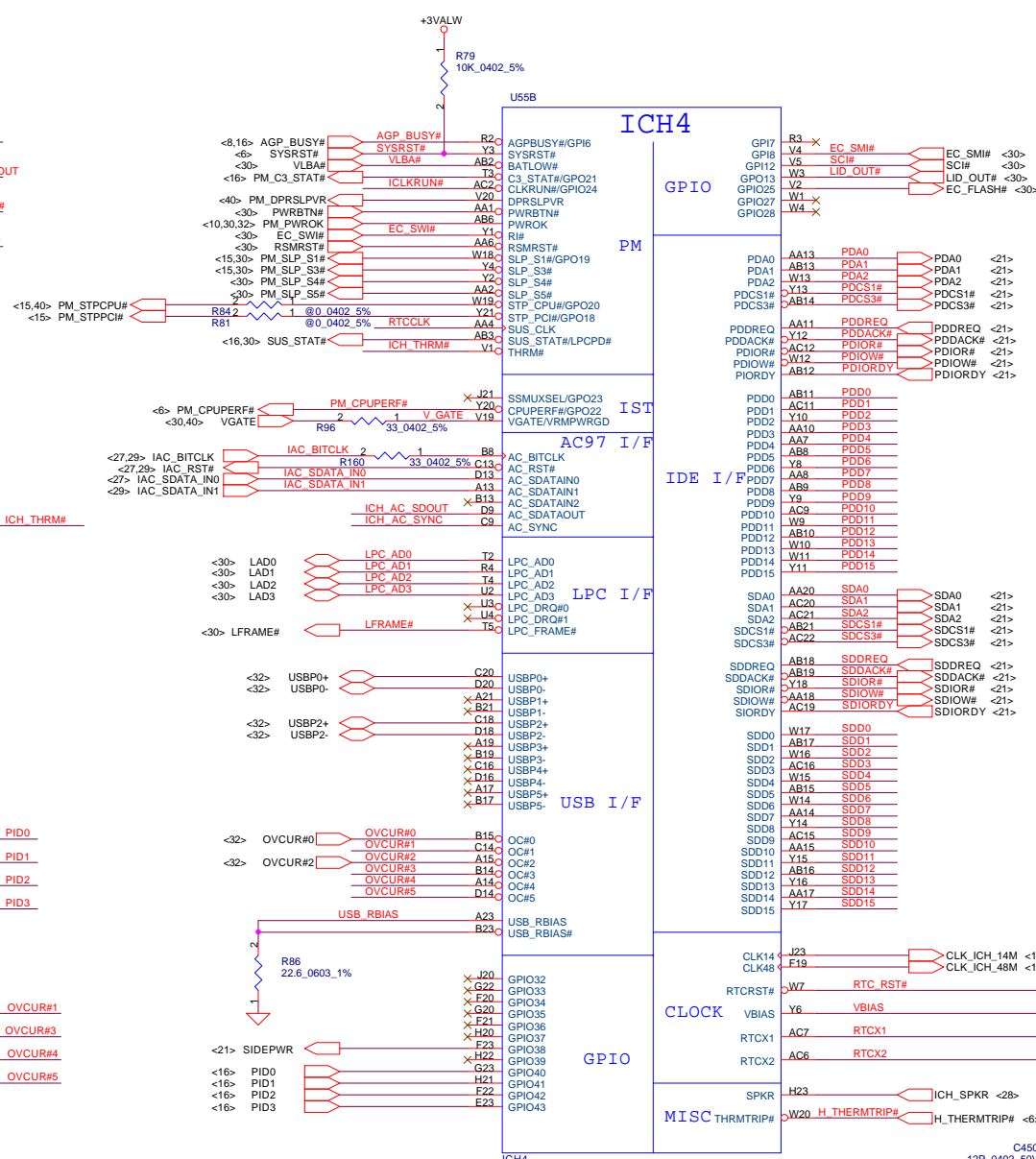
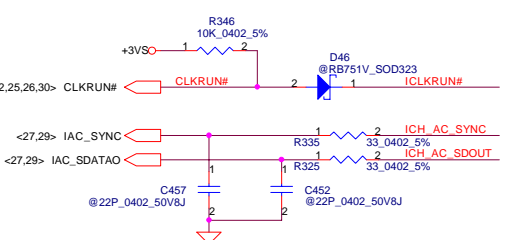
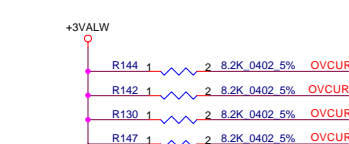
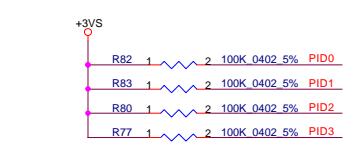
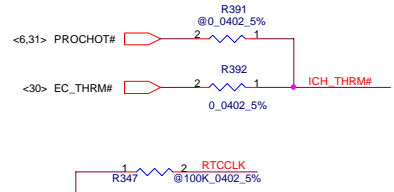
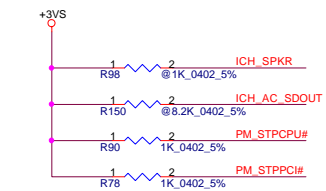
**PCI Pullups**



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<b>Compal Electronics, Inc.</b>		
<b>INTEL ICH4 (1/3)</b>		
Title		
Size	Document Number	Rev
	<b>Abacus/TangII LA-1452</b>	<b>1.0</b>
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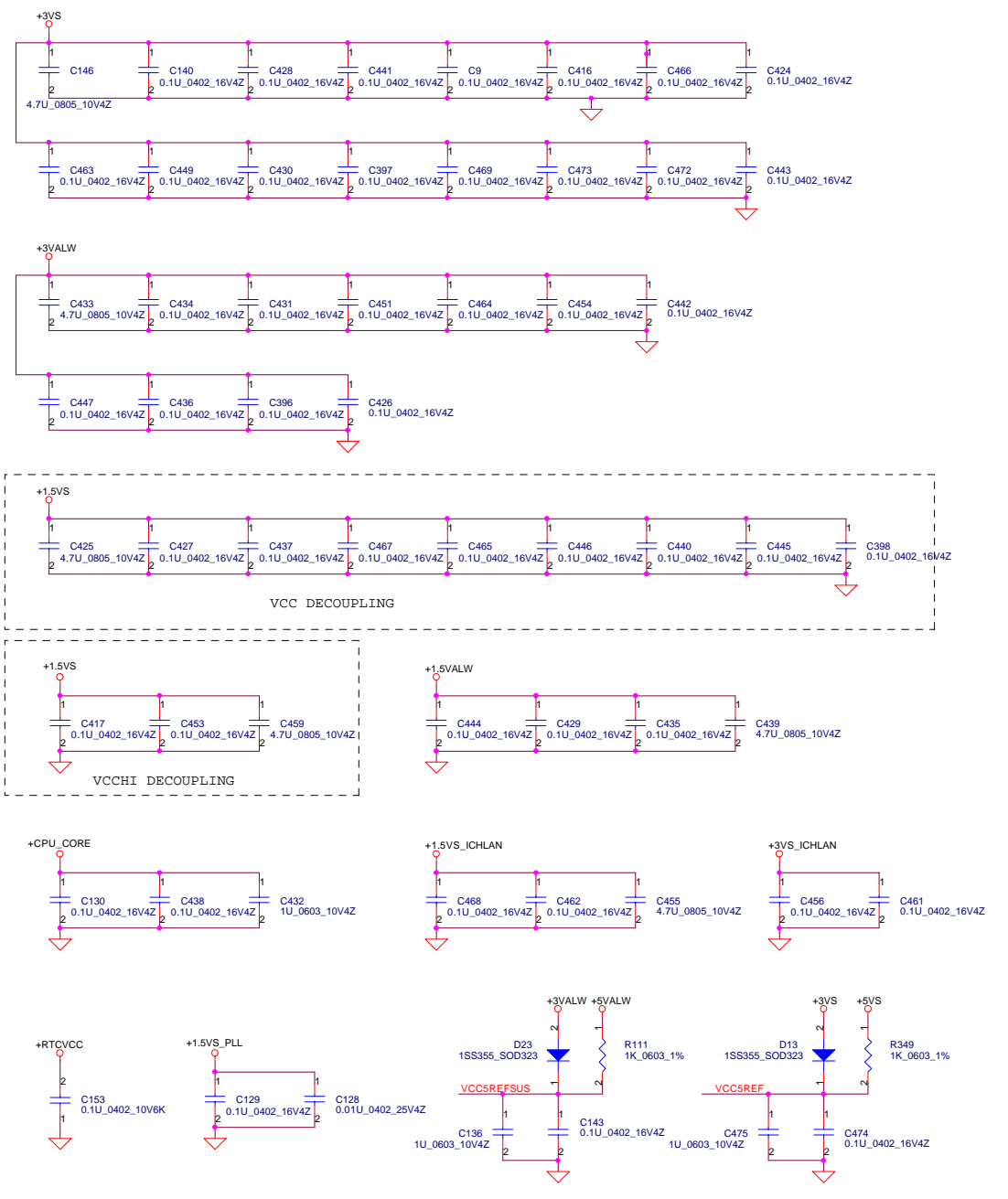
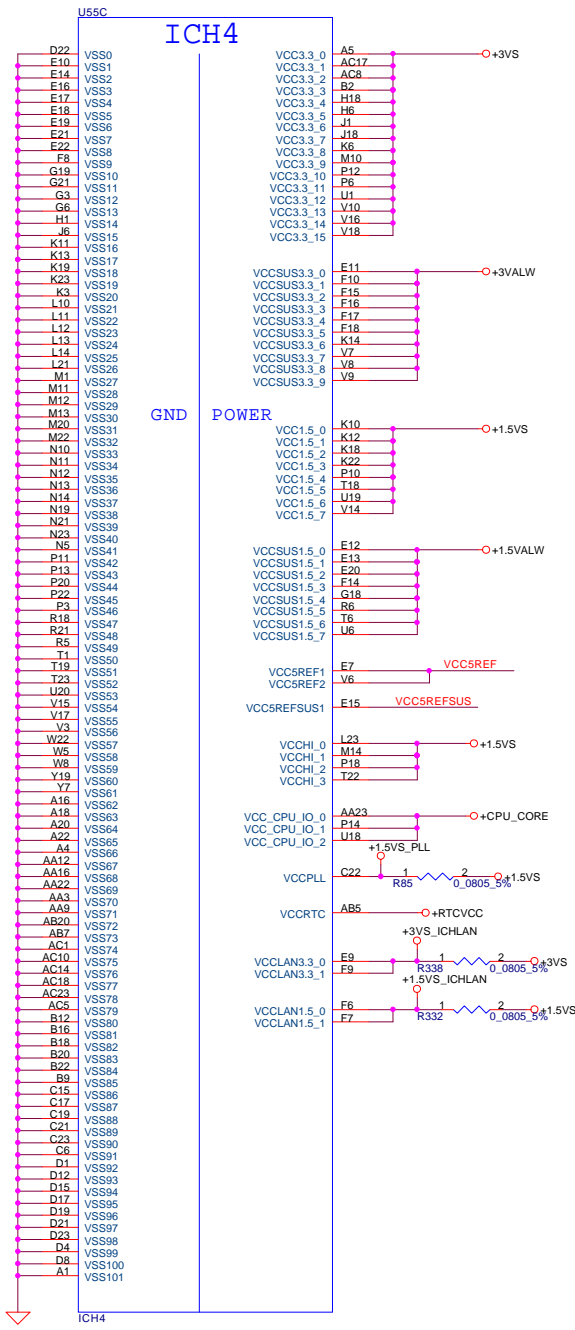


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Title		
INTEL ICH4 (2/3)		
Size	Document Number	Rev
	Abacus/TangII LA-1452	1.0
Date:	Tuesday, November 26, 2002	Sheet 19 of 46

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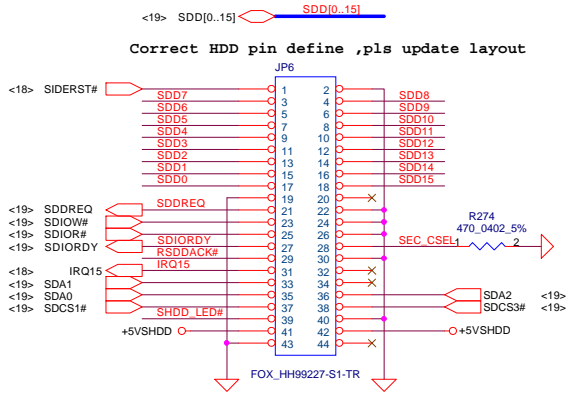
Title INTEL ICH4(3/3)

Size Document Number Abacus/TangII LA-1452 Rev 1.0

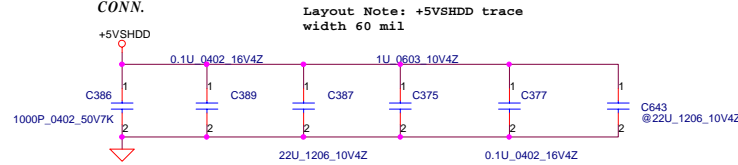
Date: Tuesday, November 26, 2002 Sheet 20 of 46

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**HDD Connector**



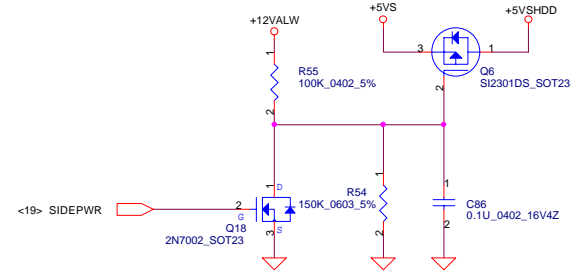
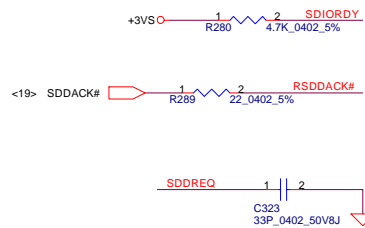
**Placea caps. near HDD CONN.**



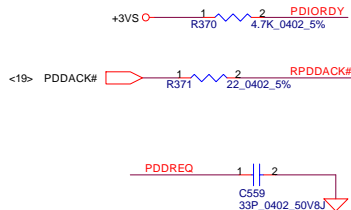
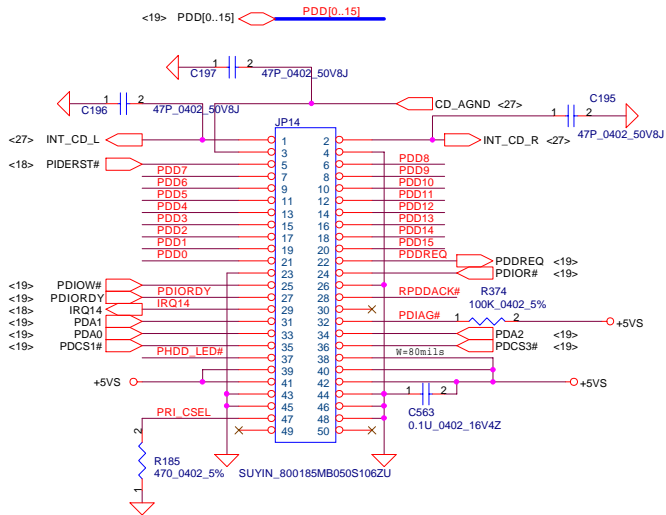
Layout Note: +5VSHDD trace width 60 mil

SI2301DS: P CHANNEL  
VGS: -4.5V, RDS: 130 mOHM  
VGS: -2.5V, RDS: 190mOHM  
Id(MAX): 2.3A  
VGS(MAX): +8V

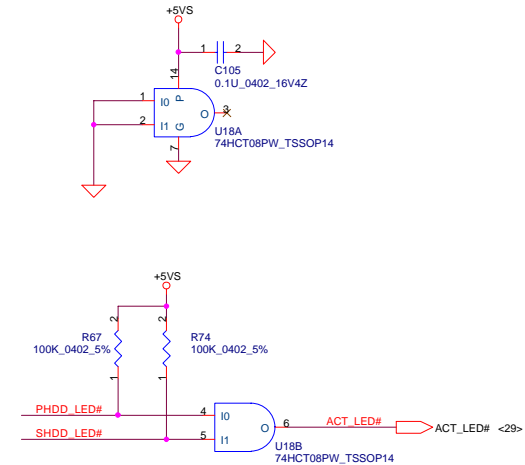
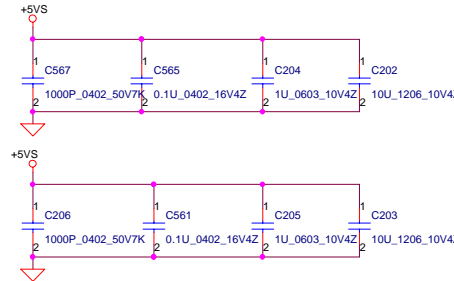
1 D



**CD-ROM Connector**



**Placea caps. near CDROM CONN.**



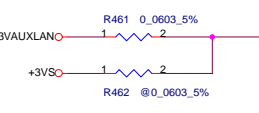
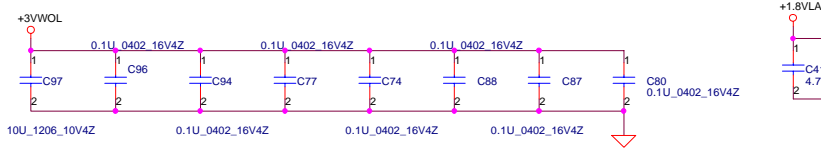
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**Compal Electronics, Inc.**

**IDE/FDD/CD-ROM Module**

Title		
IDE/FDD/CD-ROM Module		
Size	Document Number	Rev
	Abacus/TangII LA-1452	1.0
Date:	Tuesday, November 26, 2002	Sheet 21 of 46

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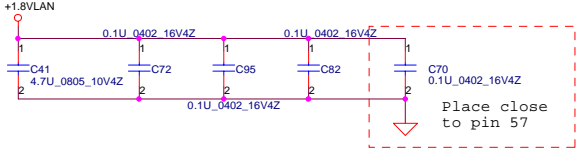
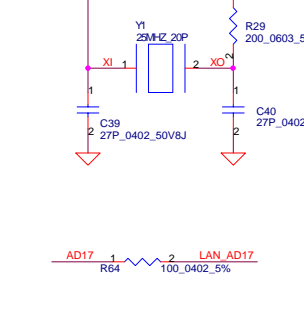


<18,23,24,25,26,33> AD[0..31]

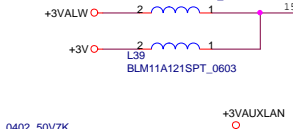
AD31	122	PCI_AD31
AD30	123	PCI_AD30
AD29	124	PCI_AD29
AD28	126	PCI_AD28
AD27	127	PCI_AD27
AD26	128	PCI_AD26
AD25	3	PCI_AD25
AD24	4	PCI_AD24
AD23	6	PCI_AD23
AD22	8	PCI_AD22
AD21	8	PCI_AD21
AD20	10	PCI_AD20
AD19	11	PCI_AD19
AD18	14	PCI_AD18
AD17	14	PCI_AD17
AD16	16	PCI_AD16
AD15	33	PCI_AD15
AD14	36	PCI_AD14
AD13	34	PCI_AD13
AD12	37	PCI_AD12
AD11	38	PCI_AD11
AD10	39	PCI_AD10
AD9	41	PCI_AD9
AD8	42	PCI_AD8
AD7	46	PCI_AD7
AD6	48	PCI_AD6
AD5	49	PCI_AD5
AD4	50	PCI_AD4
AD3	51	PCI_AD3
AD2	53	PCI_AD2
AD1	54	PCI_AD1
AD0	55	PCI_AD0

# Broadcom BCM 4401L

<18,23,25,26,33>	C/BE#3	4	PCI_CBE3_L
<18,23,25,26,33>	C/BE#2	18	PCI_CBE2_L
<18,23,25,26,33>	C/BE#1	32	PCI_CBE1_L
<18,23,25,26,33>	C/BE#0	43	PCI_CBE0_L
<18,23,25,26,33>	PCI_FRAME#	20	PCI_FRAME_L
<18,23,25,26>	PCI_IRDY#	21	PCI_IRDY_L
<18,23,25,26>	PCI_TRDY#	23	PCI_TRDY_L
<18,23,25,26,33>	PCI_DEVSEL	26	PCI_DEVSEL_L
<18,23,25,26>	PCI_STOP	27	PCI_STOP_L
<18,23,25,26>	PCI_PERR#	28	PCI_PERR_L
<18,23,25,26>	PCI_SERR#	29	PCI_SERR_L
<18,23,25,26>	PCI_PAR	116	PCI_PAR_L
<18>	PIRQ#	117	PCI_RST_L
<16,18,23,25,26,30,33>	PCIRST#	118	PCI_RST_L
<15>	CLK_PCI_LAN	119	PCI_GNT_L
<18>	GNT#0	121	PCI_REQ_L
<31>	LAN_PME#	113	PCI_PME_L
<18,23,25,26,33>	CLKRUN#	22	PCI_CLKRUN_L

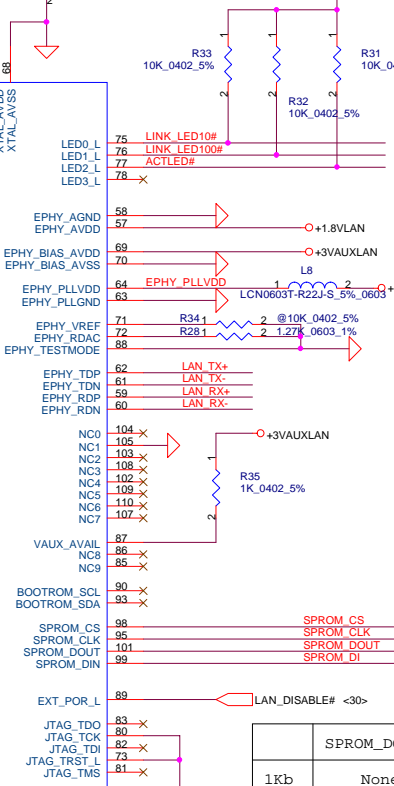


Place close to pin 57

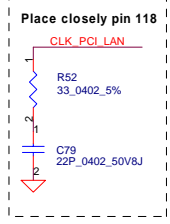


Place close to pin 69

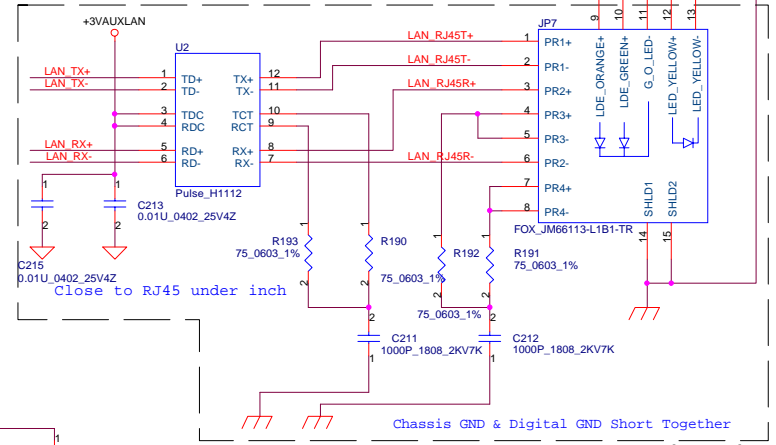
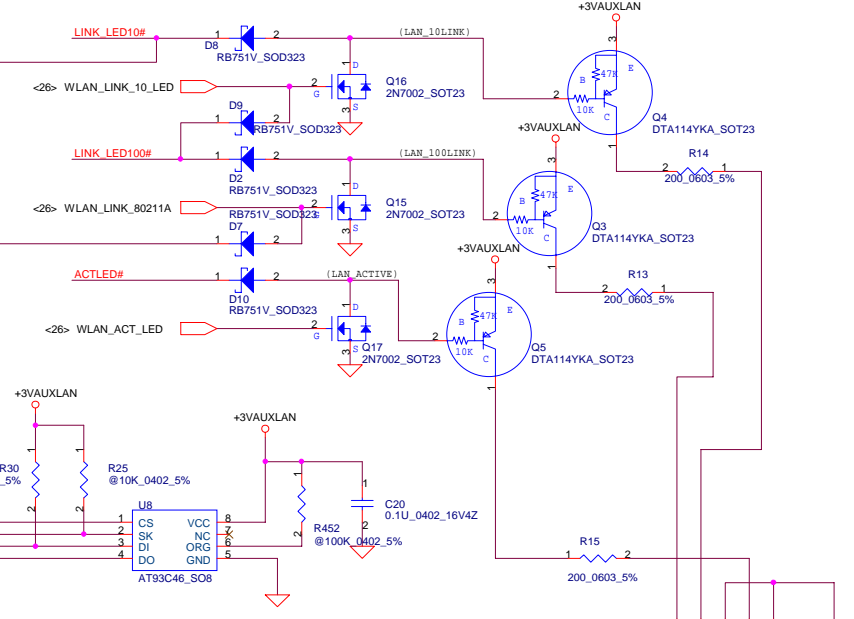
WLAN	LOM	LED (JP28)
WLAN_LINK_80211A	LINK_LED100#	ORANGE (100M)
WLAN_LINK_10_LDE	LINK_LED10#	GREEN (10M)
WLAN_ACT_LED	ACTLED#	YELLOW
WLAN_LINK_80211A		
WLAN_LINK_10_LDE	NC	ORANGE/GREEN



	SPROM_DOUT	SPROM_CLK
1Kb	None	None
4Kb	10K Pullup	None
16Kb	None	10K Pullup



Place closely pin 118

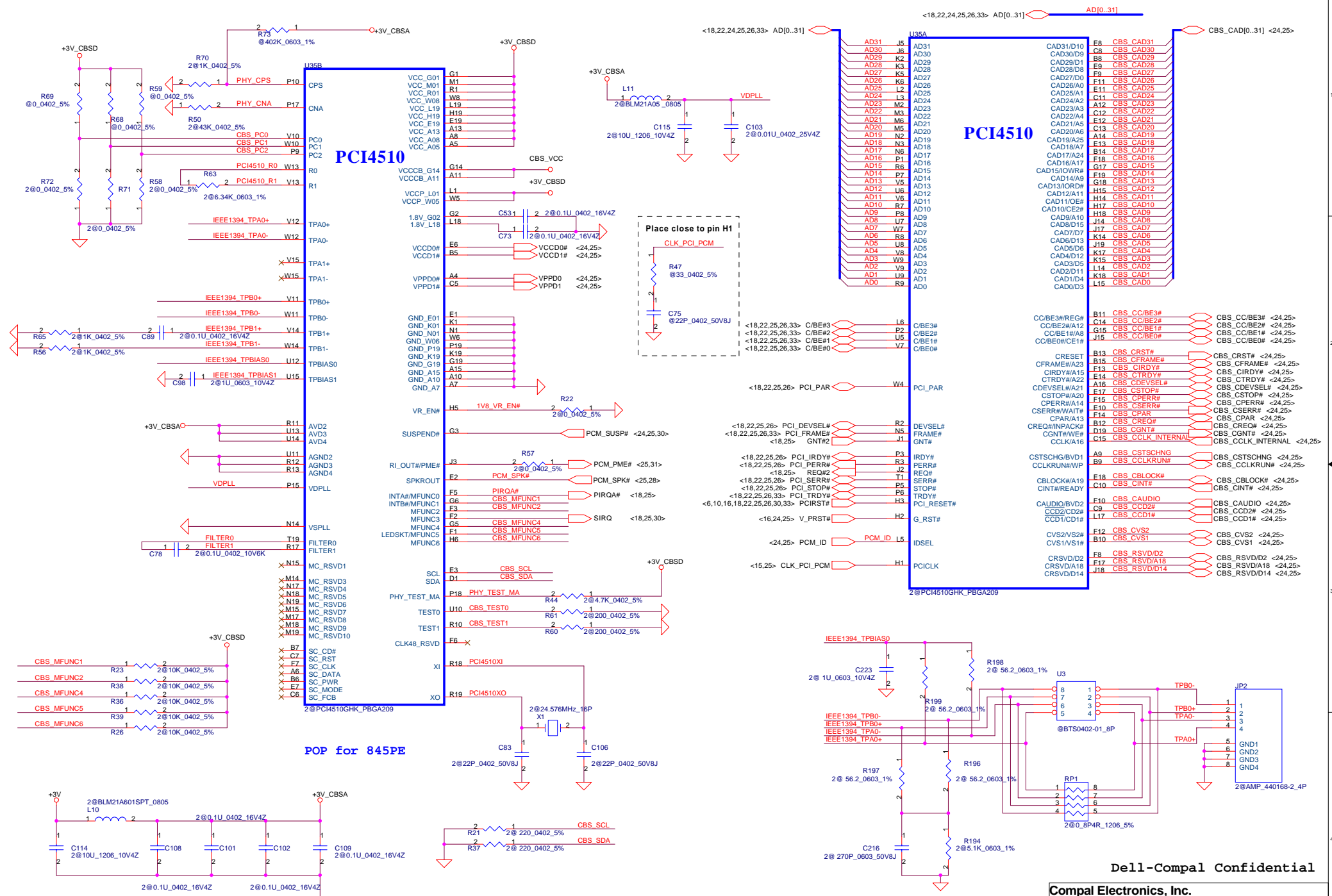


Chassis GND & Digital GND Short Together  
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<b>Compal Electronics, Inc.</b>		
<b>BROADCOM 4401L LAN</b>		
Title	Document Number	Rev
	<b>Abacus/Tangit LA-1452</b>	1.0
Date:	Tuesday, November 26, 2002	Sheet 22 of 46

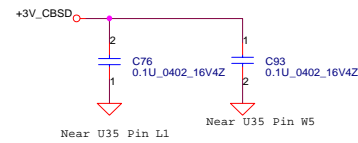
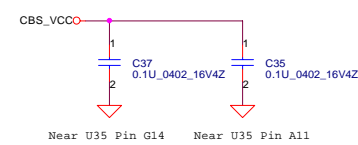
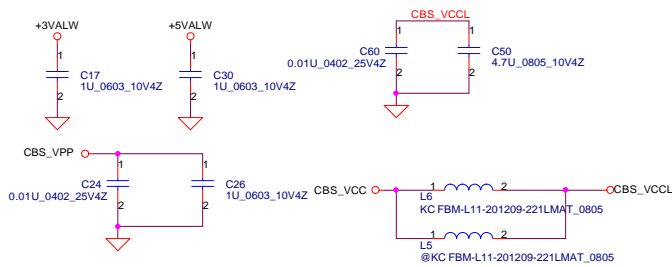
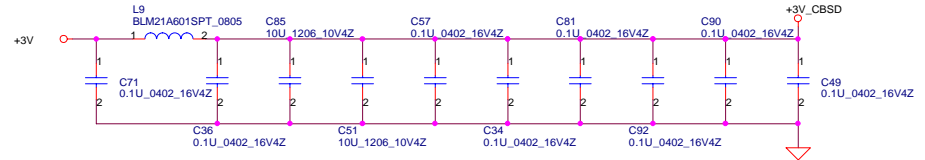
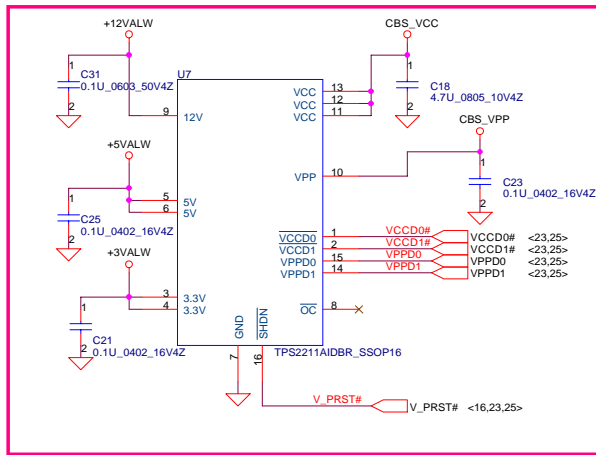
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This page POP with 845PE for EXT.

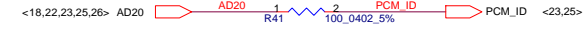
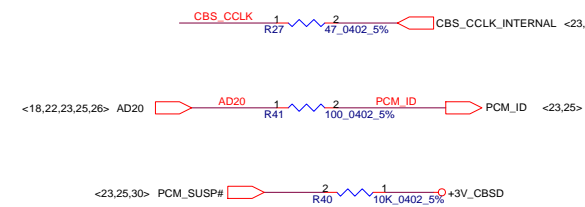
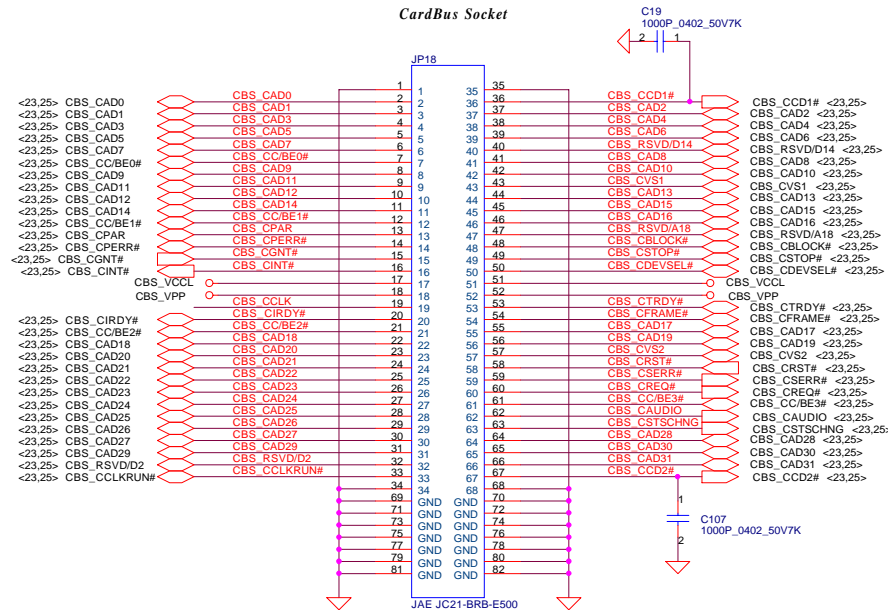


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PCMCIA Power Controller



CardBus Socket



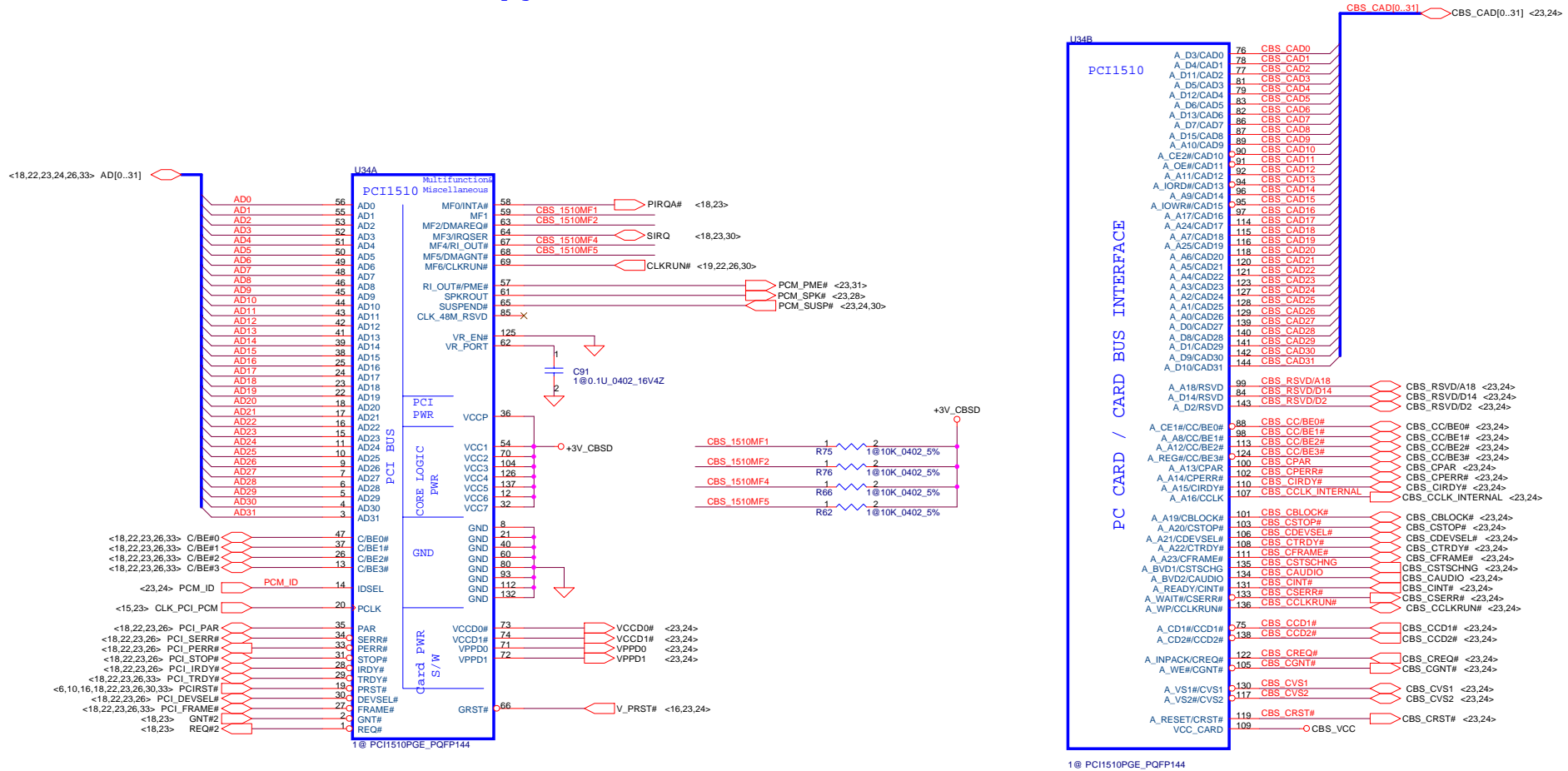
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Compal Electronics, Inc.		
Title <b>PCMCIA Socket</b>		
Size	Document Number <b>Abacus/Tangli LA-1452</b>	Rev 1.0
Date	Tuesday, November 26, 2002	Sheet 24 of 46

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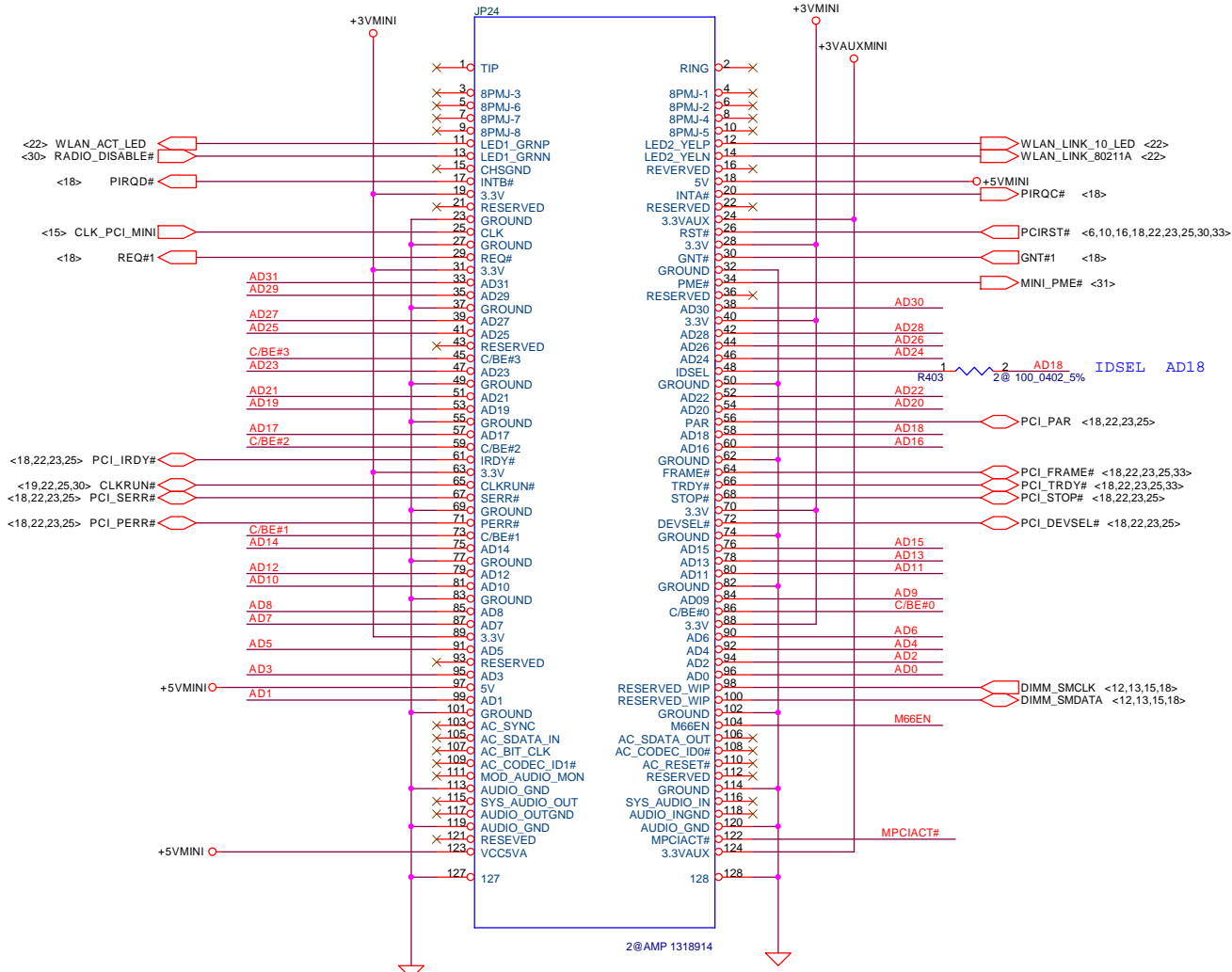


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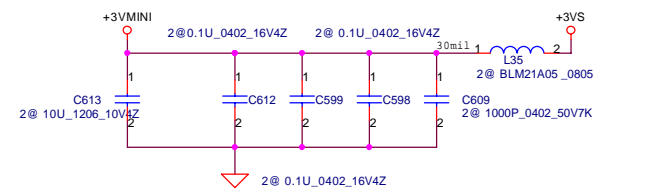
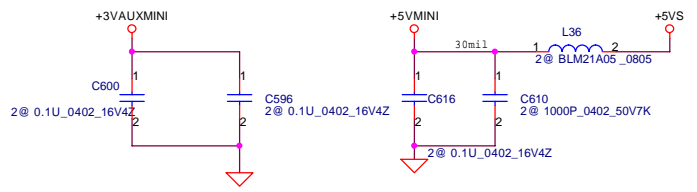
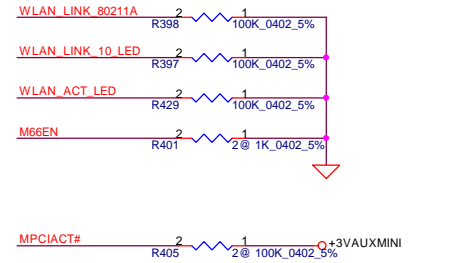
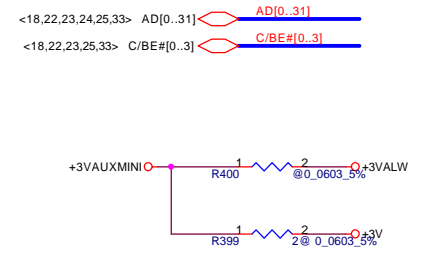
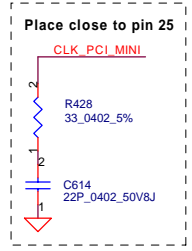
Compal Electronics, Inc.			
Title PCMCIA Controller PCI1510			
Size	Document Number	Rev	
	Abacus/Tangli LA-1452	1.0	
Date:	Tuesday, November 26, 2002	Sheet	25 of 46

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# MINI PCI TYPE III



WIRELESS SUPPORT ONLY

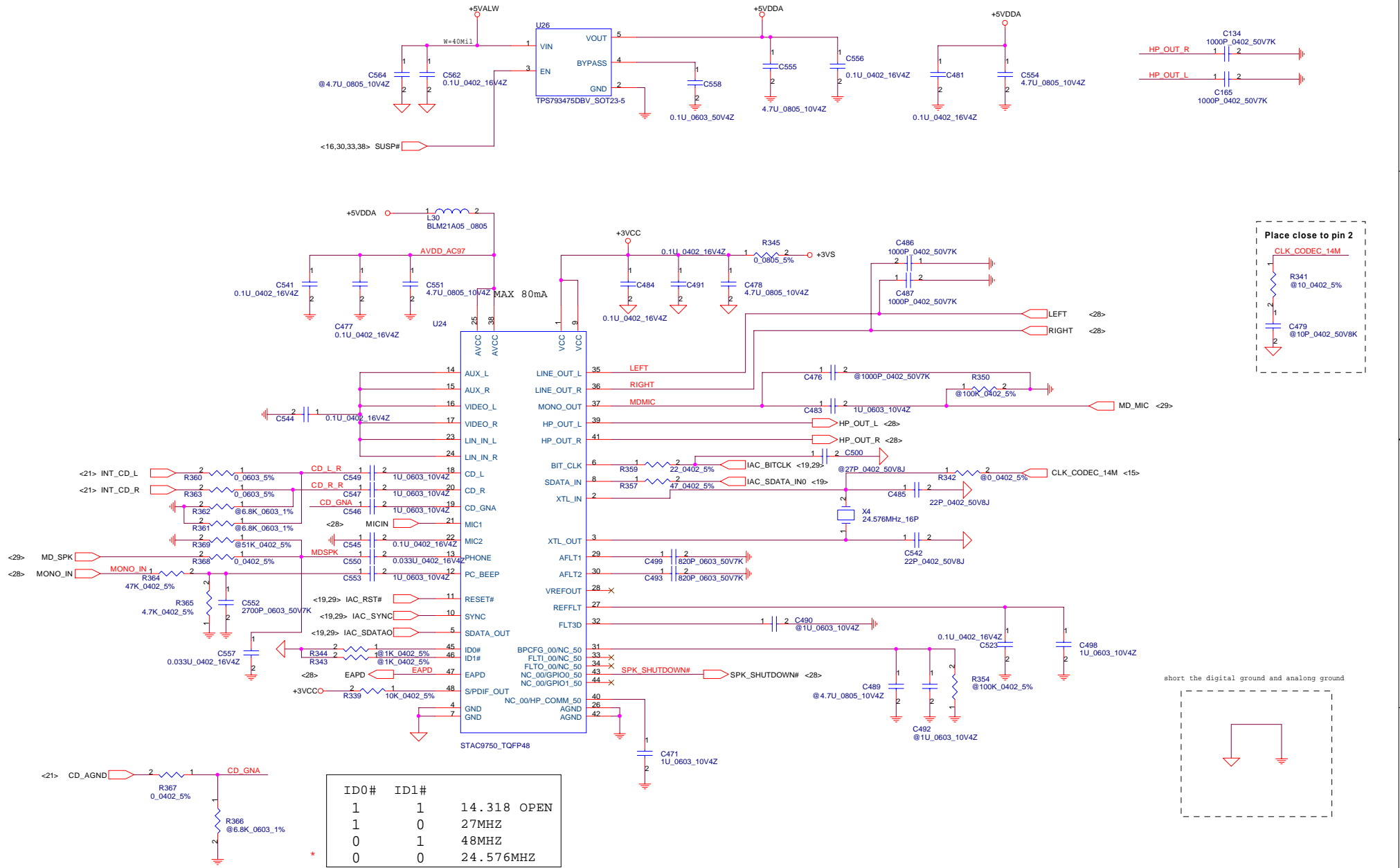


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Compal Electronics, Inc.

Title			MiniPci Port		
Size	Document Number				Rev
	Abacus/TangII LA-1452				1.0
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Place close to pin 2

CLK\_CODEC\_14M

R341 @10\_0402\_5%

C479 @10P\_0402\_50V8K

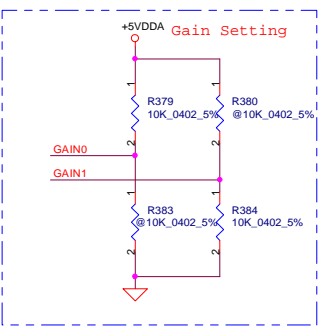
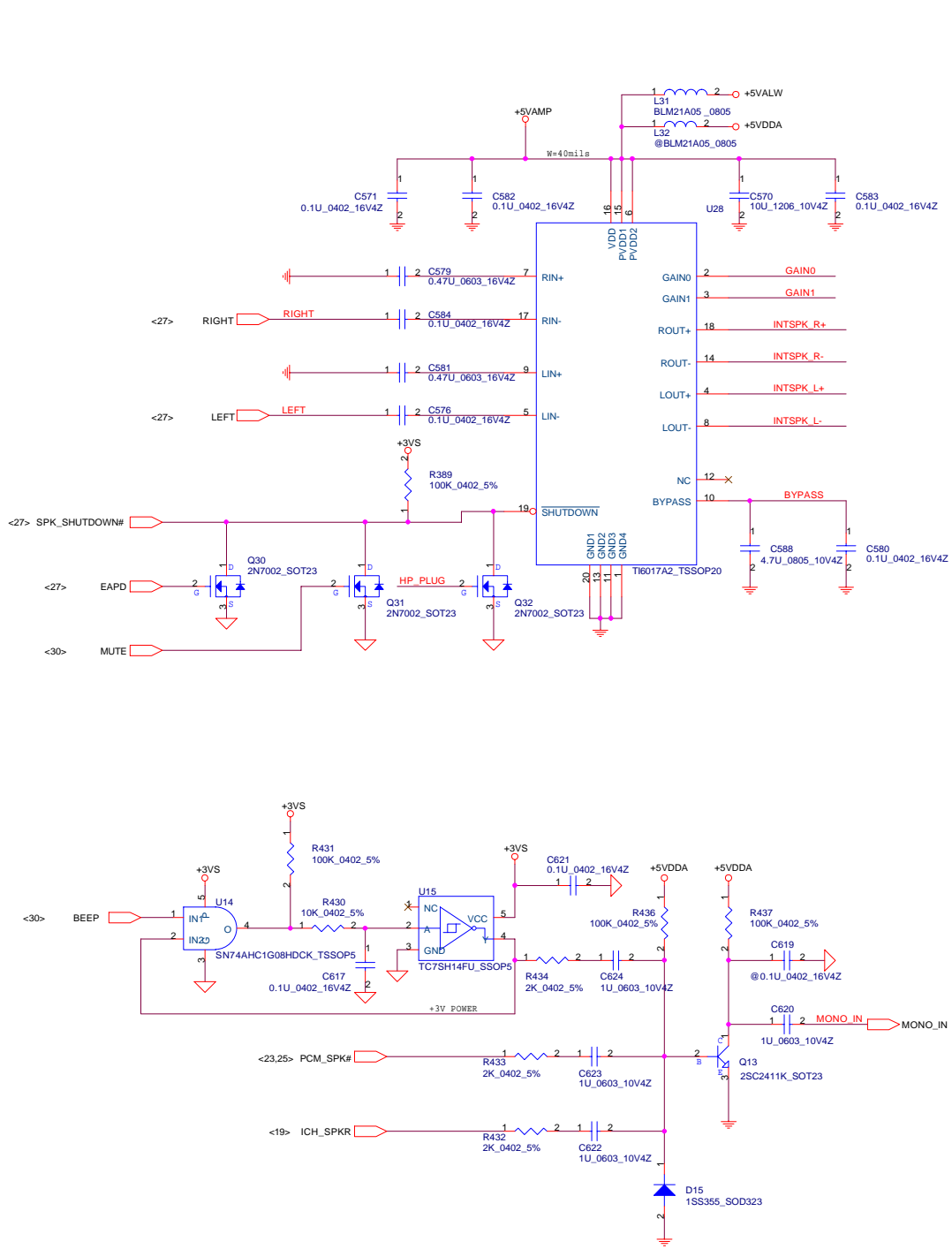
short the digital ground and analog ground

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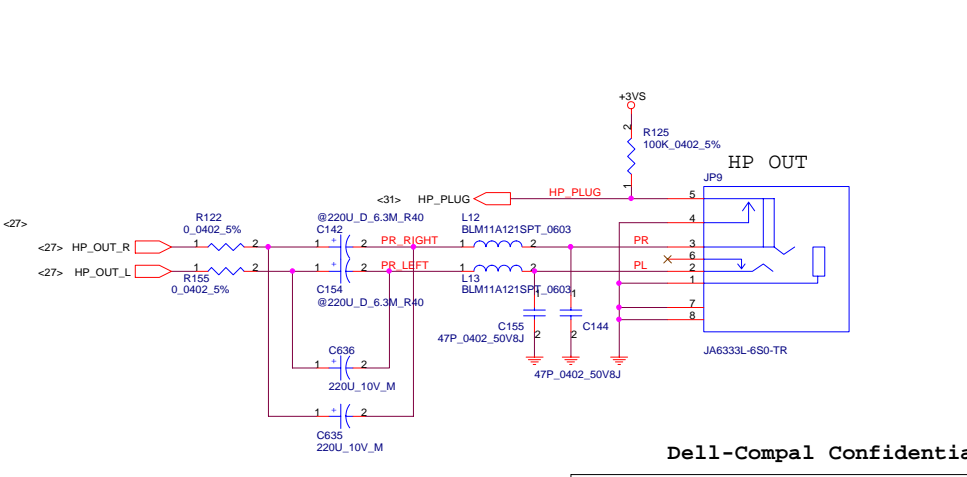
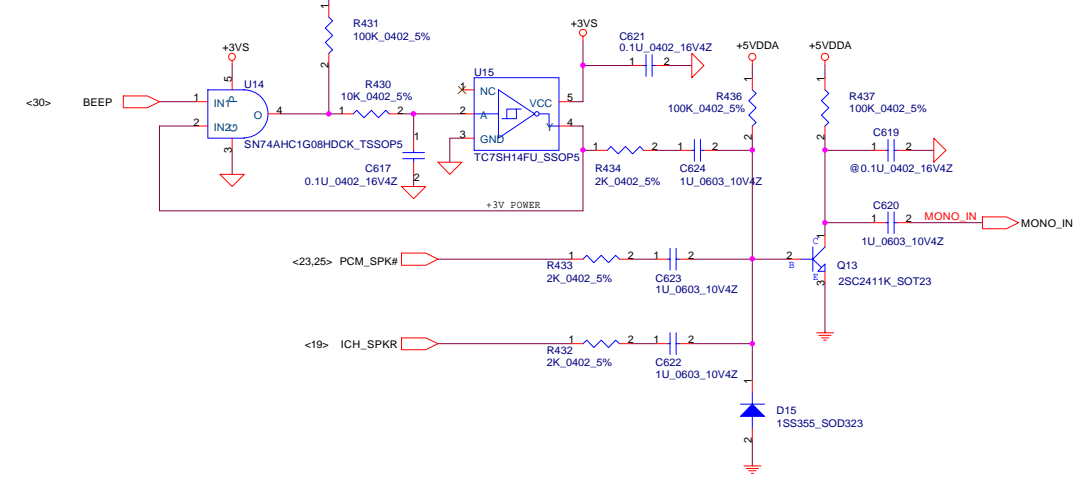
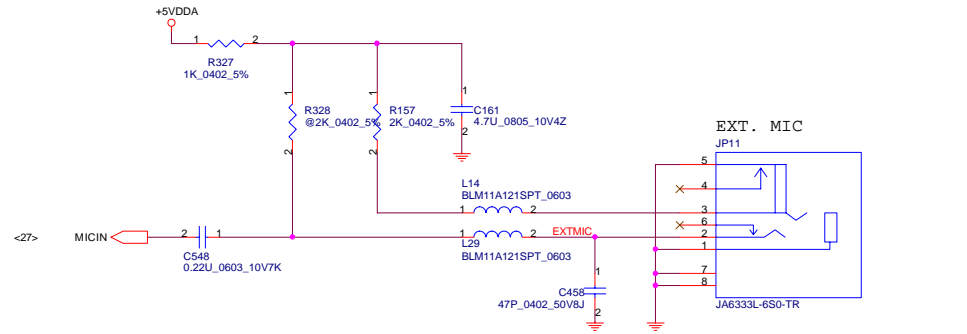
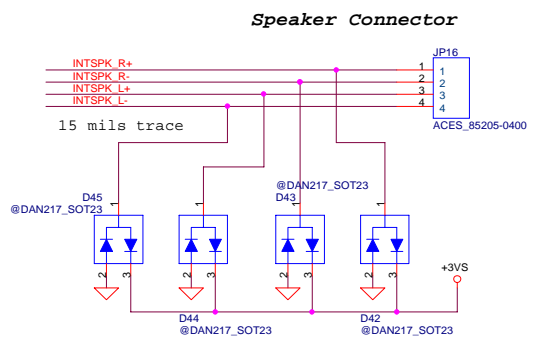
Compal Electronics, Inc.

Title		
AC97 CODEC		
Size	Document Number	Rev
	Abacus/TangII LA-1452	1.0
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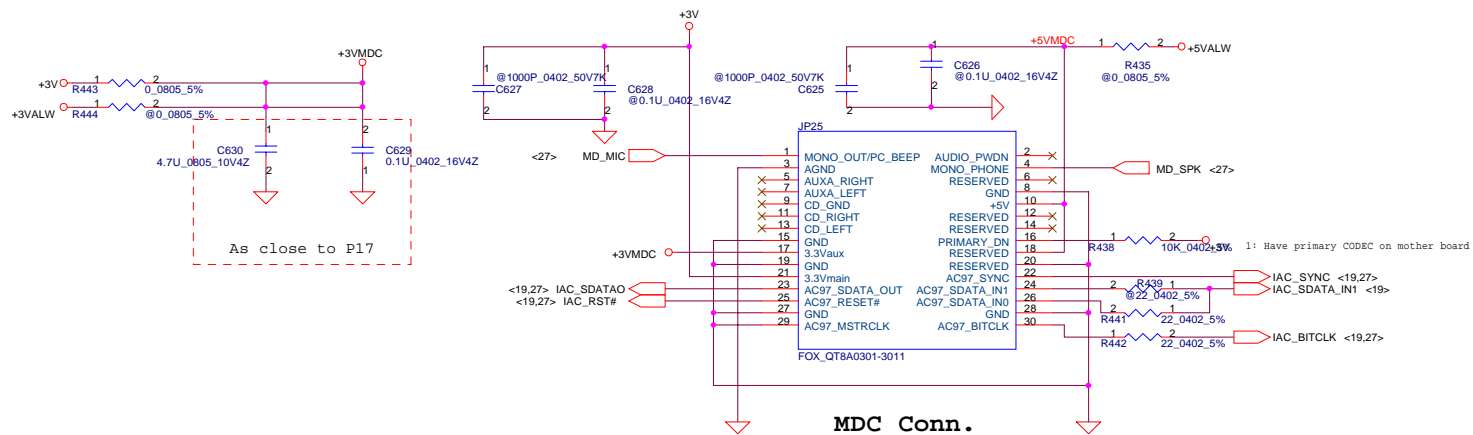
GAIN0	GAIN1	AV(inv)	INPUT IMPEDANCE
0	0	6dB	90K ohm
0	1	10dB	70K ohm
1	0	15.6dB	45K ohm
1	1	21.6dB	25K ohm



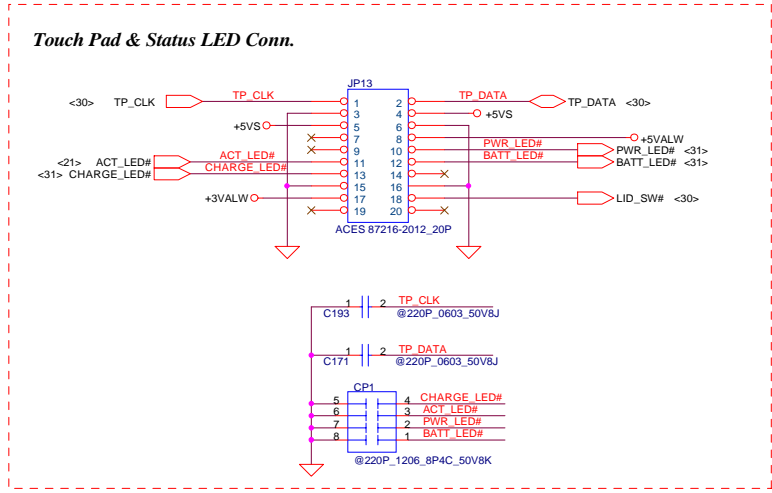
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Title		
Compal Electronics, Inc.		
AMP & Audio Jack		
Size	Document Number	Rev
	Abacus/TangII LA-1452	1.0
Date:	Tuesday, November 26, 2002	Sheet 28 of 46

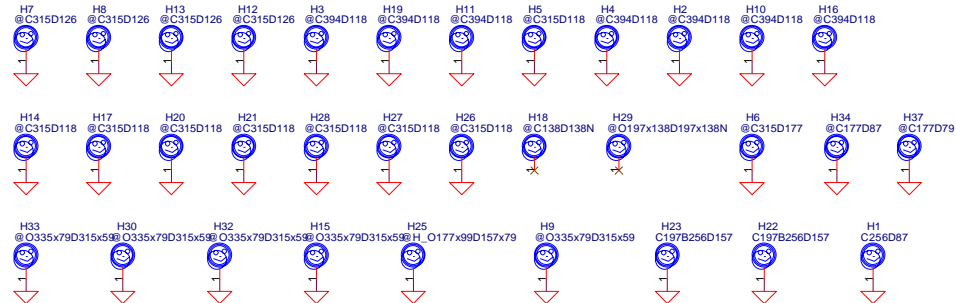
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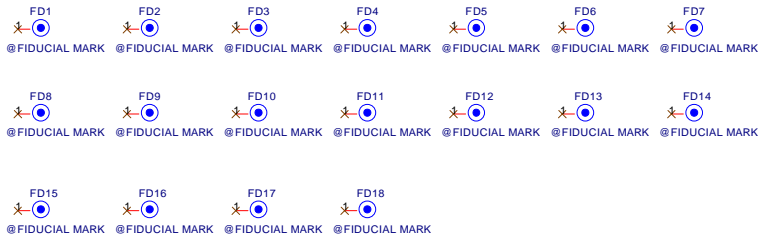
**MDC Note**  
 Pin 1 is NC for Pctel and connexant MDC modem  
 Pin 2 is NC for Pctel and connexant MDC modem



**Screw Hole**



**Fiducial Mark**

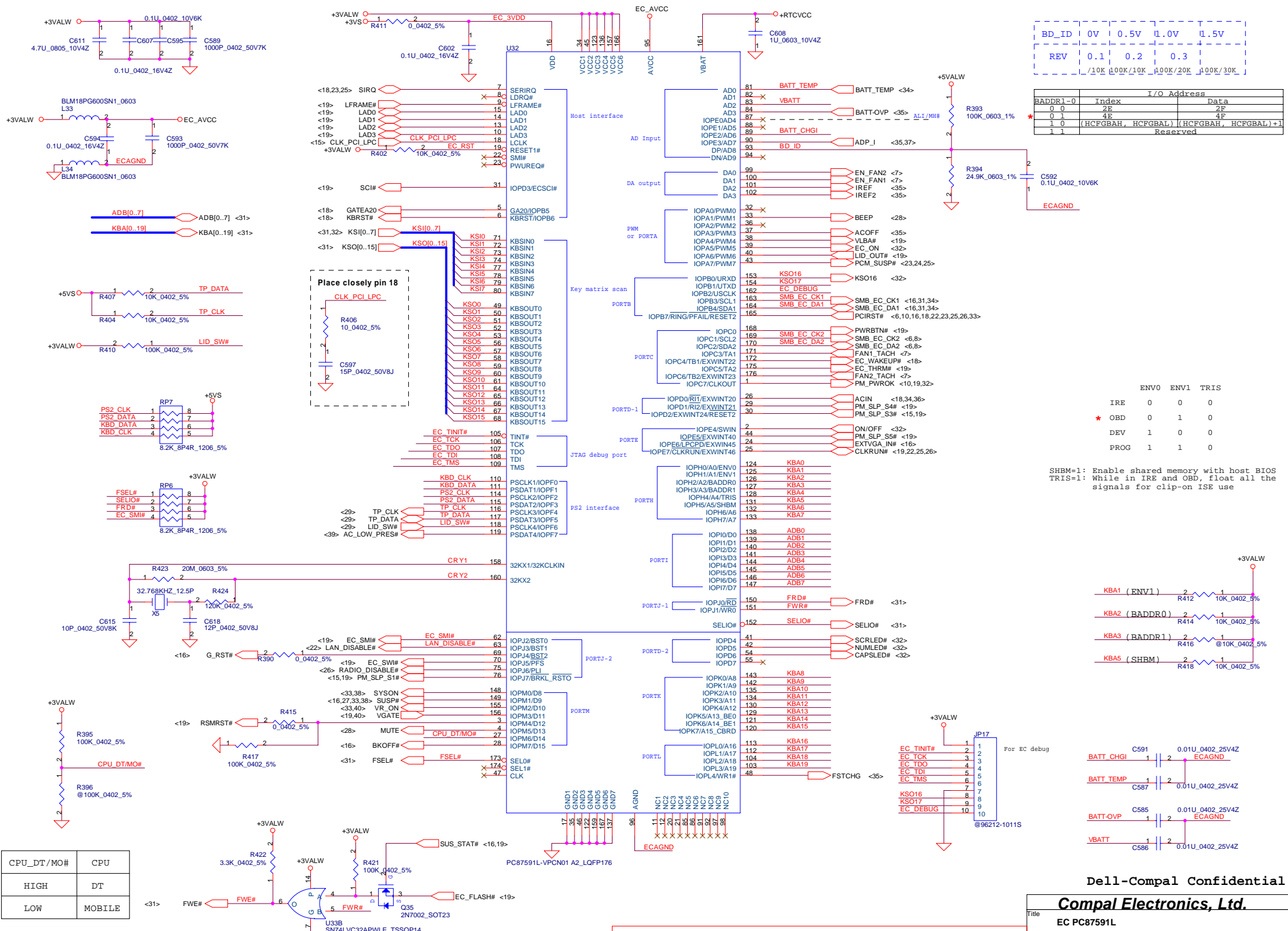


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**Compal Electronics, Inc.**

Title		
<b>MDC / SWITCH Connector</b>		
Size	Document Number	Rev
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Date:	Tuesday, November 26, 2002	Sheet 29 of 46

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BD_ID	0V	0.5V	1.0V	1.5V
REV	0.1	0.2	0.3	
	/10K	/100K	/10K	/100K/20K

BA0DR1-0	Index	I/O Address	Data
0	0	2F	2F
0	1	4E	4F
1	0	(HCFGBAH, HCFGBAL)	(HCFGBAH, HCFGBAL)+1
1	1	Reserved	

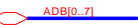
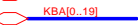
ENV0	ENV1	TRIS
IRE	0	0
OBD	0	1
DEV	1	0
PROG	1	1

SHBM=1: Enable shared memory with host BIOS  
 TRIS=1: While in IRE and OBD, float all the signals for clip-on ISE use

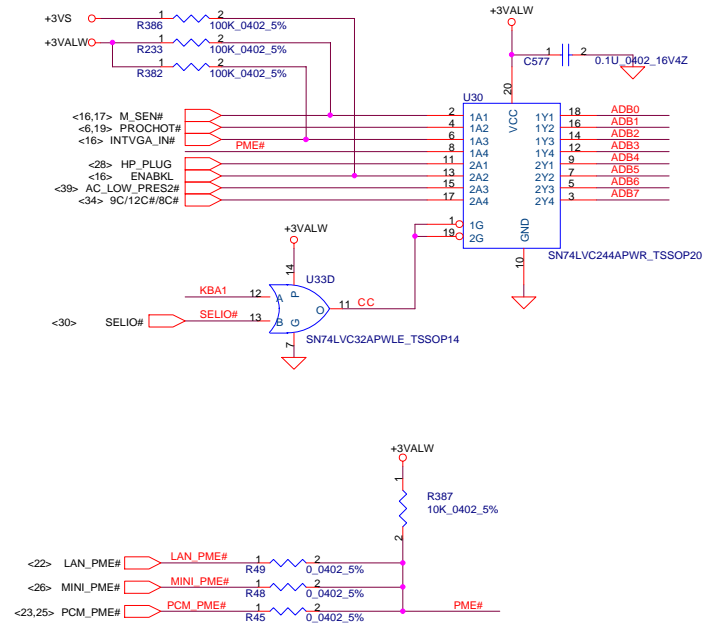
CPU_DT/MO#	CPU
HIGH	DT
LOW	MOBILE

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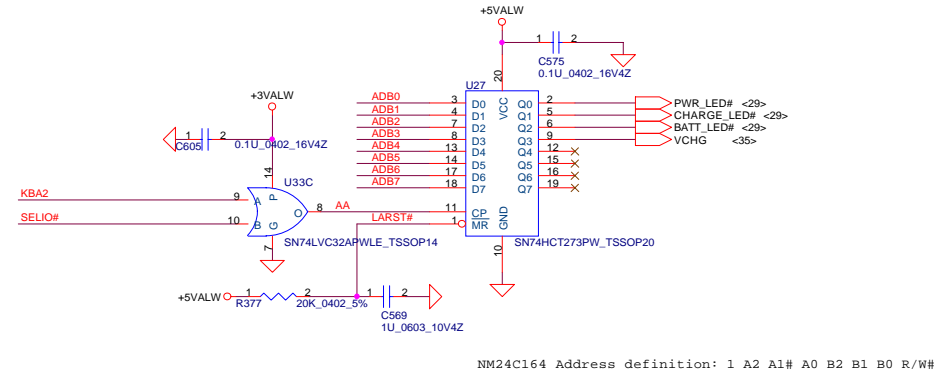
**Compal Electronics, Ltd.**  
 EC PC87591L

<30> ADB[0..7]  ADB[0..7]  
 <30> KBA[0..19]  KBA[0..19]

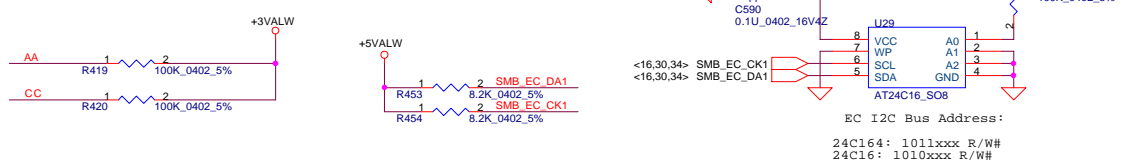
**Input Port**



**Output Port**

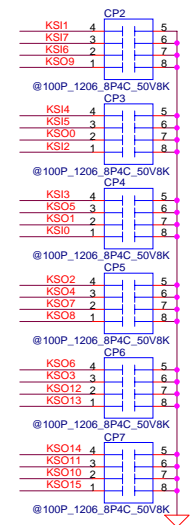
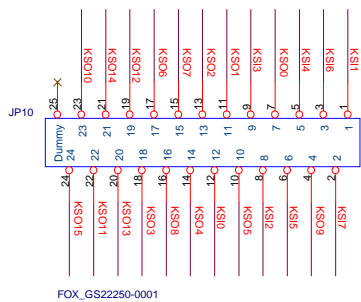




NM24C164 Address definition: 1 A2 A1# A0 B2 B1 B0 R/W#

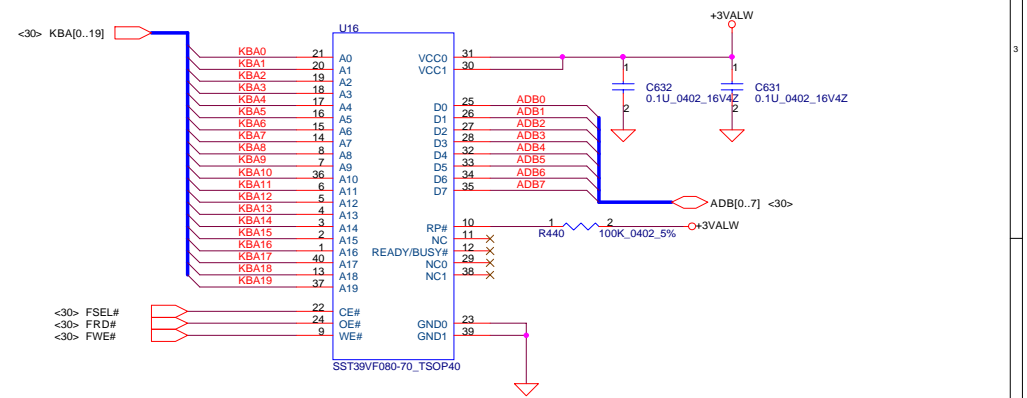


EC I2C Bus Address:  
 24C164: 1011xxxx R/W#  
 24C16: 1010xxxx R/W#

**INT\_KBD CONN.**



<30> KSO[0..15]  KSO[0..15]  
 <30,32> KSI[0..7]  KSI[0..7]



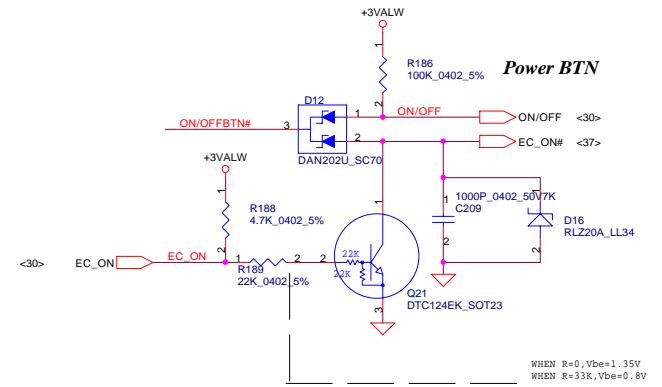
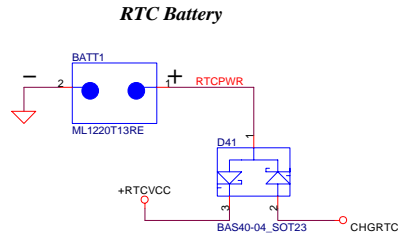
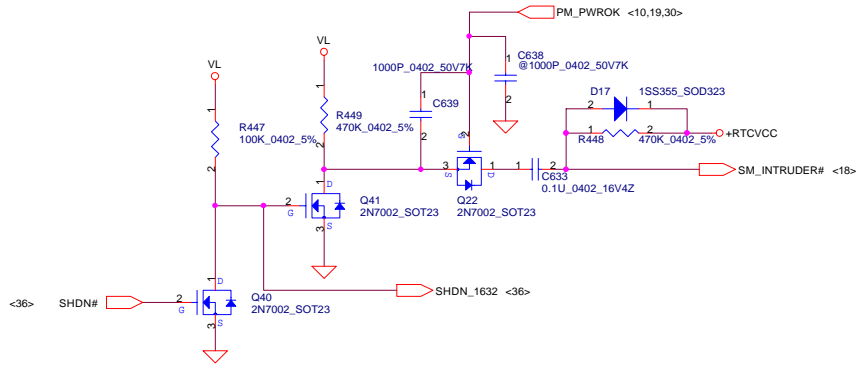
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**Compal Electronics, Inc.**

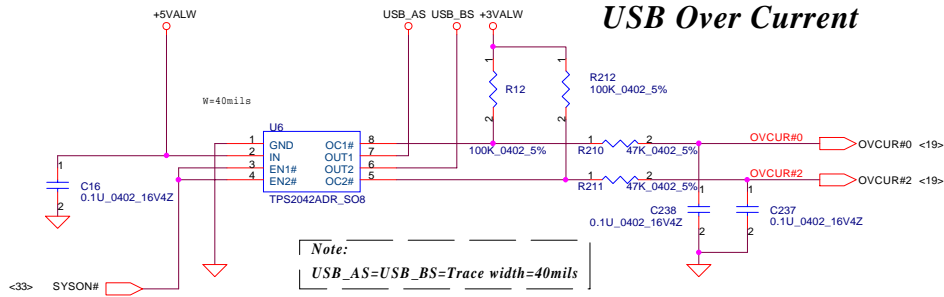
**EC Extend I/O KB Conn. & BIOS**

Title		
EC Extend I/O KB Conn. & BIOS		
Size	Document Number	Rev
	Abacus/TangII LA-1452	1.0
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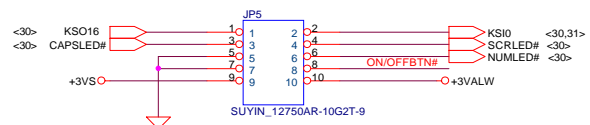
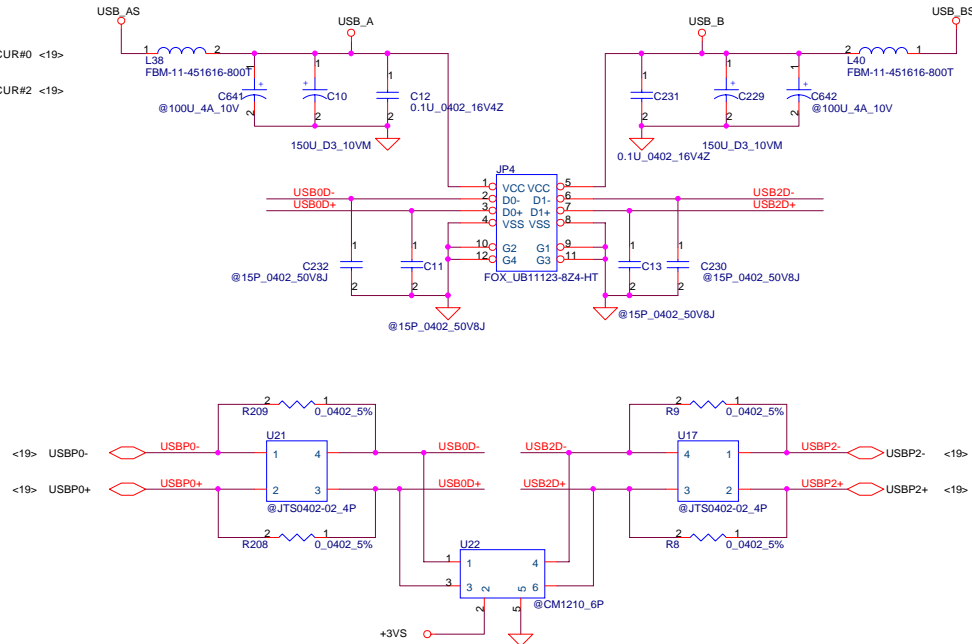


WHEN R=0, Vbe=1.35V  
WHEN R=33K, Vbe=0.8V



Note:  
USB\_AS=USB\_BS=Trace width=40mils

### USB PORT



Power SW Function Button

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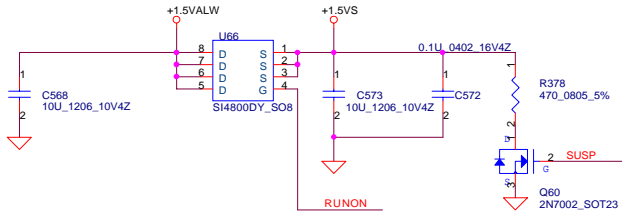
Compal Electronics, Inc.

Title <b>Power OK/Reset/RTC battery/USB Conn</b>		
Size	Document Number <b>Abacus/TangII LA-1452</b>	Rev 1.0
Date:	Tuesday, November 26, 2002	Sheet 32 of 46

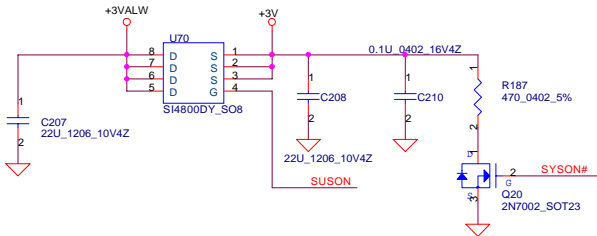
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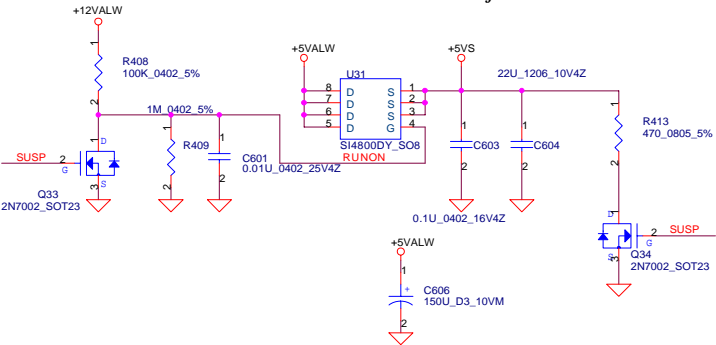
**+1.5VALW to +1.5VS Transfer**



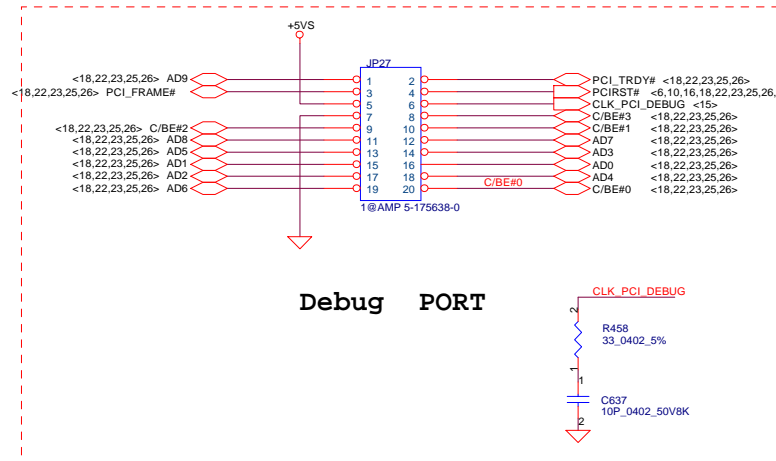
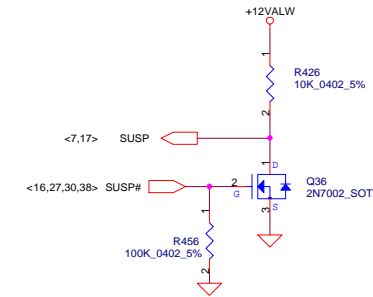
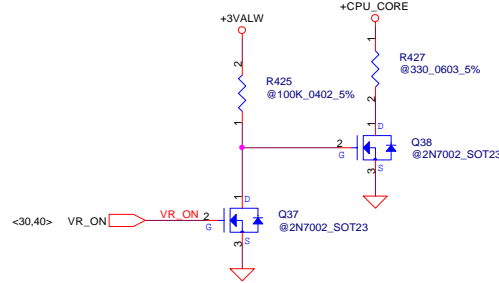
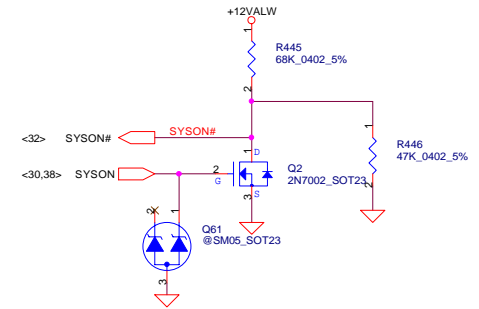
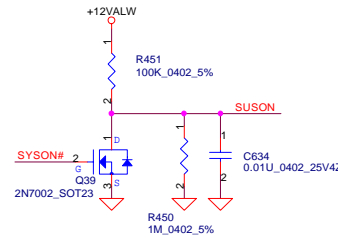
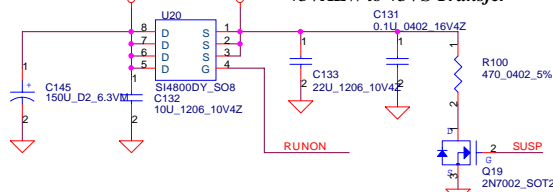
**+3VALW to +3V Transfer**



**+5VALW to +5VS Transfer**



**+3VALW to +3VS Transfer**

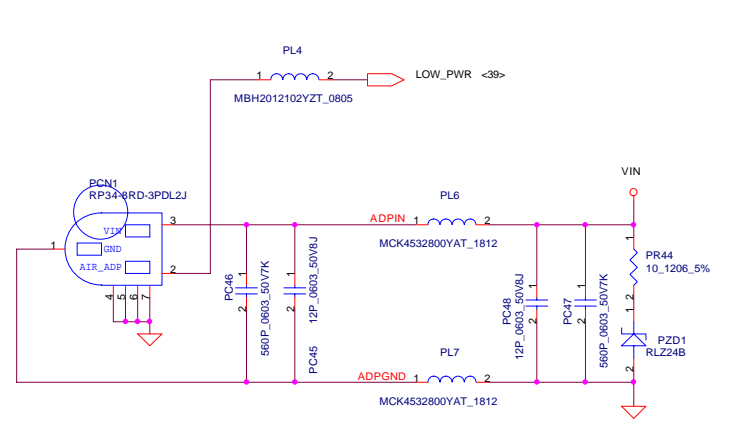


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Compal Electronics, Inc.

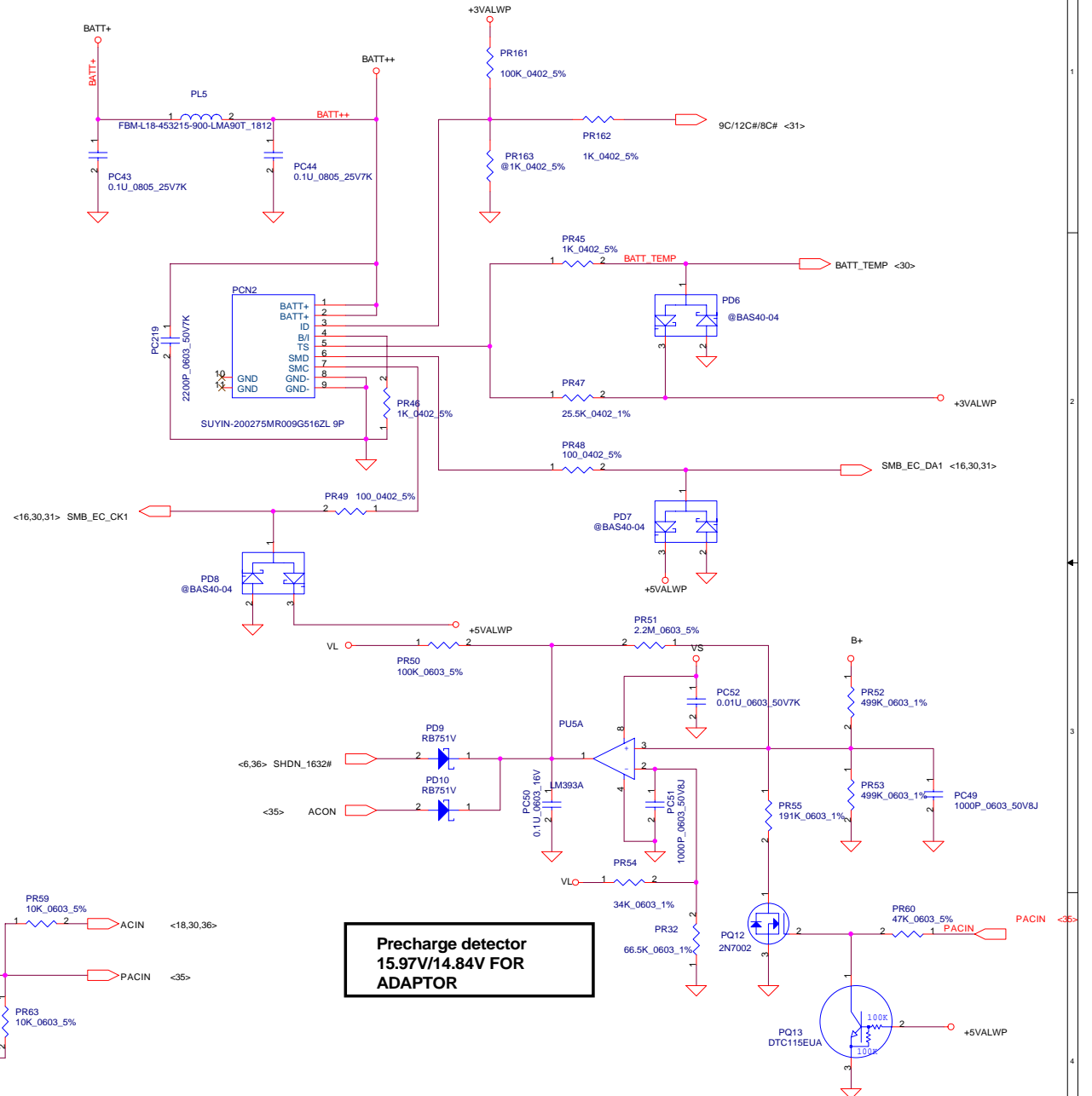
Title		
DC/DC Circuit / Debug Port		
Size	Document Number	Rev
	Abacus/TangII LA-1452	1.0
Date:	Tuesday, November 26, 2002	Sheet 33 of 46

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**Vin Detector**  
17.90V/17.24V

**PCN2 battery connector pin assignment**  
**SMART Battery:**  
 1. BATT+  
 2. BATT+  
 3. 9C/12C#/8C#  
 4. B/I  
 5. TS  
 6. SMB\_EC\_DA1  
 7. SMB\_EC\_CK1  
 8. GND  
 9. GND



**Precharge detector**  
15.97V/14.84V FOR ADAPTOR

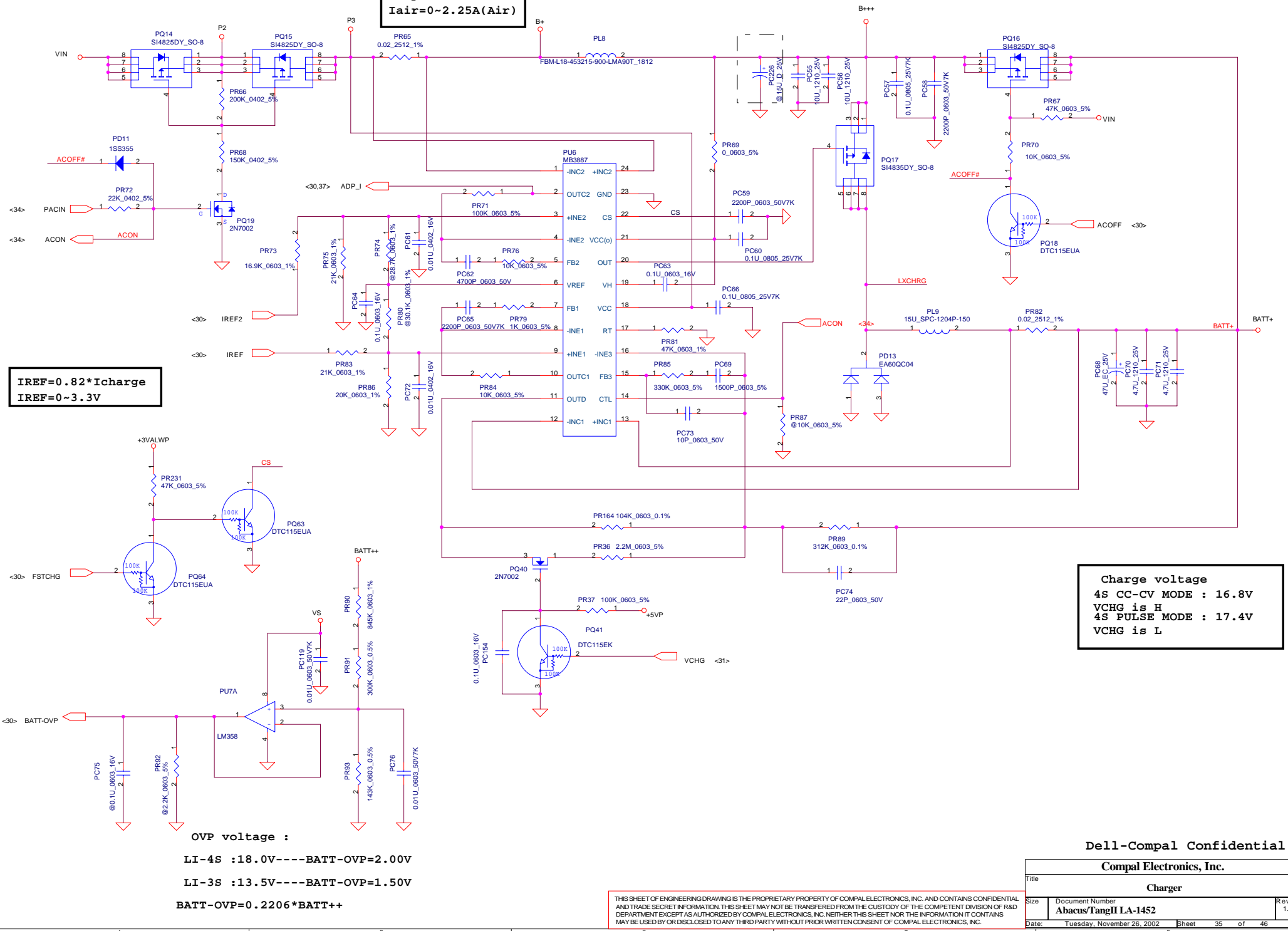
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Title		
Detector		
Size	Document Number	Rev
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Date:	Tuesday, November 26, 2002	Sheet 34 of 46

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**I<sub>adp</sub>=0~4.10A (90W)**  
**I<sub>adp</sub>=0~3.20A (70W)**  
**I<sub>air</sub>=0~2.25A (Air)**



**I<sub>REF</sub>=0.82 \* I<sub>charge</sub>**  
**I<sub>REF</sub>=0~3.3V**

**Charge voltage**  
**4S CC-CV MODE : 16.8V**  
**VCHG is H**  
**4S PULSE MODE : 17.4V**  
**VCHG is L**

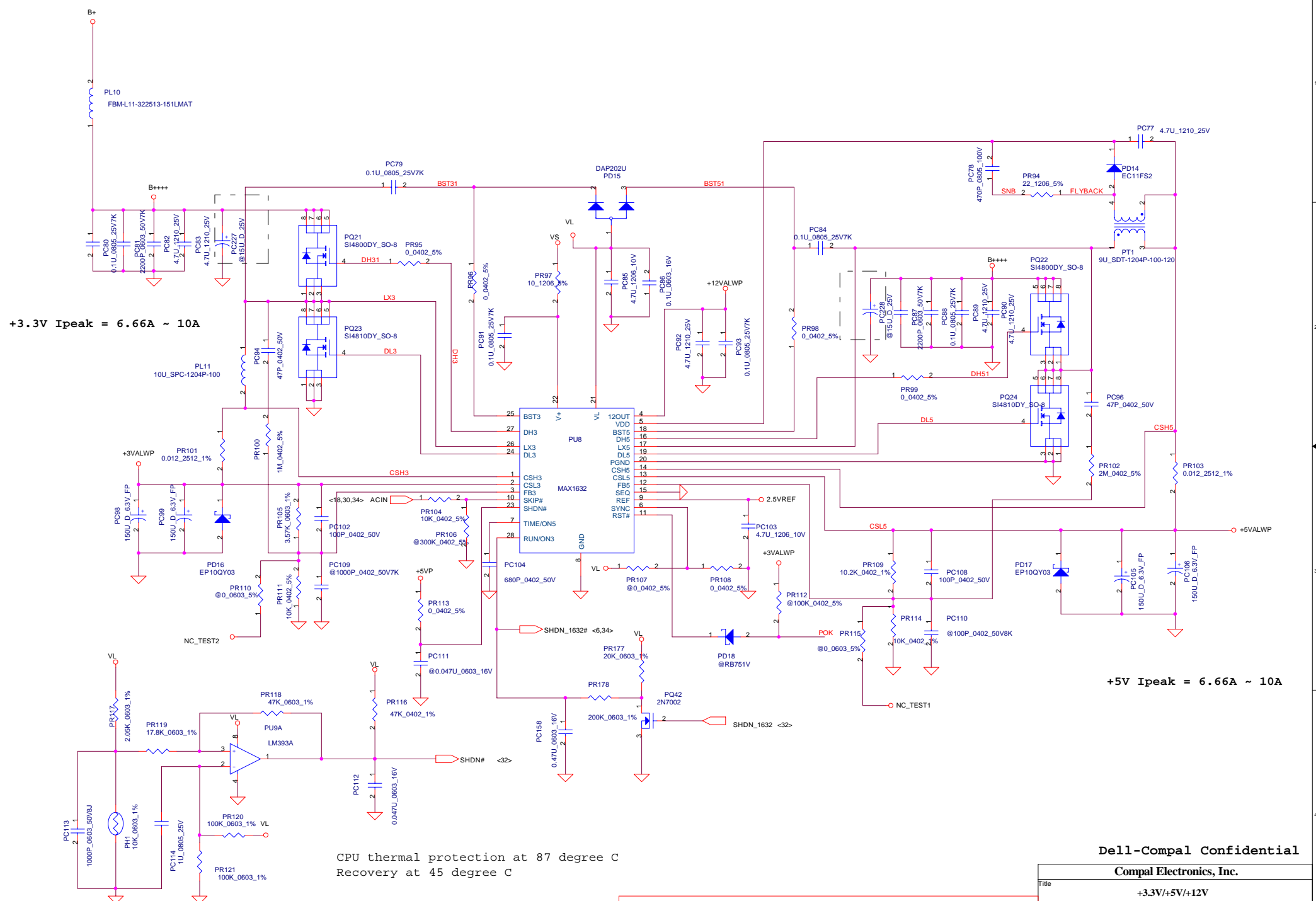
**OVP voltage :**  
**LI-4S :18.0V----BATT-OVP=2.00V**  
**LI-3S :13.5V----BATT-OVP=1.50V**  
**BATT-OVP=0.2206\*BATT++**

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Charger		
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+3.3V Ipeak = 6.66A ~ 10A

+5V Ipeak = 6.66A ~ 10A

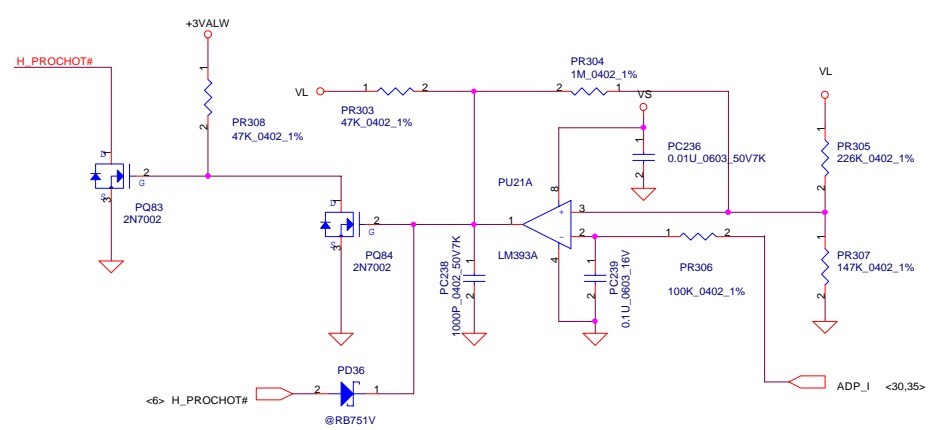
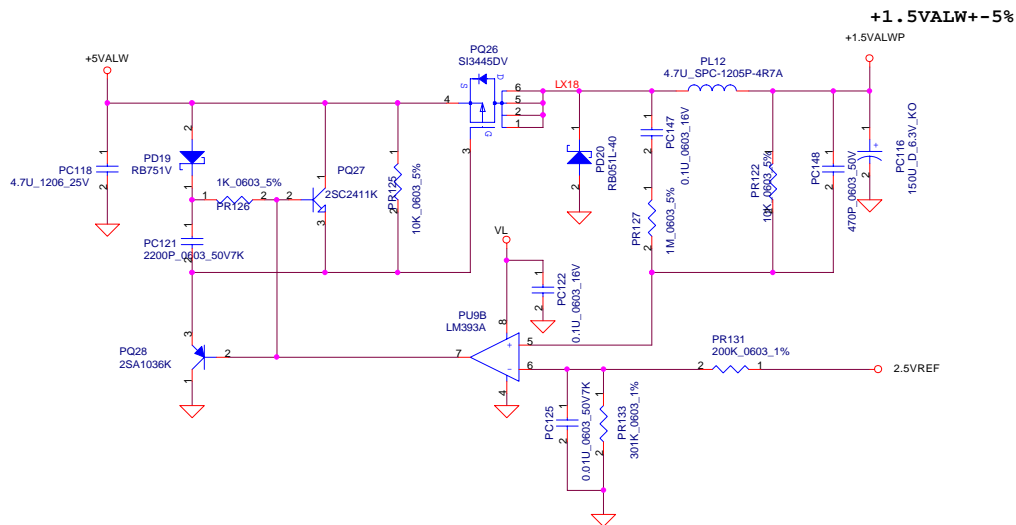
CPU thermal protection at 87 degree C  
Recovery at 45 degree C

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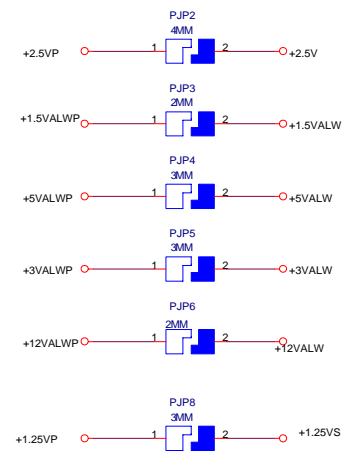
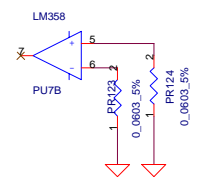
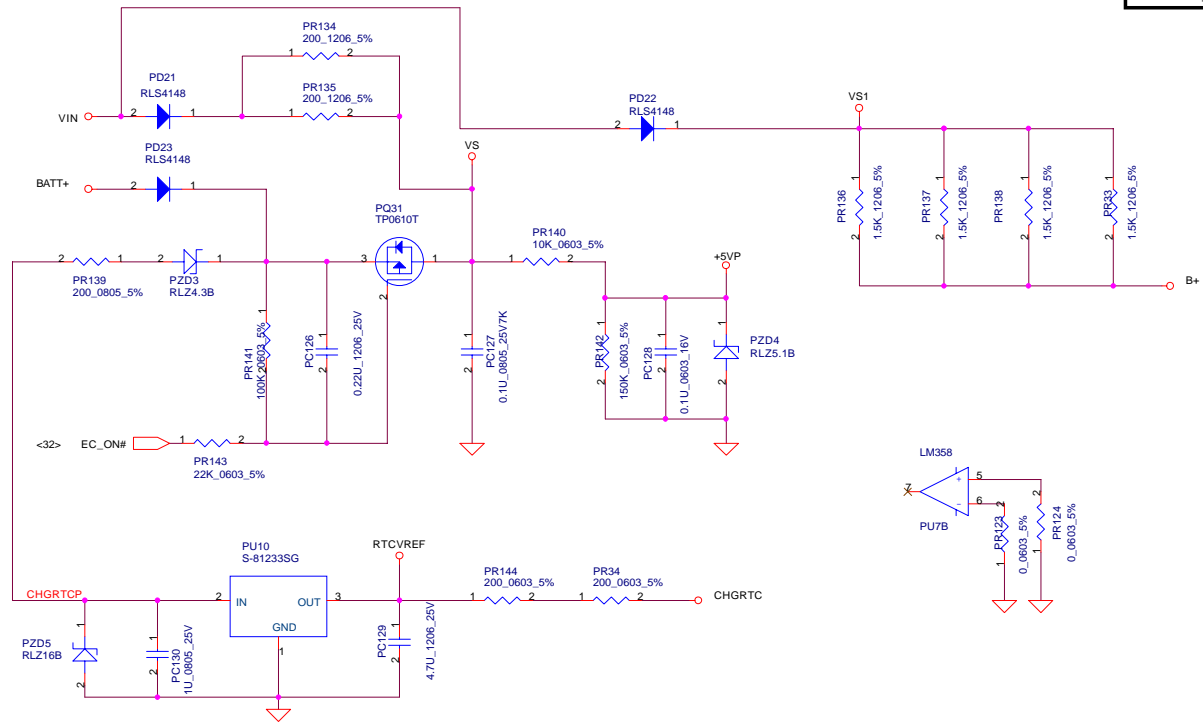
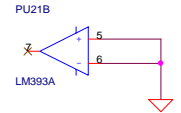
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Title		
+3.3V/+5V/+12V		
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**Adaptor Current Detector**  
 ADP\_I : 2.2V.... clock throttle(lin=5.5A)  
 ADP\_I : 1.8V....No clock throttle(lin=4.5A)



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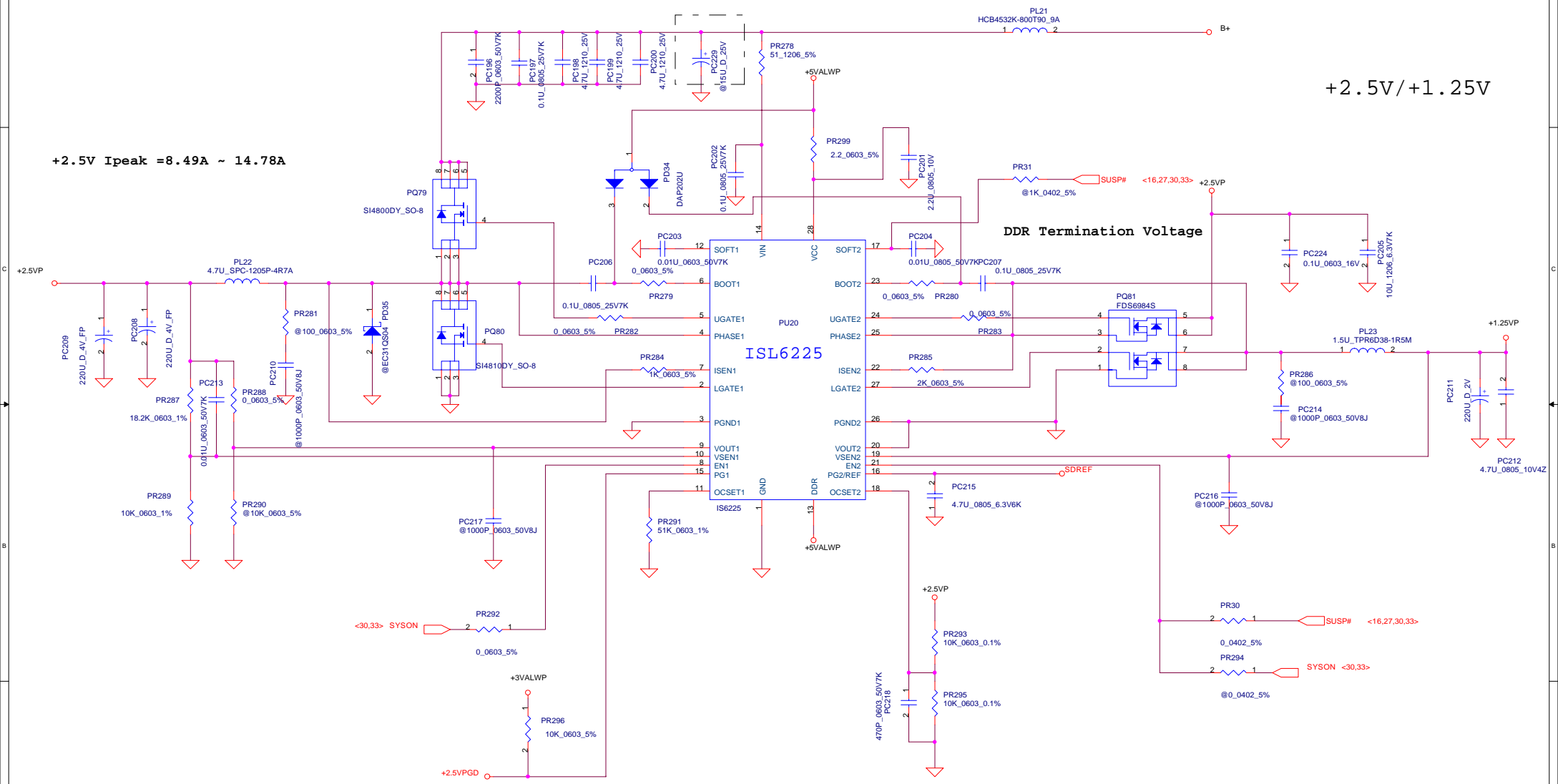
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+1.5VS		
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+2.5V I<sub>peak</sub> = 8.49A ~ 14.78A

+2.5V/+1.25V

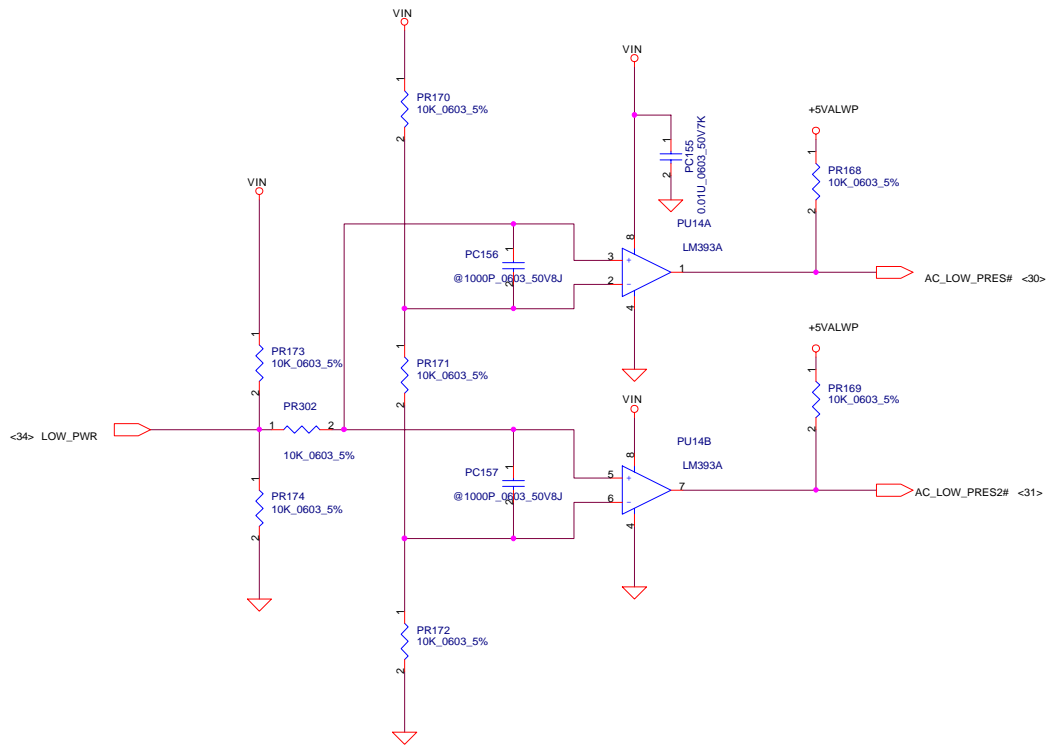


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COMPAL ELECTRONICS, INC		
Title DDR POWER 2.5V & 1.25V		
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# AC Adapter Detector



AC Adapter	LOW_PWR	AC_LOW_PRES#	AC_LOW_PRES2#	IREF2
90W	0V	0	0	2.96V
70W	Float	0	1	2.31V
AIRLINE	20V	1	1	1.62V

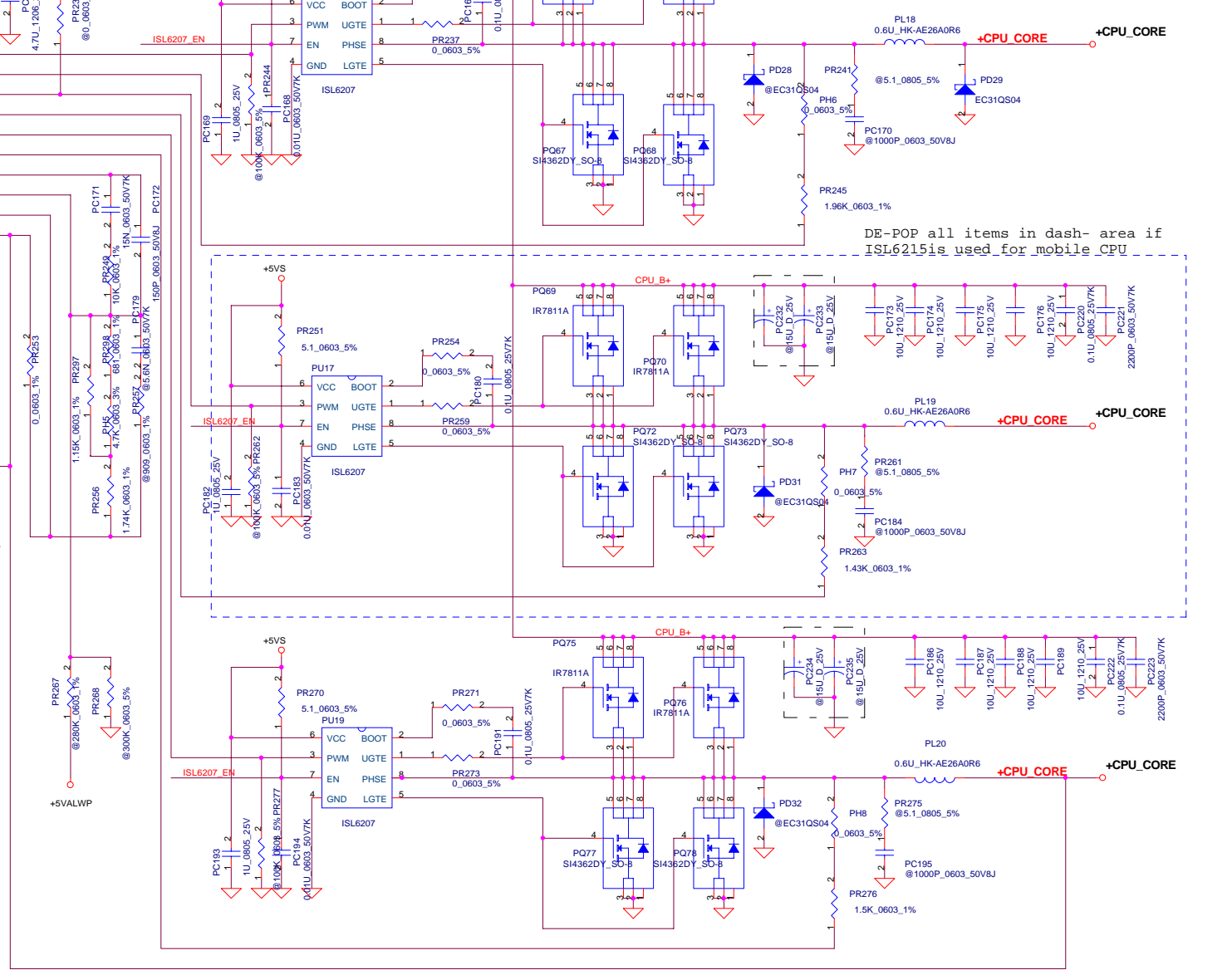
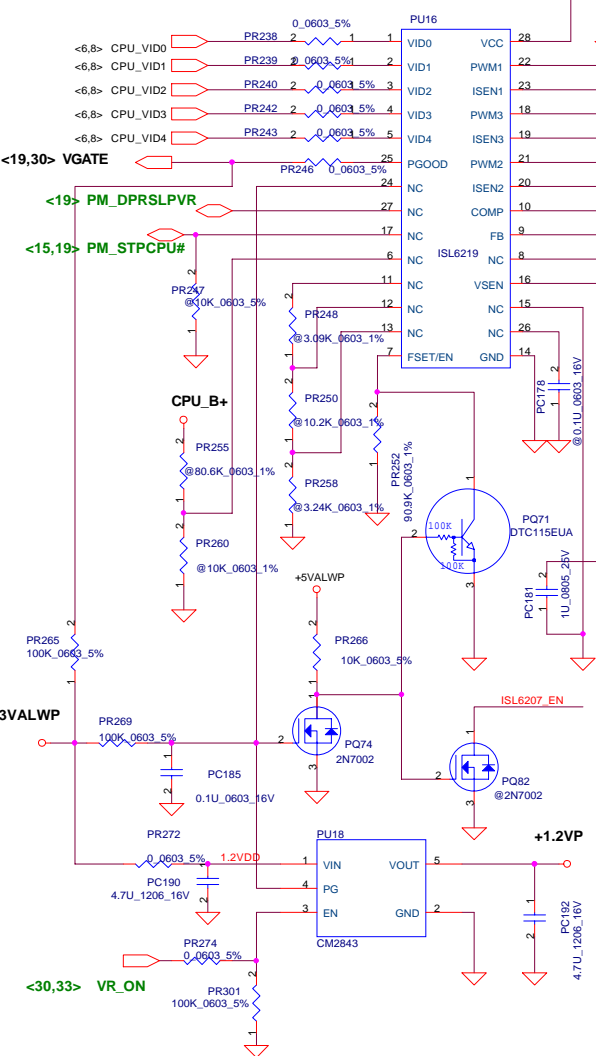
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Different Pin Definition for ISL6215 in PU16

#6	RAMPS	#12	ALTV	#17	NODV
#8	VMON	#13	OFFSET	#24	EN
#11	OCSET	#15	VRTN	#27	ALTEN
#26	SOFT				



	DE-POP	PR249	PR256	PR268	PC171
ISL6219 for desk-top	PR247, PR255, PR260 PR248, PR250, PR258, PC178, PC172, PR236	7.5K	1.74K	unpop	5.6nF
ISL6215 for mobile	PR266, PQ74, PQ71 PR253, PC179, PR257	6.04K	1.5K	130K	4.7nF

PTC solution	<ol style="list-style-type: none"> <li>PH6, PH7, PH8 pop thermal resistor</li> <li>Non-pop PR298 and PH5</li> <li>PR297 0 ohm</li> </ol>
NTC solution	<ol style="list-style-type: none"> <li>PH6, PH7, PH8 pop 0 ohm resistor</li> <li>Pop PR298 681_0603_18, PR297 1.15K_0603_18</li> <li>Pop PH5 4.7K thermal resistor</li> </ol>

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<b>COMPAL ELECTRONICS, INC</b>	
Title	<b>+CPU CORE</b>
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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver#	Phase
1	Fireware issue	The ICH4 GNTA# strap pull up for EC BIOS	0.1A	18	Depop R153, GNTA# have internal pull up	0.1	SST
2	Leakage current issue	Reduce Broadcom 4401L leakage current	0.1A	22	Depop L39 and pop L7, connccetor power source from +3VALW to +3V, R31, R32, R33 pull up to +3VAUXLAN, Q3,Q4,Q5 pin3 connect to +3VAUXLAN	0.1	SST
3	Fix schematics part value	L21, L22, L23, L26 part value different with BOM	0.1B	15	Change L21, L22, L23, L26 part value from CHE20120121 to BLM21A601SPT on schematics	0.1	SST
4	BOM issue	R445 include wrong part number	0.1B	33	Change R445 part number from SD028470200 to SD028680200. PN indicate value from 47K_0402_5% to 68K_0402_5%	0.1	SST
5	HDD leakage current issue	When AC in +5VSHDD will go up to 5V	0.1C	21	Q6 change to SI2302DS as schematics, SIDEPR active low when HDD power on	0.1	SST
6	Capture library package issue	2N7002 Drain is pin1, Source is pin3	0.1C	28	Fixed Q30, Q31, Q32 Capture libaray, pin1 fixed to pin3, pin3 fixed to pin1	0.1	SST
7	BOM issue	Fixed R196-R199 from 56.2K ohm to 56.2 ohm	0.1C	23	Change R196-R199 PN from SD014562207 to SD014562A00 on schematics	0.1	SST
8	Fix LOM EEPROM issue	U8 (AT93C46) is used X16 organization	0.1C	22	NC or pop R452 to pull up U8 pin6 for X16 organization select	0.1	SST
9	Fix CLKRUN# leakage issue	ICH4 not implement CLKRUN#, GPIO24 is resume power well.	0.1D	19	Add a diode D46 to isolate GPIO24 from ICH4 to PCI devices, and depop D46.	0.2	PT
10	LOM EEPROM issue	U8 (AT93C46) is used X16 organization. U8 pin6 pull up or NC for X16 organization select, pull down for X8 organization select.	0.1D	22	U8 pin6 pull up +3VAUXLAN via R452, and depop R452.	0.2	PT
11	SW BD LED keep turn on	SW BD LED control transistor Emitter connctet to +5VALW be keep LED always turn on	0.1D	32	Change JP5 pin9 from +5VS to +3VS	0.2	PT
12	Fix VCCA_SM voltage drop issue	Add current rating for VCCA_SM, VCCA_DPLL, VCCA_FSB (1.5VS)	0.1E	10	Change L3, L4, L27, L28 from MLF2012DR68XT to FBM-L11-201209-121LMA05	0.2	PT
13	Change address and control signals layout topology	Change ddr address and control signal layout topology	0.1E	12,13	DDR address and control signals layout topology same the ddr data layout topology	0.2	PT
14	Fix EE issue item 89	Signal COMP/B and Y/G connect error	0.1E	17	Swap COMP/B and Y/G to correct connection	0.2	PT
15	Fix EE issue item 91	BEEP# from EC should be high active	0.1E	28	Change net name BEEP# to BEEF	0.2	PT
16	Fix EE issue item 92	Fix FSB 400MHz when 845GL pop	0.1E	15	Add R455 (8.2K_5%) pull down for H_BSEL0	0.2	PT
17	Fix EE issue item 95	When AC insertion SUSP# may be floating before the KBC can programit.	0.1E	33	Add R456 (100K_5%) pull down SUSP#	0.2	PT
18	Fix EE issue item 47	Provide enough current rating	0.1F	15	L22 and L26 change frome BLM21A601SPT (300mA) to FBM-L11-201209-121LMA05 (500mA) and depop L22	0.2	PT
19	Card Bus power bead current rating not enough	Provide enough current rating	0.1F	24	L5 and L6 change frome FBM-L11-160808-800LMT_0603 (300mA) to FBM-L11-201209-121LMA05 (500mA)	0.2	PT
20	Fix EE issue item 102	Fix Intel CPU FSB frequency issue	0.1F	10,15	H_SEL0 connect to R270 pin1 from CLK generator, HBSEL0 connector to R270 pin2 from CPU. Depop R270 on GL board.	0.2	PT
21	Battery charge issue	ACIN pull up +3VALW can't change power supplier to battery when AC exit	0.1F	18	Depop R161	0.2	PT
22	NO	Change PCMCIA connector	0.1F	24	Change PCMCIA connccetor from AMP_0-1376275-1 to JAE_JC21-BRB	0.2	PT
23	Fix INTRUDER issue	ESD protect for Q22	0.1F	32	Add C638, C639 for Q22 protection	0.2	PT
24	Remove PS2 connector	No necessary	0.1G	29	Remove RP7, JP26	0.2	PT
25	Add debug port	GL board have not pop minipci connector, we need a port 80 debug tool	0.1G	33	Add R458, C637 and JP27	0.2	PT
27	For cost save	For cost save	0.1G	32	Depop C10, C229 (150U Poly Cap), add C641, C642 (100U Petit Cap)	0.2	PT
28	It no need	Use R19 pop and depop to control H_SEL0 high or low	0.1G	15	Remove R455	0.2	PT
29	Fix EE issue item 134	Change ddr address and control signal layout topology	0.1H	12,13	Change DDR address and control signal to go back SST topology	0.2	PT
30	Fix EE issue item 149	Pop Petit Cap after EA test	0.1H	32	Depop C641, C642 and pop C10, C229	0.2	PT
31	Fix EMI issue	EMI team's recommendation	0.1I	10	Pop R52, C79 for CLK_CLK_PCI_LAN; R428, C614 for CLK_PCI_MINI; R406, C597 for CLK_PCI_LFC; R321, C395 for CLK_ICH_66M	0.2	PT

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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver#	Phase
32	No	Connect MiniPci connector metal door to short to GND	0.1I	26	Add JP24 pin 127, 128 on schematics short to GND, JP24 footprint pin 127, 128 (metal lock door) be short to GND	0.2	PT
33	No	Some text mode use wire, change to line	0.1I	10,30,40	Some text mode use wire, change to line	0.2	PT
34	Fix power on issue	Use PCIRST# to set the SHDN_1632# work after PCIRST# high when power on	0.1I	6	Add Q62 gate connect to PCIRST#, source connect to SHDN_1632#	0.2	PT
35	No	Change to use approve part	0.1I	31	RP118 (8.2K +-5% 4P2R) change to R453, R454 (8.2K_0402_5%)	0.2	PT
36	No	Hard Disk source power change to +5VS	0.1I	21	Q6 change back to SI2301DS (PMOS) pin3 connect to +5VS	0.2	PT
37	Fix EE issue item 134	Change DDR address and control signal topology back to REV0.1	0.1I	12,13	Change DDR address and control signal topology back to REV0.1	0.2	PT
38	Fix EE issue item 171	For CRT Hsync and Vsync to allow tuning	0.1I	17	Add series resistors R459, R460 for Hsync and Vsync	0.2	PT
39	No	Schematic version change for PT build	0.2	ALL	Change revision from 0.1I to 0.2	0.2	PT
40	Fix issue item 20	Slow rising and falling time	0.2A	10	Pop R234, C249 for CLK_MCH_DISPLAY; R286, C333 for CLK_MCH_66M	0.2	PT
41	Fix CRT rising and falling time issue	Fast rising and falling time	0.2A	17	Pop L1, L2, L15 Change Form FCM-2012C-800 to FBM-10-201209-260T for PE board	0.2	PT
42	No	Change Board ID output level	0.2A	30	Pop R393 100K_0603_1% for Board ID	0.2	PT
43	No	Add off-page reference	0.2A	24	Add off-page on pg24 FCMCIA connector	0.2	PT
44	No	Net in for Rev 0.2A Gerber	0.2B	ALL	Modify Text	0.2A	PT-2
45	Fix DFx issue	C387 effect DIMM door lock	0.2C	21	Add C643 22u_1206 replace C387's layout location and C387 leave DIMM area.	0.2A	PT-2
46	No	Add JP18 PCMCIA connector GND pads	0.2C	24	JP18 pin75,76,77,78,79,80,81,82 connect to GND	0.2A	PT-2
47	No	PM_GMUXSEL for mobil platform to support SpeedStep, desktop platform just GPIO fuction	0.2C	19	Remove PM_GMUXSEL signal net	0.2A	PT-2
48	Fix PIR2 issue	PIR not match schemaitcs	0.2F	22	Pop L39 and depop L7	0.2A	PT-2
49	Fix PIR19 issue	PIR not match schemaitcs	0.2F	24	L5, L6 change to FBM-L11-201209-221LMAT (3A). And Depop L5	0.2A	PT-2
50	Fix PIR23 issue	PIR not match schemaitcs	0.2F	32	Depop C638	0.2A	PT-2
51	Fix PIR24 issue	PIR not match schemaitcs	0.2F	30	Rp7 pop for pull up PS2 signal	0.2A	PT-2
52	Fix PIR25 issue	PIR not match schemaitcs	0.2F	33	JP27 pop on GL board for debug and depop on PE board	0.2A	PT-2
53	Fix EE issue item 62	Schematics component's PN not match BOM	0.2G	29	JP13 (TP CONN) PN change to "SP020010910" in schematics to match BOM	0.2A	PT-2
54	Fix EE issue item 63	Schematics component's PN not match BOM	0.2G	29	JP25 (MDC CONN) PN change to "SP02F00410L" in schematics to match BOM	0.2A	PT-2
55	Fix EE issue item 64	Schematics component's PN not match BOM	0.2G	32	JP4 (USB CONN) PN change to "DC233I0241L" in schematics to match BOM	0.2A	PT-2
56	3VDDCDA, 3VDDCCK rising time issue	3VDDCDA, 3VDDCCK rising slow on SMBus EA measurement	0.2G	17	R5, R201 change from I0K_0402_5% to 2K_0402_5%	0.3	ST
57	EE issue list item 91	CLK_PCI_ICH timing out of spec	0.2H	18	Pop R349 (22_0402_5%), C480 (10P_0402_50V8K) for CLK_PCI_ICH AC termination	0.3	ST
58	EE issue list item 103	Depop sub thermal sensors for cost save	0.2H	8	Depop U25, U23, C394, C482, R308, R351 and R306	0.3	ST
59	Fix Boardcom 4401L wake up from S3 issue	Fix Boardcom 4401L wake up from S3 issue	0.2H	22	Add R461, R462 and depop R462. Option VESD and VDDBUS power source from +3VS to +3VAUXLAN. C97, C96, C77, C74, C88, C87, C80 bypass +3VWOL	0.3	ST
60	EE issue list item 103	H_BSEL0 of 845PE should get 1.5V at input and CLK chip should be seeing 3.3V with 533MHz CPU	0.2H	15	Add R463 (0_0402_5%) Pop on PE board. RI9 move to CPU side and power source +3VS.	0.3	ST

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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver#	Phase
61	ESD protection on 2nd FAN	ESD protection on 2nd FAN	0.2I	7	Reserve Q63 (SM05) for 2nd FAN ESD protection	0.3	ST
62	Fix EE issue item 105	H_BSEL0 circuit not correct	0.2I	10, 15	Series resistor R270 for CPU and MCH	0.3	ST
63	No	Change Board ID for ST build	0.2I	30	R394 change from 10K_0603_1% to 24.9K_0603_1%	0.3	ST
64	No	Change for ITP test on PCBA	0.2I	6, 8	Depop R313, R305 and pop R310, R372, R183, R184, R304	0.3	ST
65	Fix EE issue item 126	Using larger cap for high-pot margin	0.2J	22	C211, C212 change package from 1206 size to 1808.	0.3	ST
66	RJ11 ISN failed	EMI team recommend to resolve RJ11 ISN test failed	0.2J	29	Cut a separated GND for MDC and connect to system GND via a schottky diode. Reserve a jump for connect system and MDC GND.	0.3	ST
67	Fix EE issue item 140	Connect 9C/12C#/8C# to EC GPIO for future 9Cell support if required	0.2K	31, 34	Connect 9C/12C#/8C# from PR162 to U30 pin17 and remove R388	0.3	ST
68	TI TPS793475DBVR damage issue	When power on, there are 1.5A sink current when TPS793475DBVR started	0.2K	29	For power solution, C558 change package size from 0402 to 0603 for value tolerance	0.3	ST
69	Fix EE issue item 136	Add hardware circuit to sense Adapter current and automatically generate PROCHOT to the CPU to generate automatic throttling	0.2K	6	R311 change to 4.7K_0402_5%, H_PROCHOT# connect to PD36	0.3	ST
70	Fix ThermTrip function	When thermal protective resistor PH1 work, SHDN_1632# can't tie to low	0.2K	6	R320 connect to Q59 base, R316 connect to Q59 collector and VL power source. Add Q64 between Q59 and Q62. Q62 change pin1 Drain to connect SHDN_1632#	0.3	ST
71	RJ11 ISN failed	Change solution for ISN failed	0.3	29	Remove PJP9-13 and D47	0.3	ST
72	Fix EE issue item 136	Follow Intel desing guide recommend pull up resistor value	0.3	6	R311 change back to 62_0402_5%	0.3	ST
73	Fix EE issue item 141	Prevent noise issue	0.3	28	Depop R328 for noise prevention	0.3	ST
74	No	For cost save	0.3	7	Depop C148, C150 (470U_D4_2.5VM) and C152 (330U_D2E_2.5VM)	0.3	ST
75	Fix PROTO3 EE issue item 44	Minipci connector pop for PE board only	0.3B	26	Add 2@ symbol for JP24 for PE board pop only	0.3	ST
76	No	Vendor schematics review recommendation	0.3B	22	R35 change from 10K_0402_5% to 1K_0402_5%	0.3	ST
77	Fix PROTO3 EE issue item 45	Remove minipci suport component for GL board cost save	0.3B	26	Remove R405, R399, C600, C596, C613, C612, C599, C598, C609, L35, C616, C610, L36, R401, R403 on GL board	0.3	ST
78	No	Modify material value	0.3C	23, 26, 27, 28	Change value L11, L30, L31, L35, L36 from BDM21A05_0805 to BLM21A05_0805	0.3	ST
79	No	Modify material part number	0.3C	27	U24 STAC9750 change from (SA097500000) to (SA097500010) for both BOM	0.3	ST
80	No	Depop Fan2 Control circuit	0.3C	7	Delete R11, D11, D20, U1, R10, R6, Q1, C234, Q8, JP19	0.3	ST
79	No	EMI require	1.0	17	Pop D1, D3, D18 for EMI requirement	1.0	QT
80	No	Modify Fiduiial Mark & Screw Hole value for non pop	1.0	29	Fiduiial Mark & Screw Hole value add @ symbol	1.0	QT

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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver#	Phase
1	CPU_CORE can't power up	Pin7 of PU16 can't be used as on/off control pin	0.1B	40	1. Change VCC power source of PU16 from +5VALWP to +5VS	0.1	SST
2	current limited is not up to 60A	Current limited is about 37A while PH6,PH7,PH8 is 1.5K that is not enough for design target.Because we don't use PTC resistor on PCB now, the value must be tuned later.	0.1B	40	1. Change PH6,PH7,PH8 from 1.5K_0603_5% to 3K_0603_1%	0.1	SST
3	Turn on voltage of PQ19 is not enough	Vgs of PQ19 is 2V while PR72 is 47K. That is not enough. While PR72 is 22K, the Vgs can be improved to 2.5V.	0.1B	35	1. Change PR72 from 47K_0402_5% to 22K_0402_5%	0.1	SST
4	current rating is not enough.	FBM-L11-322513-151LMAT is 5A that is not enough.So FBM-L18-453215-900LMA90T1812 is 9A that is better.	0.1B	35	1. Change PL8 from FBM-L11-322513-151LMAT to FBM-L18-453215-900LMA90T1812.	0.2	PT
5	Fix noise issue	On SST PCB, we can sound some noise due to PC77, the ceramic capacitor has sounded noise with thinner type.	0.1C	36	1. Change PC77 from 2.2U_1206_25V to 4.7U_1210_25V	0.2	PT
6	Fix CPU_CORE Transient Response fail	The transient response is too slow. We must to tune feedback resistor and capacitor to fix it.	0.1E	40	1. Change PR249 from 3.48K_0603_1% to 5.76K_0603_1%. 2. Change PR257 from 49.9_0603_1% to 1.1K_0603_1% 3. Populate PC172 68PF_0603_50V.	0.2	PT
7	SDREF output voltage is over spec.	Add bypass capacitor pallel pin18 of ISL6225	0.1E	38	Populate PC218 470P_0603_50V7K	0.2	PT
8	PG of CM28423 has a glitch while VCC is ready and VR_ON is float	Add pulldown resistor tie to GND while VR_ON is float that can be made sure the logic is low.	0.1E	40	Add PR301 100K_0603_1%	0.2	PT
9	Change VCC power source of PU15, PU17, PU19 from +5VALWP to +5VS	Negative voltage was observed on +5VALWP when system powered off	0.1E	40	1. Change VCC power source of PU15, PU17, PU19 from +5VALWP to +5VS	0.2	PT
10	Prevent abnormal function OVP caused by ISL6219 while system powerwd off ; bouble pulses was observed at output PW1, PW2, PWM3 of ISL6219	ISL6219 caused OVP when on/off pin changed from high to low level	0.1E	40	1. Add PQ82 2N7002 2. Change PR232 from 5.1_0603_5% to 10K_0603_5% 3. Change PC168 from 1U_0805_25V to 0.01U_0603_50V. 4. Depop PR251, PR270, PC183, PC194 5. Tie the EN pin of PU15, PU17, PU19 to Pin1 of PQ82	0.2	PT
11	Fine-tune current sharing of CPU VR phasel,2,3 to have thermal balance	uneven current sharing found	0.1E	40	1. Change PH6, PH7, PH8 form 3K_0603_1% to 0_0603_5% 2. Change PR245 from 0_0603_5% to 1.96K_0603_1% 3. Change PR263 from 0_0603_5% to 1.43K_0603_1%. 4. Change PR276 from 0_0603_5% to 1.5K_0603_1%	0.2	PT
12	Fine-tune CPU load-line with NTC	Fine-tune CPU load-line with NTC	0.1E	40	1. Keep PR268 nonpop 2. Change PR256 from 2K_0603_1% to 1.74K_0603_1% 3. Change PR297 from 0_0603_5% to 1.15K_0603_1%. 4. Change PH5from depop to 4.7K_0603_1% 5. Change PR298 from depop to 681_0603_1% 6. Change PR257 from 49.9_0603_1% to 909_0603_1% 7. Change PC179 from 3900P_0603_50V to 5.6N_0603_50V 8. Change PR249 from 3.48K_0603_5% to 7.5K_0603_1% 7. Change PC171 from 6800P_0603_50V to 5.6N_0603_50V 8. Change PC172 from depop to 47P_0603_50V	0.2	PT
13	Audio noise found	Still find root cause	0.1E	35, 36, 38, 40	1. reserve 15U_D_25V capacitors on PC226-PC235,	0.2	PT
14	PC212 location space change	requested by ME to put a connector around	0.1E	38	1. change the size of PC212 from D size to 0805 and pop 4.7U_0805_10V	0.2	PT
15	Remove PD5	no possibilty to have a reverse voltage at Vin when adapter plug-in because of the DC-jack orientation structure	0.2C	34	1.delete PD5 from schematics	0.2A	PT-2
16	Prevent PU14 from burn out	When pin1 (GND pin) of DC-jack PCN1 disconnected from B/M (damaged by force from outside), there is a large current going through PU14 resulted in PU14 damaged	0.2C	39	Add PR302 10K_0603_5%	0.2A	PT-2

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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver#	Phase
17	100MHz EMI broad-band over spec.	Improve 100MHz EMI broad-band	0.2E	34	Add a FBM-L18-453215-900-LMA90T_1812 bead on PL7	0.2A	PT-2
18	100MHz EMI broad-band over spec.	Improve 100MHz EMI broad-band	0.2H	34	1. Change PL6,PL7 from FBM-L18-453215-900-LMA90T_1812 to MCK4532800YAT_1812 2. Add PL4 MBH2012102YZT_0805 3. Change PC45 from 100P to 560P, PC46 from 1000P to 12P,PC47 from 100P to 12P and PC48 from 1000P to 560P	0.3	ST
19	Precharge function has some bug, while AC Adapter plug in first time	Precharge can reduce surge current from AC adapter,while Adapter plugged in	0.2H	34	1. Change PR51 from 1M to 2.2M,PR55 from 215K to 191K. 2. Change PR54 from 10K to 34K,add PR32 66.5K. 3. Change PC51 from 0.1U_16V to 1000P_50V. 4. Change PC50 from 1000P_50V to 0.1U_16V. 5. Change net +5VP and RTCVREF to VL. 6. Change PR113 from 47K_0402_5% to 0.0402_5%. 7. De-pop PC111 and change PC158 from 0.1U_16V to 0.47U_16V.	0.3	ST
20	Power rating of 0.02_2010 is not enough.	rating power of 0.02_2010 is 0.5W that is very poor for 90W adpater	0.2H	35	1. Change PR65 from 0.02_2010_1% to 0.02_2512_1%.	0.3	ST
21	Power open issue	Change size of thermal resistor and cost down	0.2H	36	Change PH1 from 10K_0805_1% to 10K_0603_1%.	0.3	ST
22	Power good glitch issue in ISL6225	The glitch occurs while secondary PWM is enabled that effects system boots up	0.2H	38	1. Add PR31 1K_0402_5%.. 2. De-pop PR294	0.3	ST
23	Fix open issue #137	DELL don't approve item22 solution, prefer using new version ISL6225	0.2J	38	1. De-pop PR31 1K_0402_5%. 2. De-pop PR294 0_0402_5%. 3. Add PR30 0_0402_5%.	0.3	ST
24	Fix open issue #124	Fix open issue #124 and using ISL6219A	0.2J	40	1. Change PR232 from 10K_0603_5% to 5.1_0603_5%. 2. Populate PR251 and PR270 5.1_0603_5%. 3. Populate PC183 and PC194 0.01U_0603_50V. 4. De-pop PQ82,PD31,PD,32	0.3	ST
25	Fix ISN fail issue	Fix ISN fail with 200KHz	0.2J	35	1. Change PR81 from 66.5K_0603_1% to 47K_0603_1% 2. Change PC55 and PC56 from 4.7U_1210_25V to 10U_1210_25V 3. Change PL9 from 15UH to 22UH	0.3	ST
26	Fix open issue #123	Rds(on) of SI4835DY is too high,change PQ14,15,16 to SI4825DY for power stress	0.2J	35	Change PQ14,PQ15,and PQ16 from SI4835DY to SI4825DY	0.3	ST
27	Adapter shut down while running P4MaxPower 100%	Adapter current over 5.5A 4 sec while running P4MaxPower 100%	0.3	37	1. add PR303, PR306 47K_0402_1%. 2. add PR304 1M_0402_1%. 3. add PR305 226K_0402_1% 4. add PR307 147K_0402_1% 5. add PR308 100K_0402_1% 6. add PC236 0.01U_0603_50V 7. add PC239 0.1U_0603_16V 8. add PC238 1000P_0402_50V 9. add PQ83, PQ84 2N7002 10. add PU21 LM393A	0.3	ST
28	Modify thermal protect temp. from 95C to 87C	Based on thermal team requirement	0.3A	36	1. ChangePR119 from 21K_0603_1% to 17.8K_0603_1% 2. Change PR117 from 1.74K_0603_1% to 2.05K_0603_1%	0.3	ST

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Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	B.Ver#	Phase
29	modify compension for reduce output capacitor	modify compension for reduce output capacitor	0.3A	40	1. De-pop PR257 and PC179. 2. Change PC171 from 5.6N_0603_50V to 15N_0603_50V 3. Change PC172 form 47P_0603_50V to 150P_0603_50V 4. Change PR249 from 7.5K_0603_1% to 10K_0603_1%	0.3	ST
30	Fix item25 about ISN test without changing inductor	Fix item25 about ISN test without changing inductor	0.3A	35	1. Change PL9 from 22UH_SPC-1205P-220A to 15UH_SPC-1204P-150	0.3	ST
31	Capacitor DFX issues	Component layout pad overlap (reservated for noise issue) causes some components shifting when pass the re-flow	0.3D	35 36 38 40	remove PC226, PC227, PC228, PC229, PC230, PC231, PC232, PC233, PC234, PC235	1.0	QT
32	Noise issue in B+ power	Add reservated caps. back for noise issue	0.3E	35 36 38 40	reserve PC226, PC227, PC228, PC229, PC230, PC231, PC232, PC233, PC234, PC235	1.0	QT

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